



Future Directions in Computational Electromagnetics for Digital Applications

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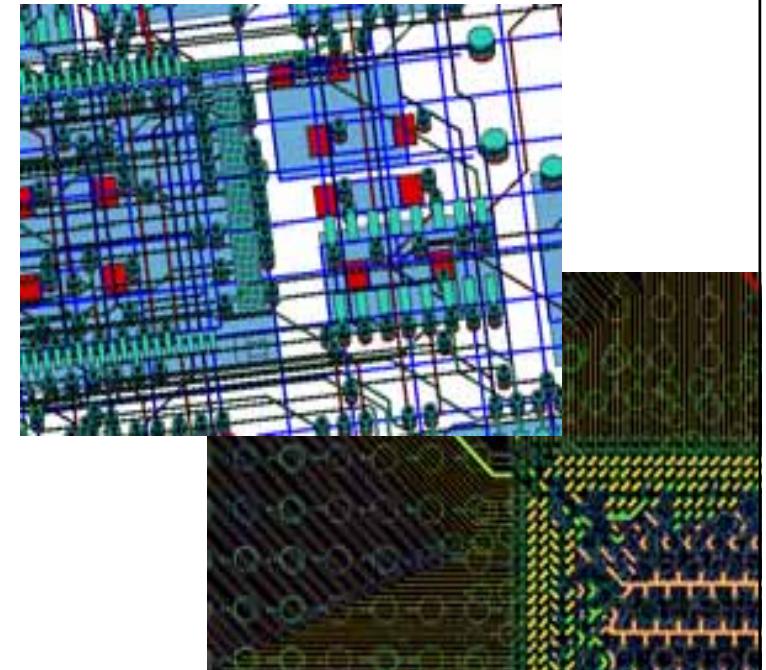
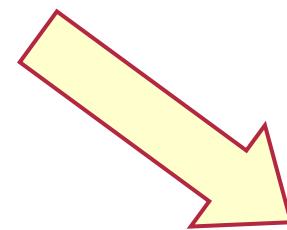


- Introduction
- State of the art
 - Three steps in solving an EM Problem
 - Finite Integration Technique as universal method
 - Wide choice of solution methods
- Future trends
 - Geometrically complex problems
 - EMC, Signal and Power integrity
 - Network Extraction, Passivity
 - Coupled problems
 - Integrated flows
- Conclusions

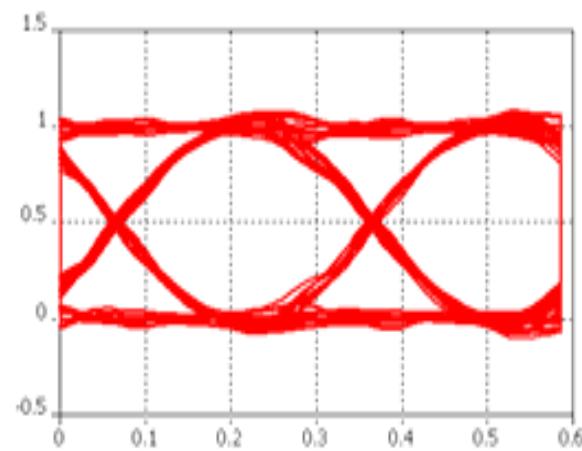


Motivation: Why 3D EM simulation?

- Growing frequencies / clock rates
- High density of components
- Increasing parasitics relevance
- Sophisticated packaging technologies
- 3D packaging



- No simple models available
- Increase in crosstalk problems
- EMI / EMC concerns
- Signal / power integrity issues
- 2 ½D solvers cannot cope with all 3D effects





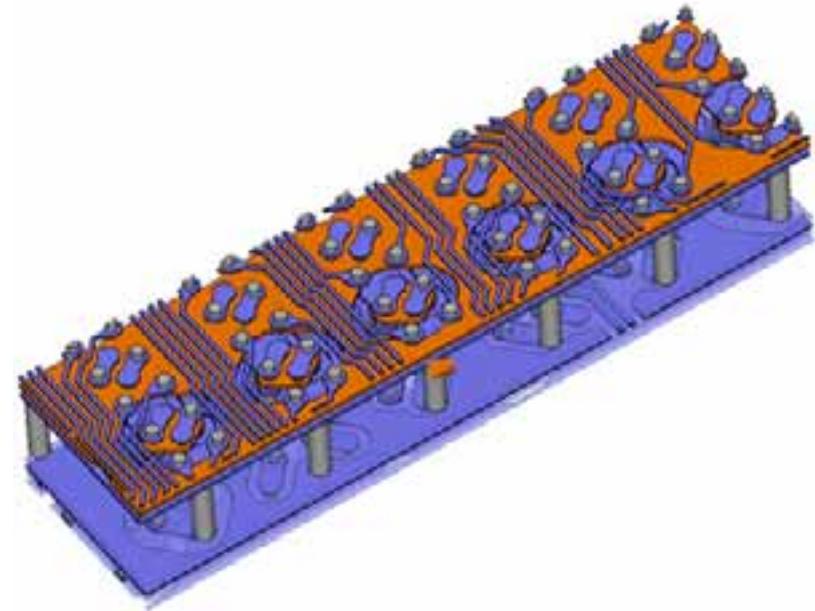
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EM Solution = 3 Steps

1 Spatial Discretization of geometry

- Staircase grid
- Tetrahedral grid
- Surface mesh
- Boundary fitted meshes
-



2 Local approximation of Maxwell's Equations

- Finite Difference
- Finite Integration Technique
- Finite Element
- Finite Volume
-

3 Solving the algebraic system

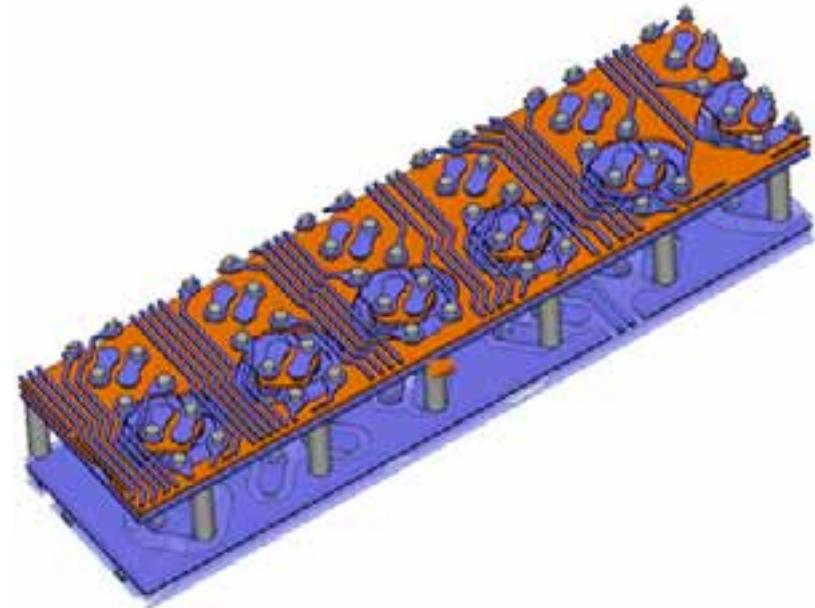
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- Iterative solver
- Eigenvalue solver
- Time stepping solver
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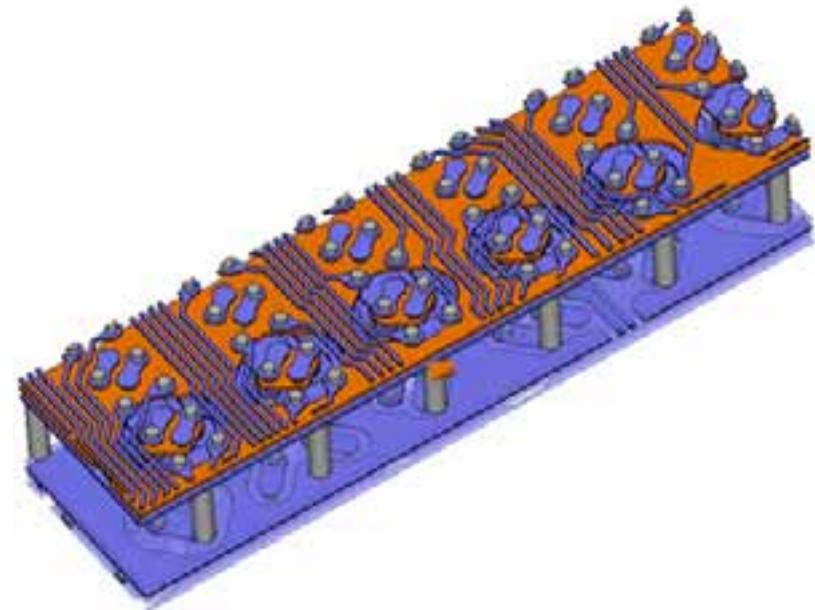
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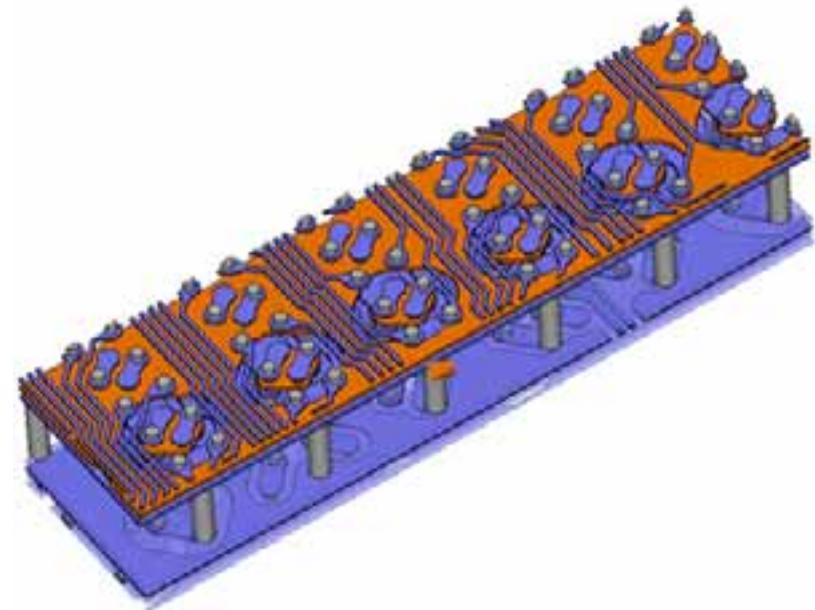
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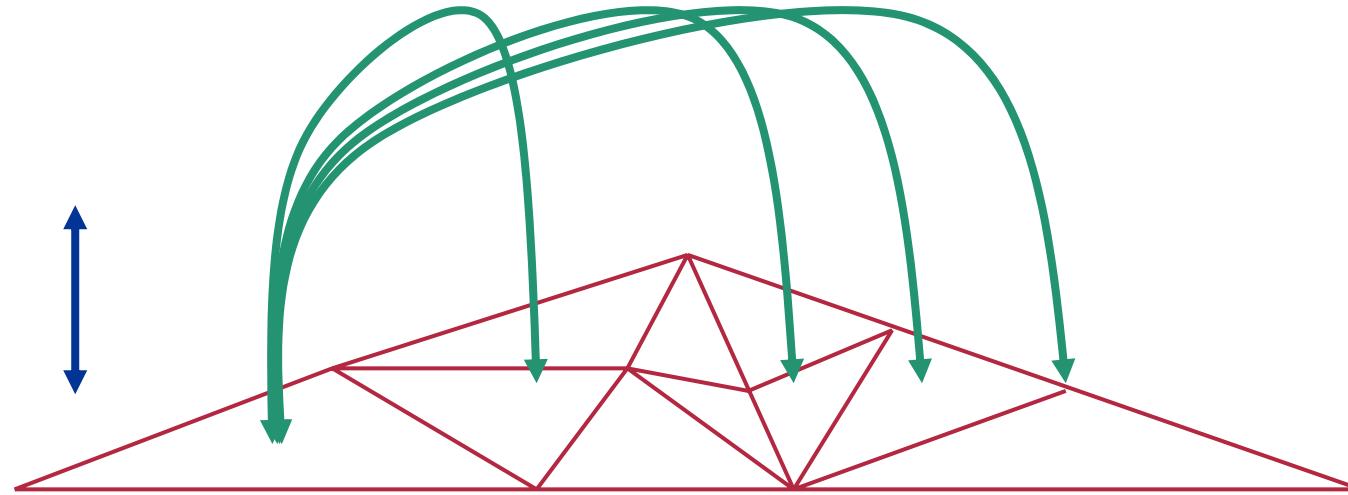
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3 Solving the algebraic system

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Surface Meshing

Each patch talks to each patch



With **D** as linear dimension

„Method of Moments“

$$N_{\text{cell}} \propto D^2 ; \text{ Matrix rank} \propto D^2$$

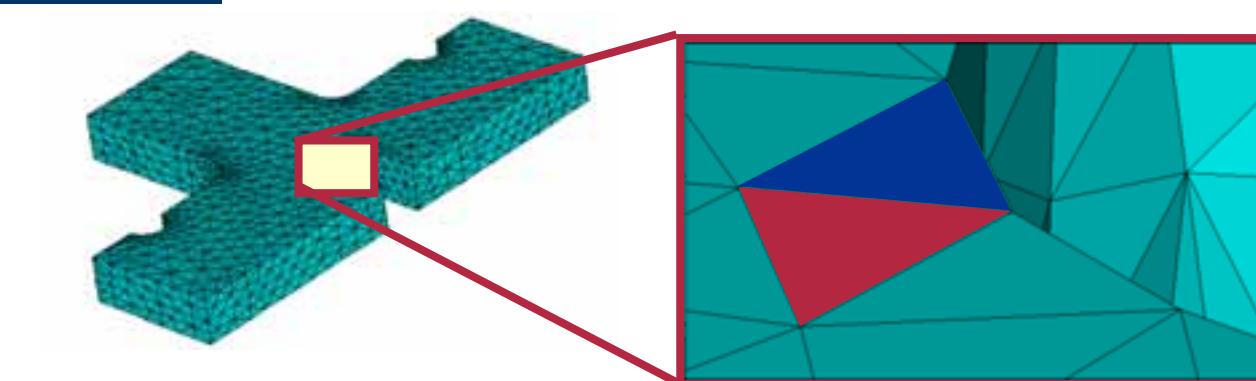
Matrix completely filled

Number of matrix elements $\propto D^4$

Solvers mostly $\propto (D^2)^3 = D^6 \dots D^2 \log D^2$

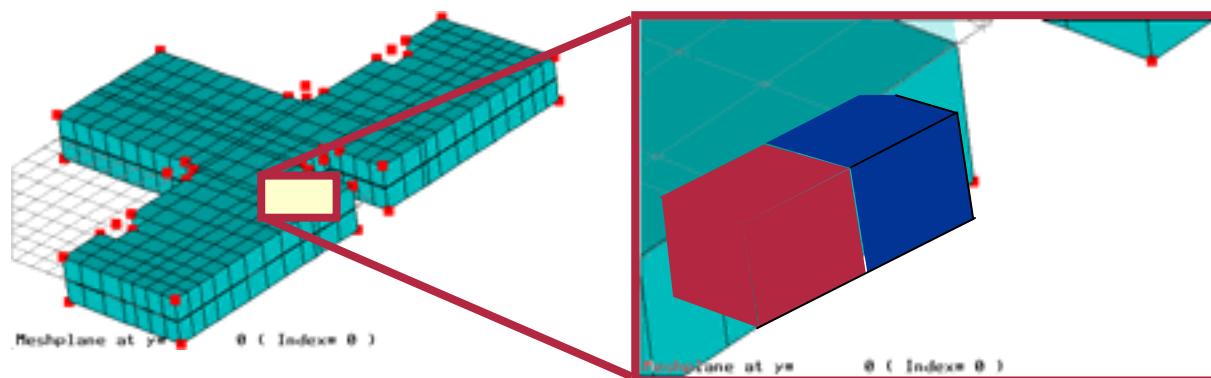
Good for linear materials

Good for Volume/Surface=Large



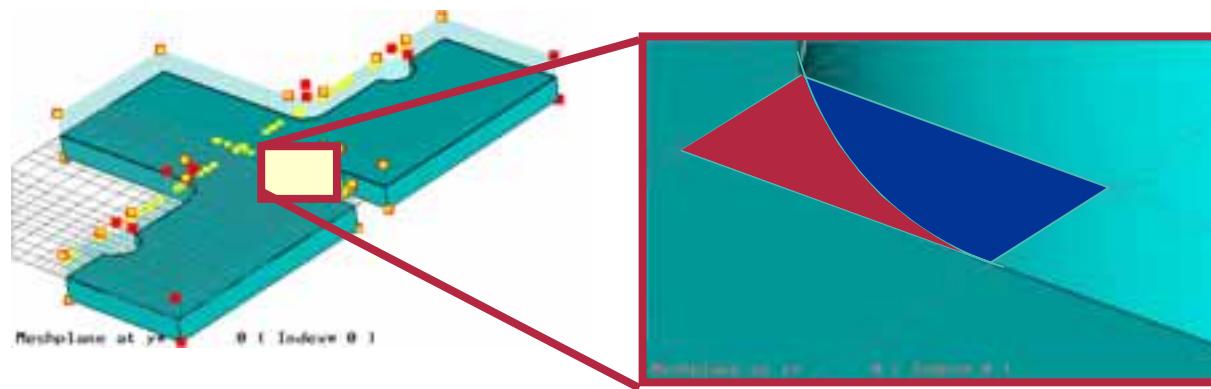
$$\epsilon_1, \mu_1, \kappa_1$$

$$\epsilon_2, \mu_2, \kappa_2$$



$$\epsilon_1, \mu_1, \kappa_1$$

$$\epsilon_2, \mu_2, \kappa_2$$

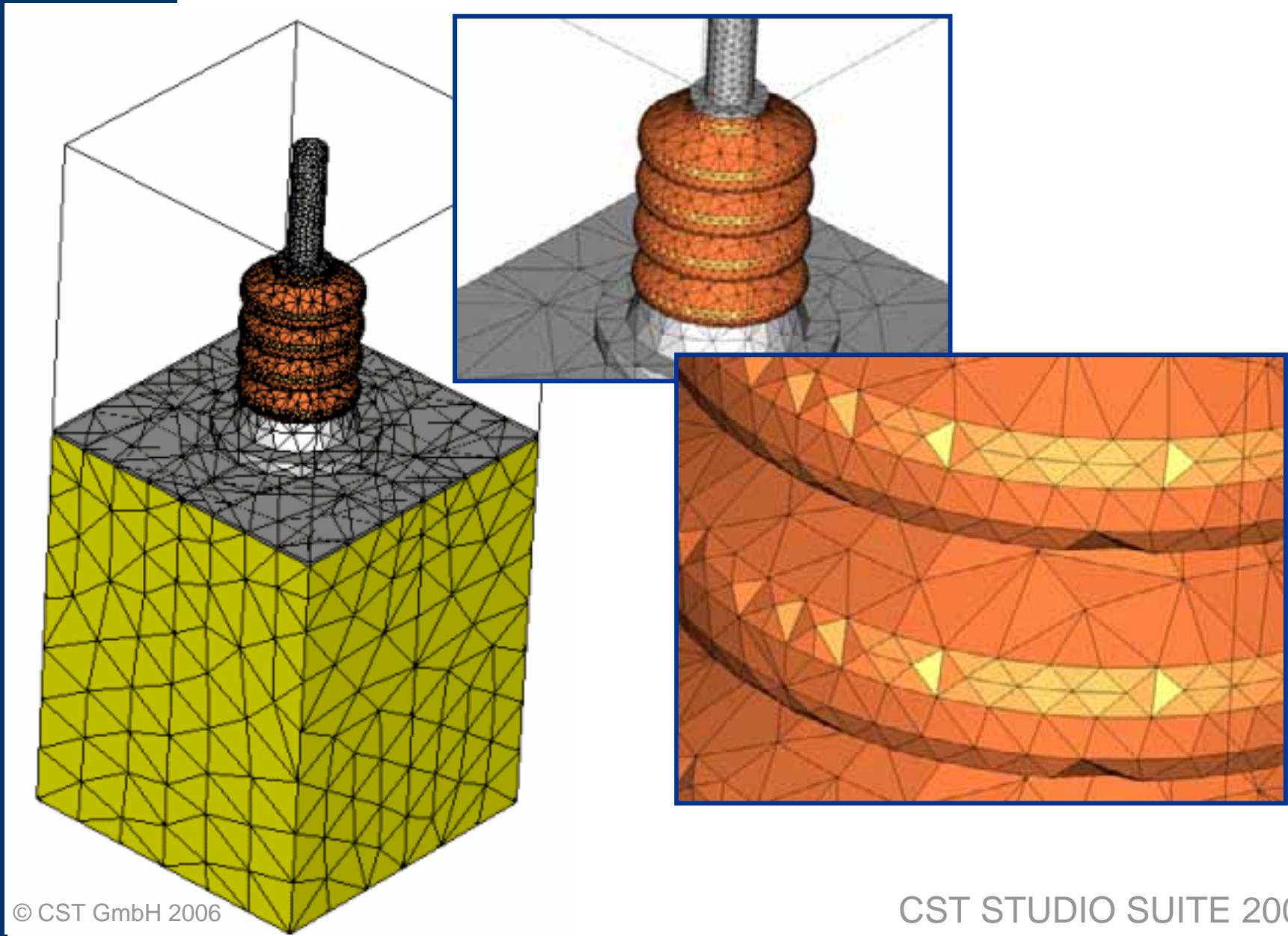


$$\epsilon_1, \mu_1, \kappa_1$$

$$\epsilon_2, \mu_2, \kappa_2$$

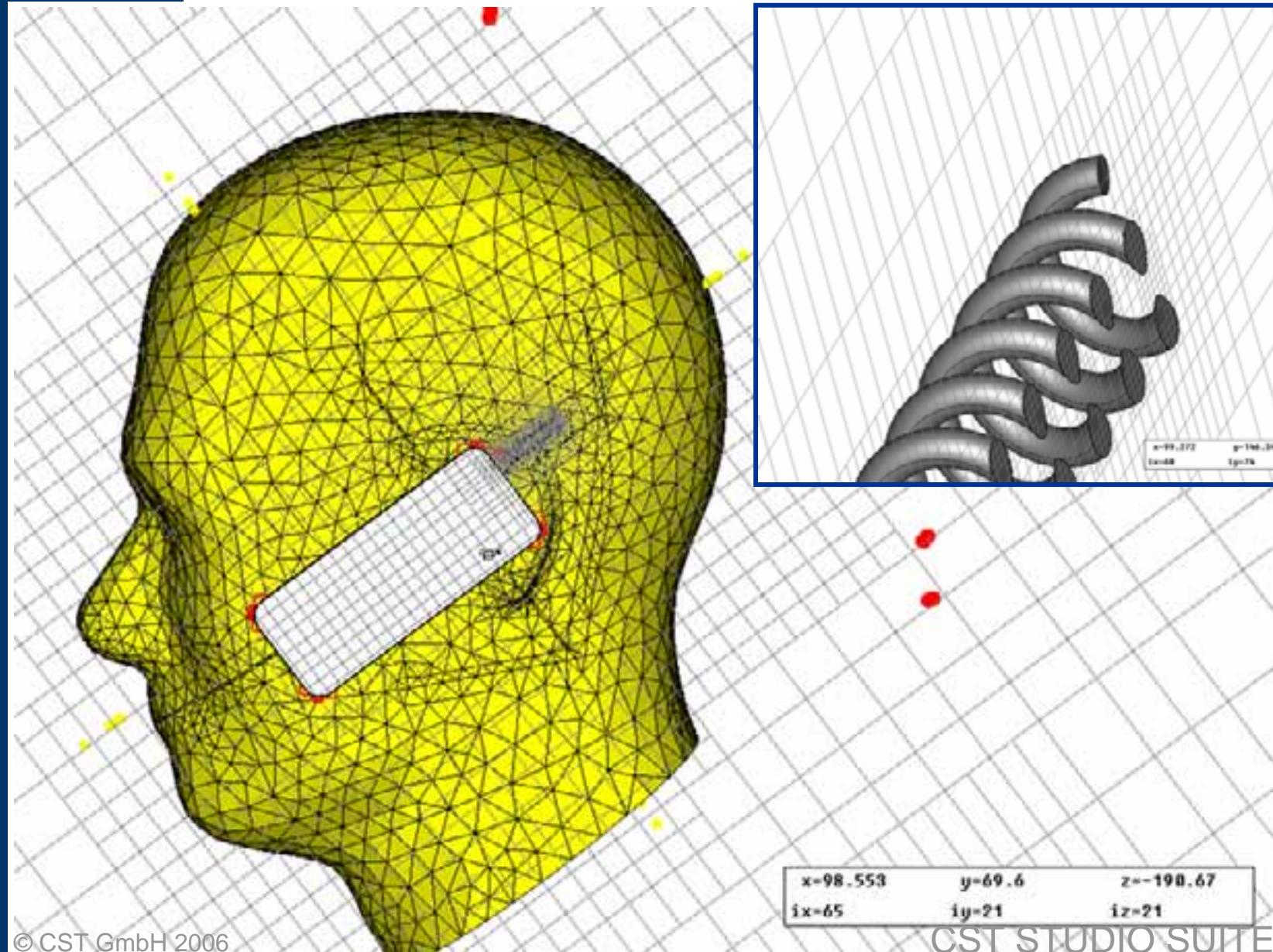


High Voltage - Bushing



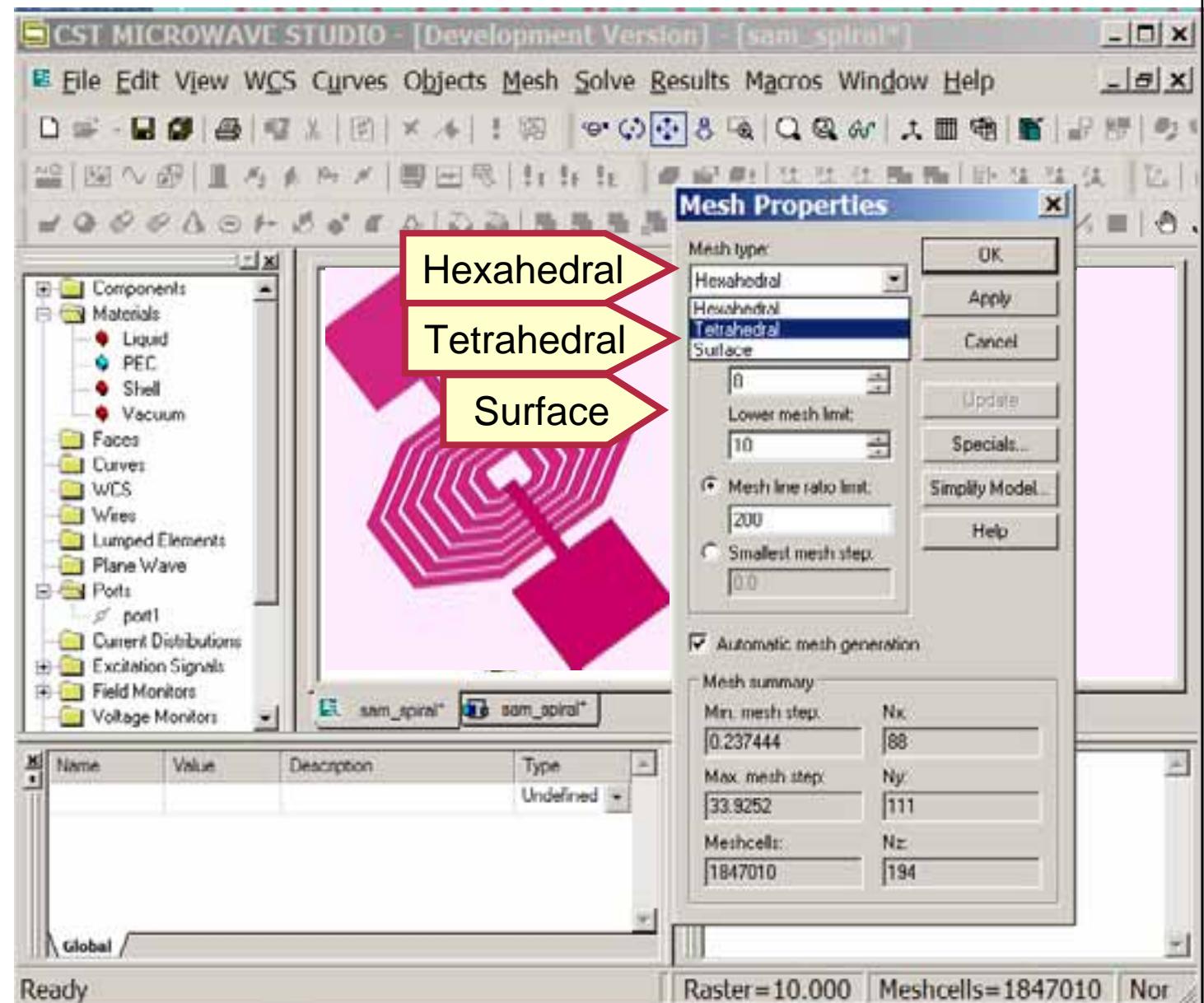


Hexahedral - Subgrids





Wide choice of mesh type

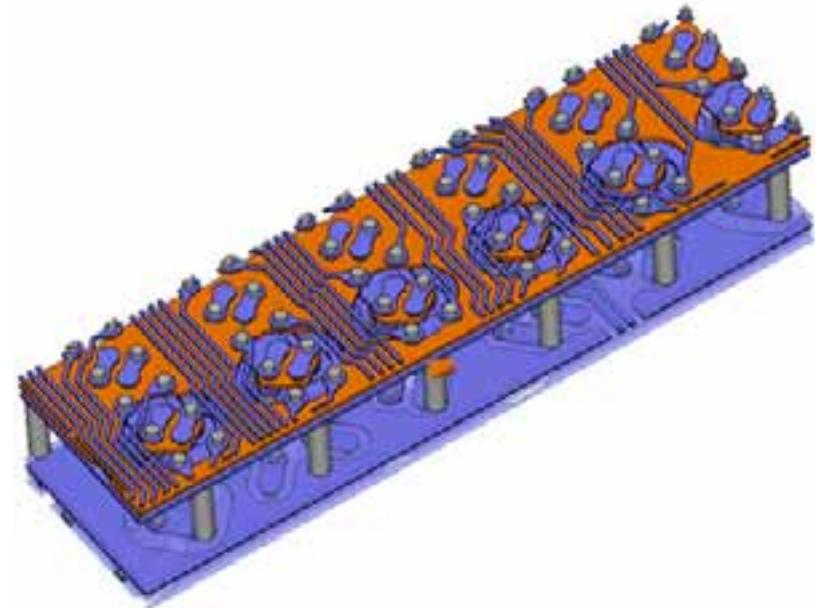




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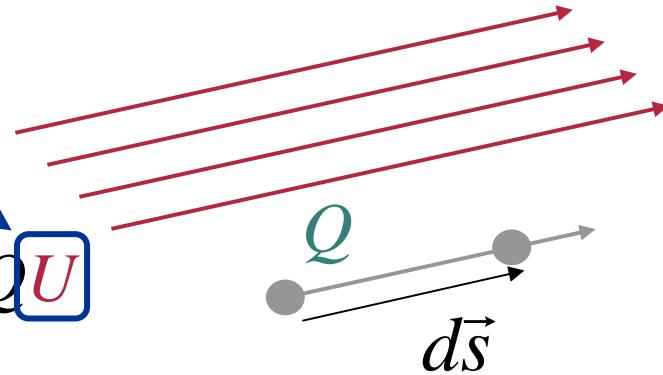
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Measurable=Integral Quantities

$$\vec{F} = Q \boxed{\vec{E}}$$

$$\vec{E} = \vec{F} / Q$$

$$\vec{F} \cdot d\vec{s} = (Q \vec{E}) \cdot d\vec{s} = Q (\vec{E} \cdot d\vec{s}) = Q \boxed{U}$$



$$\vec{F} = Q \vec{v} \times \boxed{\vec{B}}$$

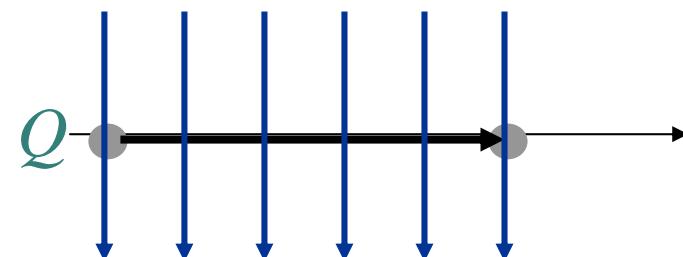
$$\Delta \vec{p} = \int \vec{F} dt$$

$$= Q \int (\vec{v} \times \vec{B}) dt = Q \vec{n} \int B v dt$$

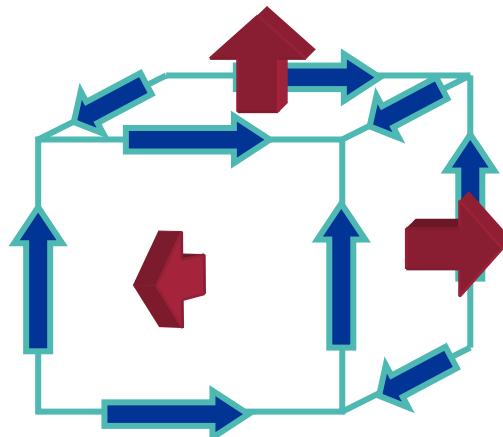
$$= Q \vec{n} \int (B d\vec{s}) = Q \vec{n} (\boxed{\Psi})$$



$$d\vec{s} = \vec{v} dt$$



- Grid G

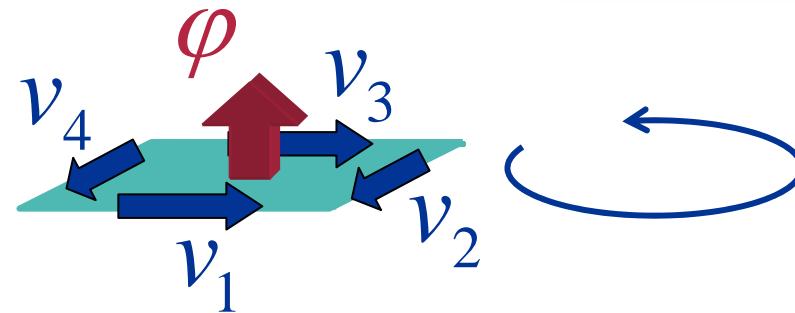


$$\varphi = \int_A \vec{B} \cdot d\vec{A}$$

$$v = \int_L \vec{E} \cdot d\vec{s}$$

$$\int_L \vec{E} \cdot d\vec{s} = - \int_A \frac{\partial}{\partial t} \vec{B} \cdot d\vec{A}$$

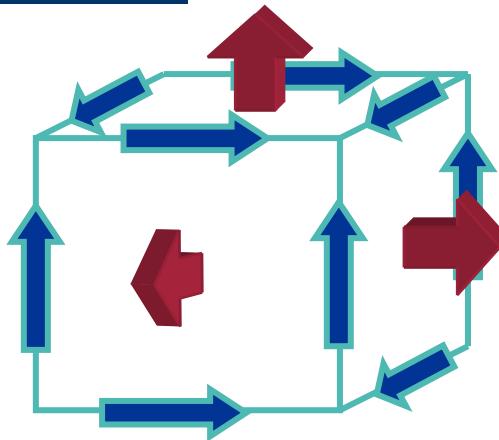
$$v_O = - \frac{d\varphi_{S_F}}{dt}$$



$$v_1 - v_2 - v_3 + v_4 = - \frac{d}{dt} \varphi$$

$$\sum_{i=1,4} c_i v_i = - \frac{d}{dt} \varphi$$

$$c_i = +/- 1$$



$$\sum_{i=1,4} c_i v_i = - \frac{d}{dt} \varphi_j$$

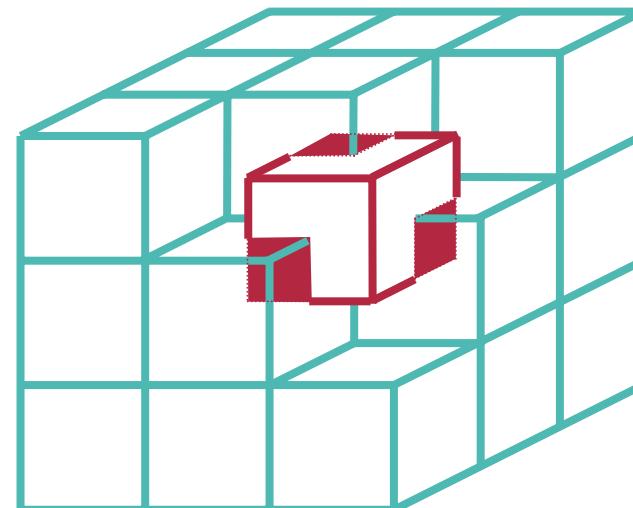
$$Cv = - \frac{d}{dt} \varphi$$

$$Ce = - \frac{d}{dt} \hat{b}$$

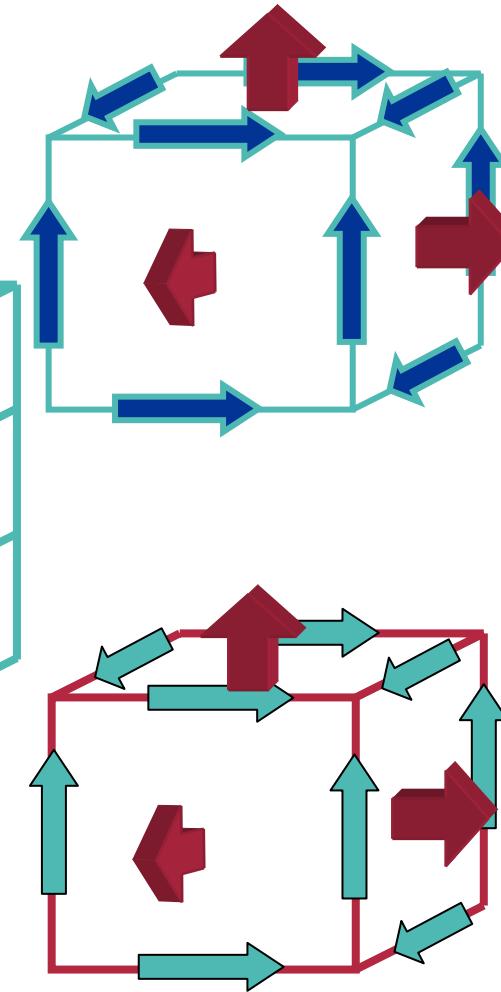
$$C = \begin{pmatrix} \dots & & & \\ & \dots & & \\ & -1 & +1 & \\ & +1 & -1 & \\ & \dots & & \end{pmatrix} \quad v = \begin{pmatrix} v_1 \\ v_2 \\ \dots \\ v_N \end{pmatrix} \quad \varphi = \begin{pmatrix} \varphi_1 \\ \varphi_2 \\ \dots \\ \varphi_N \end{pmatrix}$$

Grid \tilde{G} and \tilde{G} :

$$\tilde{C}\tilde{e} = -\frac{d}{dt}\tilde{b}$$



$$\tilde{C}\tilde{h} = \frac{d}{dt}\tilde{d} + \mathbf{j}$$



$$\hat{b} = \int_A \vec{B} \cdot d\vec{A}$$

$$\hat{e} = \int_L \vec{E} \cdot d\vec{s}$$

$$\hat{d} = \int_A \vec{d} \cdot d\vec{A}$$

„Surface charge“

$$\hat{h} = \int_L \vec{H} \cdot d\vec{s}$$

„Magnetic voltage“



Maxwell's Grid Equations

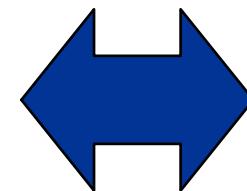
Almost Complete Discrete Form of Maxwell's Equations

$$\int_{\partial A} \vec{E} \cdot d\vec{s} = -\frac{\partial}{\partial t} \iint_A \vec{B} \cdot d\vec{A}$$

$$\int_{\partial A} \vec{H} \cdot d\vec{s} = \iint_A \left(\frac{\partial \vec{D}}{\partial t} + \vec{J} \right) \cdot d\vec{A}$$

$$\iint_{\partial V} \vec{B} \cdot d\vec{A} = 0$$

$$\iint_{\partial V} \vec{D} \cdot d\vec{A} = \iiint_V \rho \cdot dV$$



Developed
since

1975

continuous

$$\mathbf{C}\hat{\mathbf{e}} = -\dot{\mathbf{b}}$$

$$\tilde{\mathbf{C}}\hat{\mathbf{h}} = \dot{\mathbf{d}} + \mathbf{j}$$

$$\tilde{\mathbf{S}}\hat{\mathbf{d}} = \mathbf{q}$$

$$\tilde{\mathbf{S}}\hat{\mathbf{b}} = \mathbf{0}$$

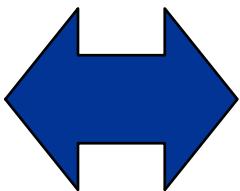
EXACT!!

discrete

$$\vec{D} = \epsilon \cdot \vec{E} + \vec{P}$$

$$\vec{B} = \mu \cdot \vec{H} + \vec{M}$$

$$\vec{J} = \kappa \cdot \vec{E}$$



?



Material Equations

$$C\hat{e} = -\dot{\hat{b}}$$

$$\tilde{C}\hat{h} = \dot{\hat{d}} + \dot{\hat{j}}$$

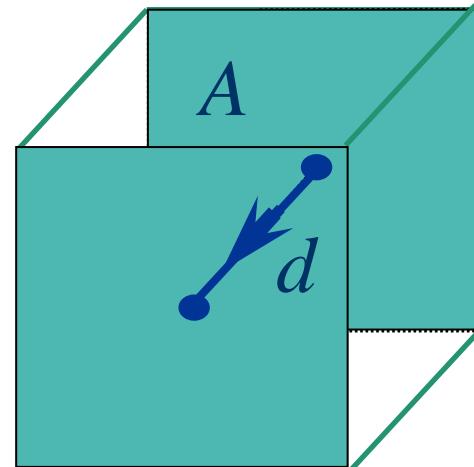
$$\tilde{S}\hat{d} = q$$

$$S\hat{b} = 0$$

+

Material relations $\hat{d} = \hat{e}, \hat{b} = \hat{h}$

*Equivalent of branch
constitutive equations*



$$\hat{d} = M_{\epsilon} \hat{e}$$

$$M_{\epsilon} : \frac{\epsilon A}{d}$$

Capacitance

Similarly:

$$\hat{b} = M_v^{-1} \hat{h}$$

$$M_v^{-1} :$$

Inductance

$$\hat{e} \approx \vec{E} \cdot d\vec{s}$$



$$\int_{\partial A} \vec{E} \cdot d\vec{s} = -\frac{\partial}{\partial t} \iint_A \vec{B} \cdot d\vec{A}$$

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$$\iint_{\partial V} \vec{B} \cdot d\vec{A} = 0$$

$$\iint_{\partial V} \vec{D} \cdot d\vec{A} = \iiint_V \rho \cdot dV$$

$$\vec{D} = \epsilon \cdot \vec{E} + \vec{P}$$

$$\vec{B} = \mu \cdot \vec{H} + \vec{M}$$

$$\vec{J} = \kappa \cdot \vec{E}$$

Developed

1975

$$\mathbf{C}\hat{\mathbf{e}} = -\dot{\mathbf{b}}$$

$$\tilde{\mathbf{C}}\hat{\mathbf{h}} = \dot{\mathbf{d}} + \dot{\mathbf{j}}$$

$$\tilde{\mathbf{S}}\hat{\mathbf{d}} = \mathbf{q}$$

Choice of FD/FE/FI/FV....

$$\mathbf{d} = \mathbf{M}_t \hat{\mathbf{e}} + \hat{\mathbf{p}}$$

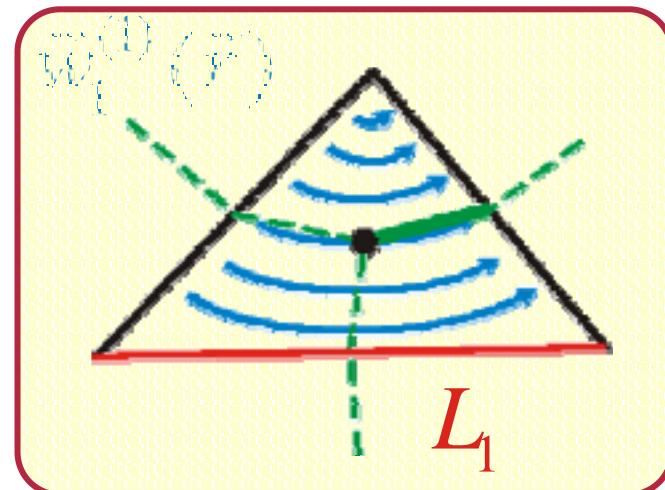
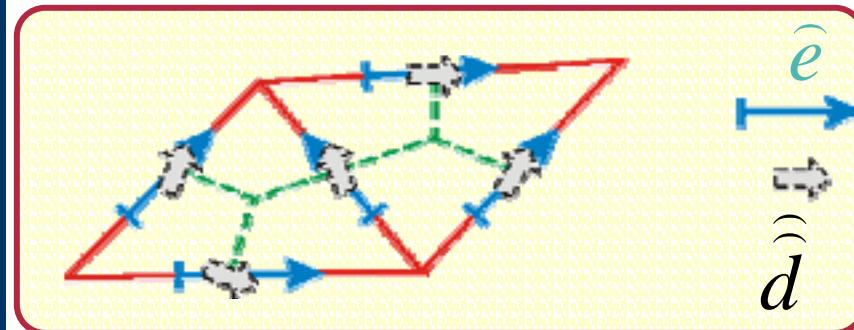
$$\mathbf{b} = \mathbf{M}_v^{-1} \hat{\mathbf{h}} + \hat{\mathbf{m}}$$

$$\mathbf{j} = \mathbf{M}_\sigma \hat{\mathbf{e}}$$

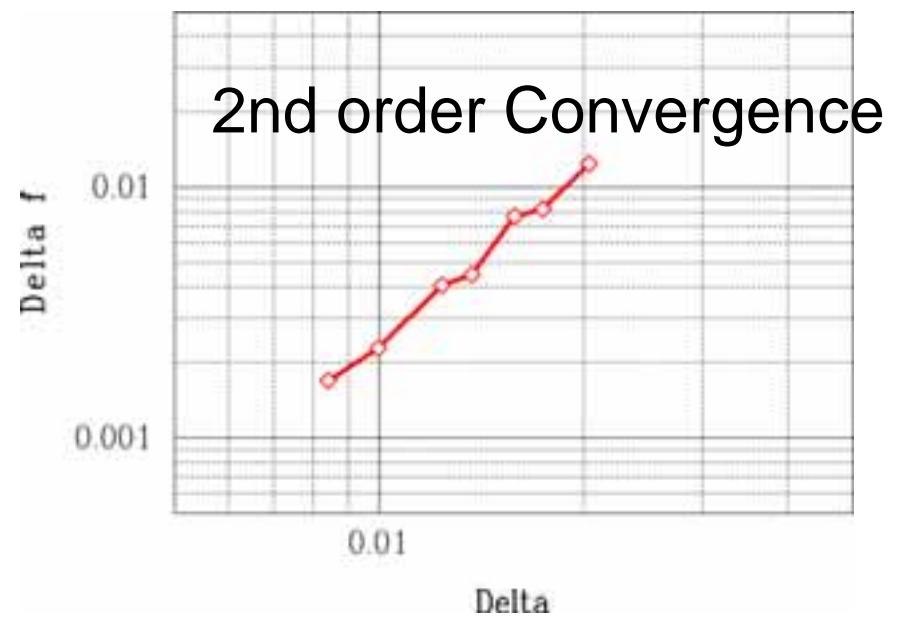
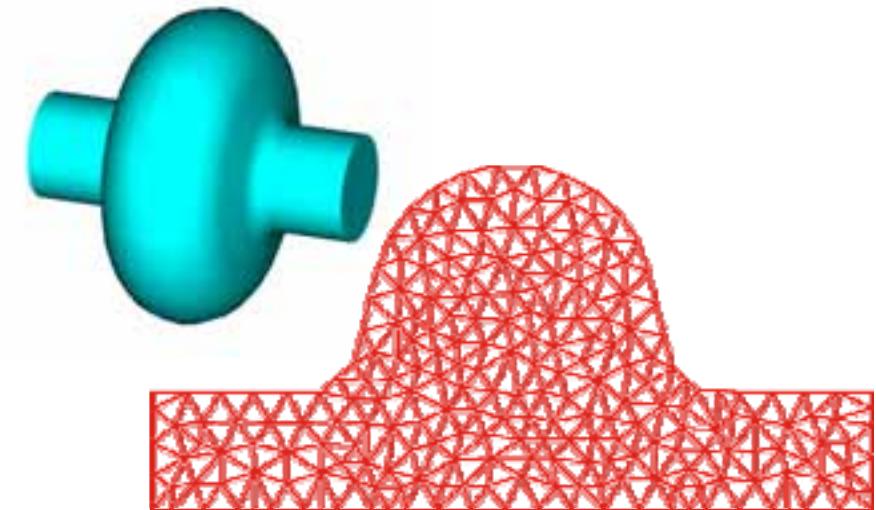
EXACT!!



Allocation of integral components
van Rienen 1983



Discrete Material Relation
based on Whitney elements
R. Schuhmann 2001





Circuit mesh analysis

$$\frac{\partial}{\partial t} = 0$$

Circuit equations

$$\mathbf{Cv} = 0$$

$$\mathbf{C}^T \mathbf{i}_m = \mathbf{i}$$

$$\mathbf{v} = \mathbf{Ri} + \mathbf{v}_S$$

$$\boxed{\mathbf{CRC}^T \mathbf{i}_m = -\mathbf{Cv}_S}$$

Field analysis

$$\mathbf{C}\hat{\mathbf{e}} = 0$$

$$\mathbf{C}^T \hat{\mathbf{h}} = \hat{\mathbf{j}}$$

$$\hat{\mathbf{e}} = \mathbf{M}_\rho \hat{\mathbf{j}} + \hat{\mathbf{e}}_S$$

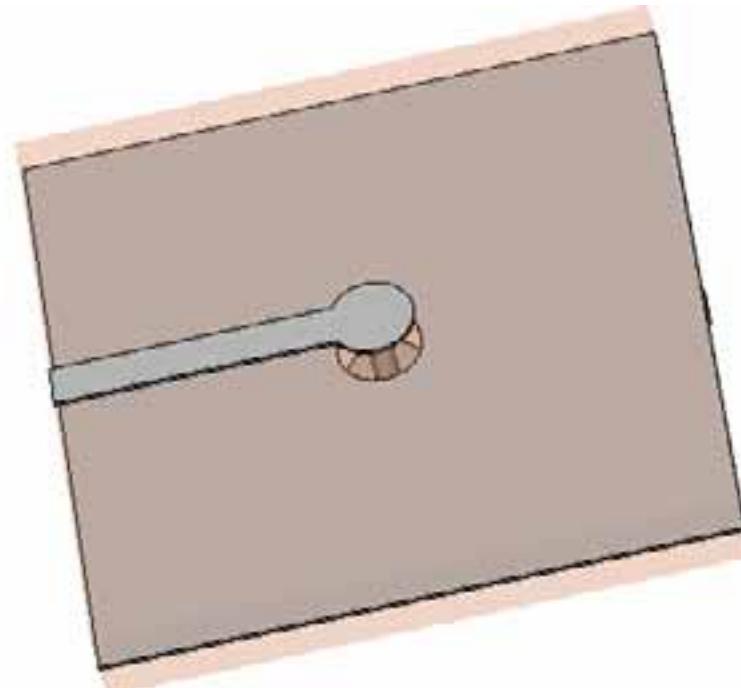
$$\boxed{\mathbf{CM}_\rho \mathbf{C}^T \hat{\mathbf{h}} = -\mathbf{C}\hat{\mathbf{e}}_S}$$



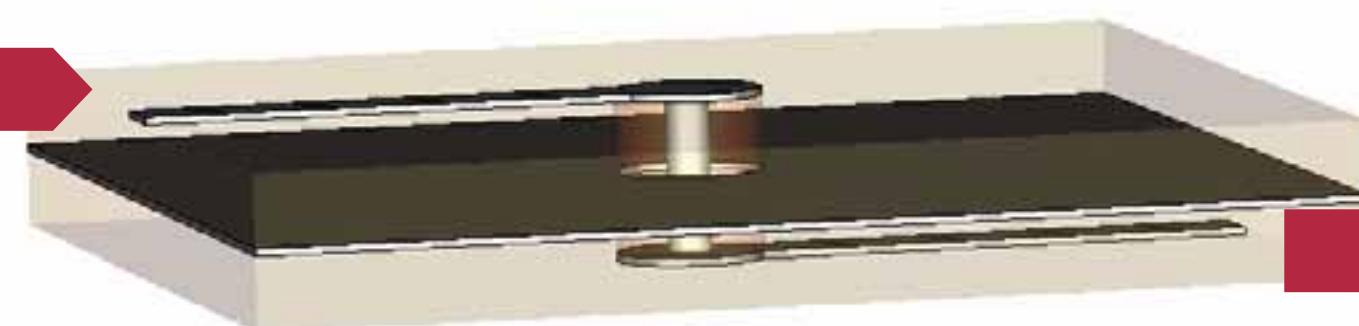
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Simple Via Structure



Input port

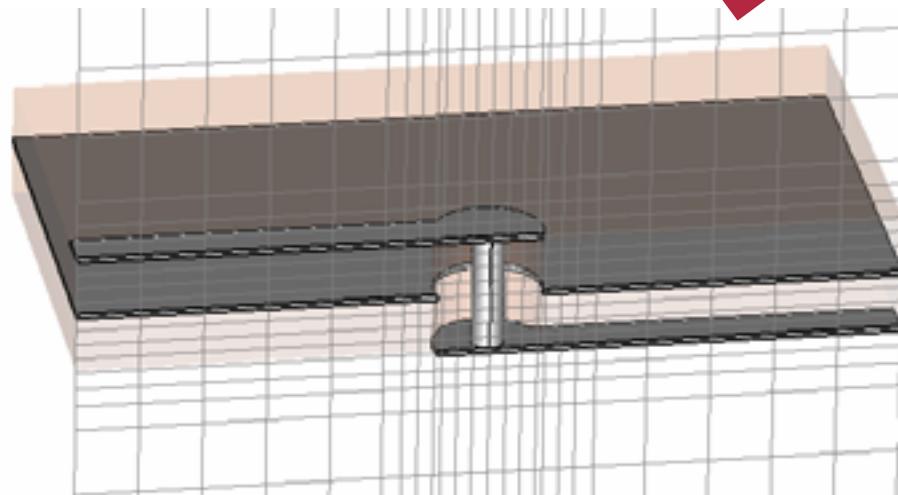


Output port



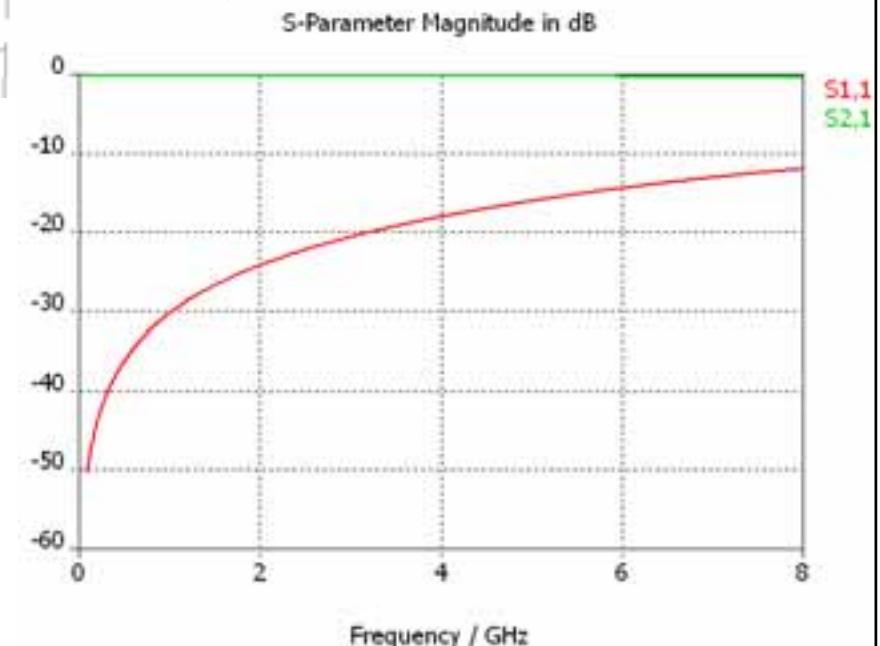
- HEX Transient Solution
- HEX Frequency Domain
- TET Frequency Domain
- Model Order Reduction

- HEX Transient Solution



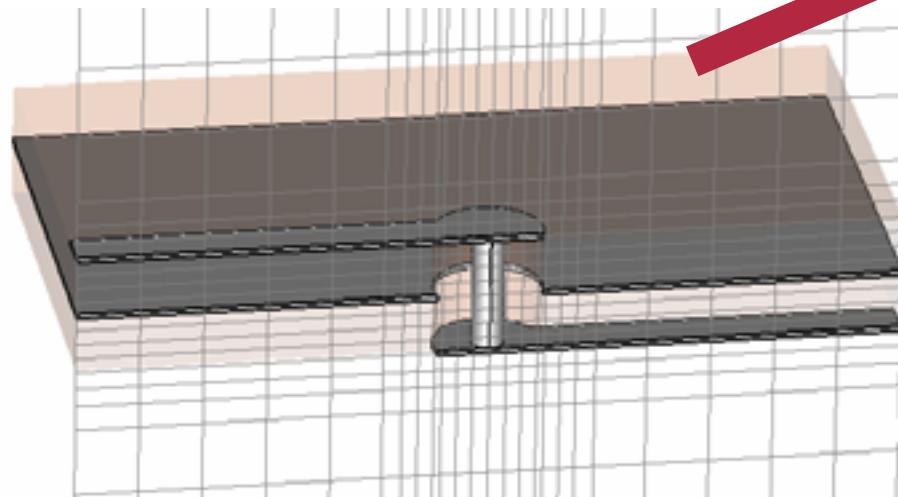
$$\tilde{\mathbf{C}}\mathbf{M}_v \mathbf{C}\hat{\mathbf{e}} + \mathbf{M}_\kappa \frac{d}{dt} \hat{\mathbf{e}} + \mathbf{M}_\varepsilon \frac{d^2}{dt^2} \hat{\mathbf{e}} = -\frac{d}{dt} \hat{\mathbf{j}}_s$$

FFT(Output) / FFT(Input)



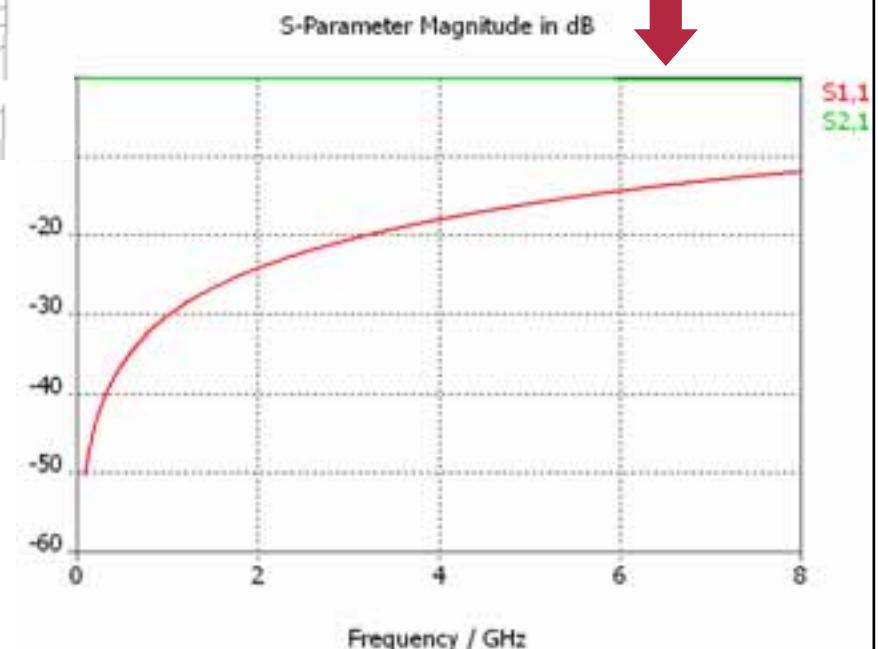
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- HEX Transient Solution
- **HEX Frequency Domain**



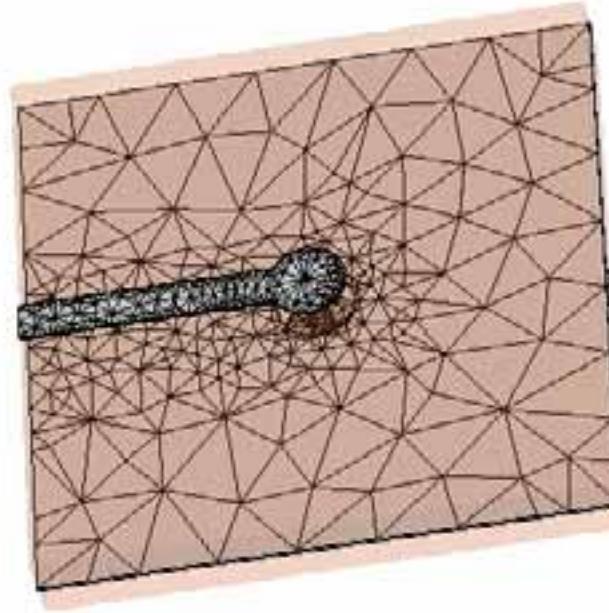
$$(\tilde{\mathbf{C}}\mathbf{M}_v \mathbf{C} + i\omega \mathbf{M}_\kappa - \omega^2 \mathbf{M}_\varepsilon) \hat{\mathbf{e}} = -i\omega \hat{\mathbf{j}}_s$$

$$\mathbf{A} \hat{\mathbf{e}} = \mathbf{r}$$



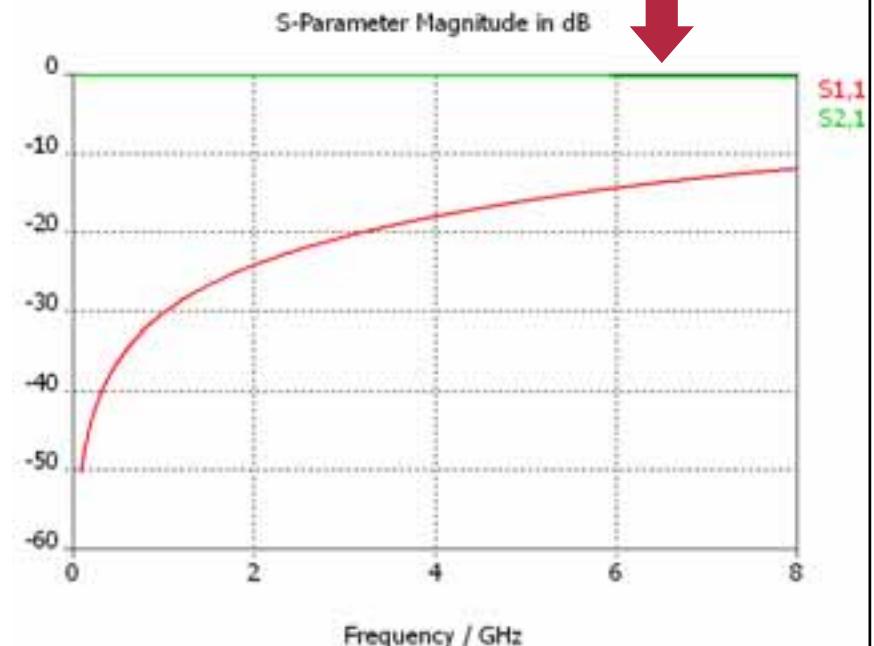
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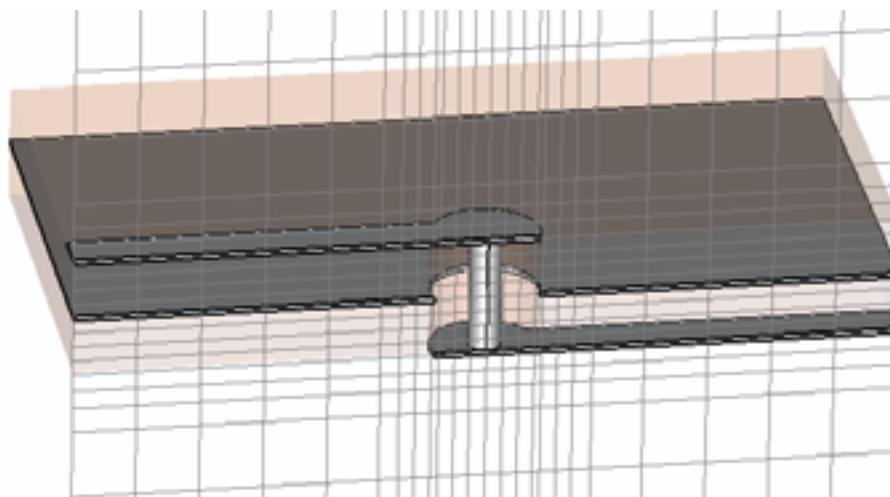
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$$\mathbf{A}\hat{\mathbf{e}} = \mathbf{r}$$



- Model Order Reduction

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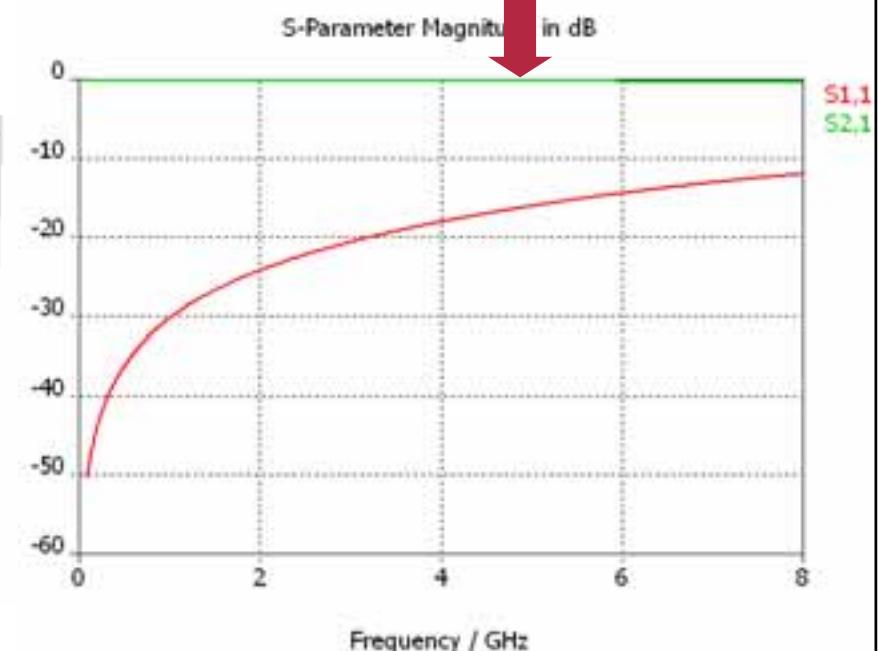


$$(\tilde{\mathbf{C}}\mathbf{M}_v\mathbf{C} + i\omega \mathbf{M}_\kappa - \omega^2 \mathbf{M}_e)\hat{\mathbf{e}} = -i\omega \hat{\mathbf{j}}_s$$

$$\mathbf{A}_{N \times N} \hat{\mathbf{e}} = \mathbf{r}$$

MOR

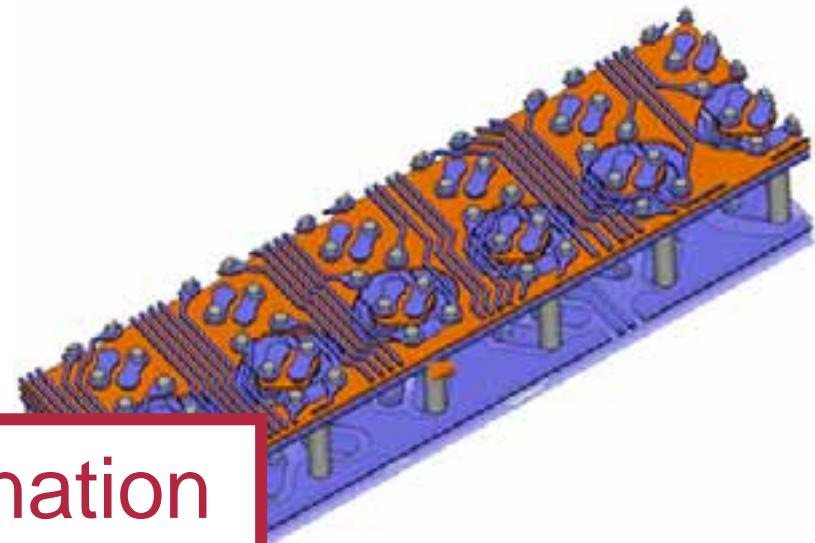
$$\mathbf{A}_{n \times n} \hat{\mathbf{e}} = \mathbf{r}$$



EM Solution = 3 Steps

1 Spatial Discretization of geometry

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Which combination

is the best ?

2 Local approximation

Maxwell's Equations

- Finite Difference
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Solving the algebraic system

- Direct solver
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Selection of the “best” Algorithm

$$G = \frac{Q}{\$}$$

Required accuracy

Reliability

Robustness

Absolute Calc. Time

....

CPU

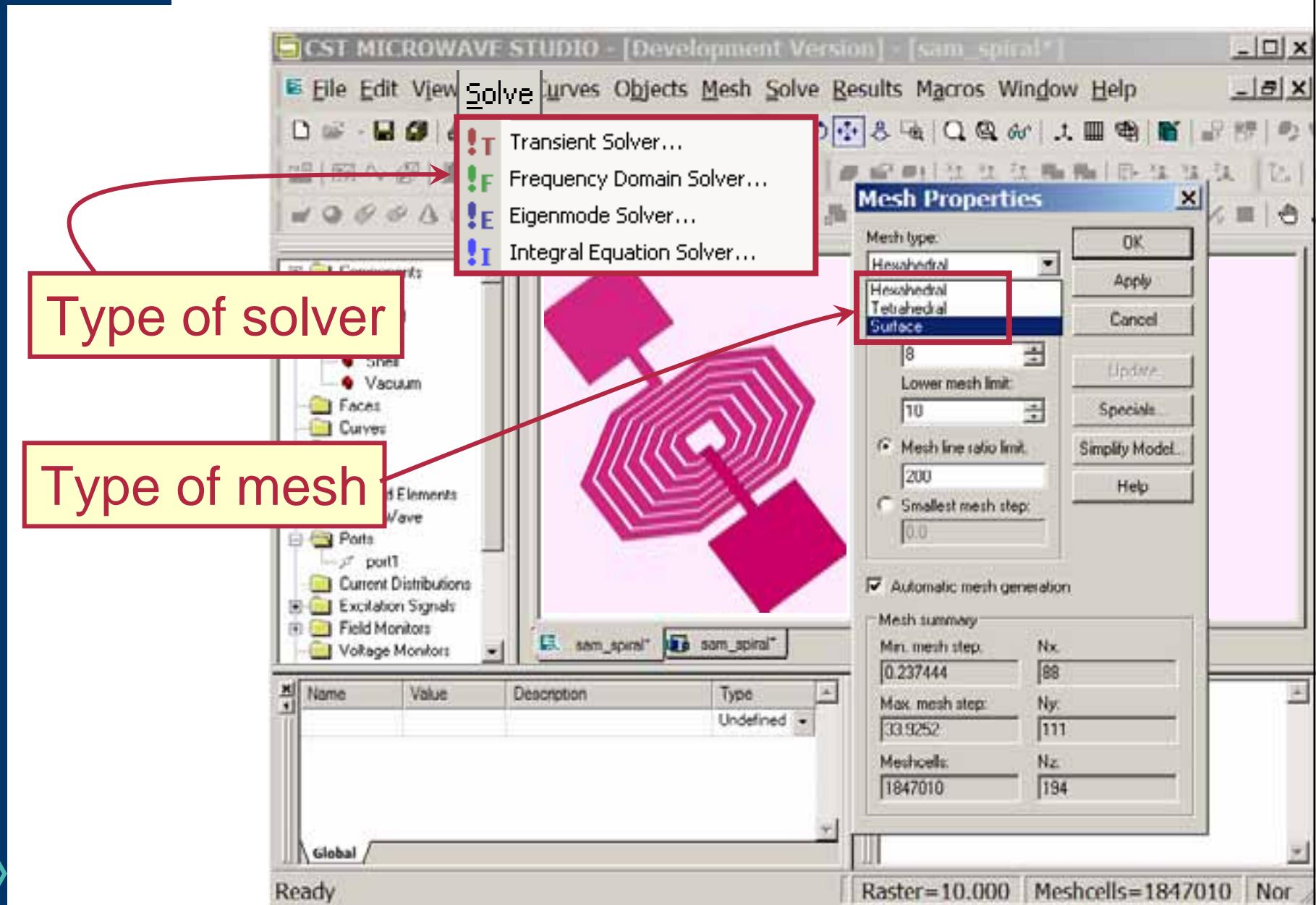
Memory

Manpower

....



Example of User Choice

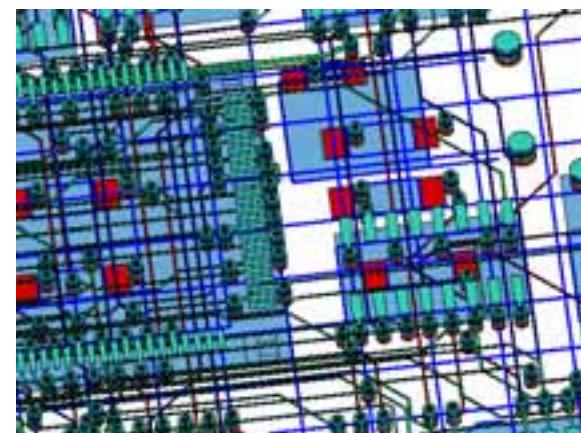
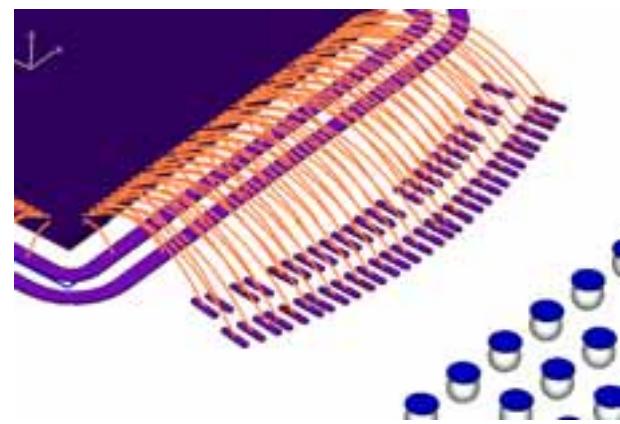
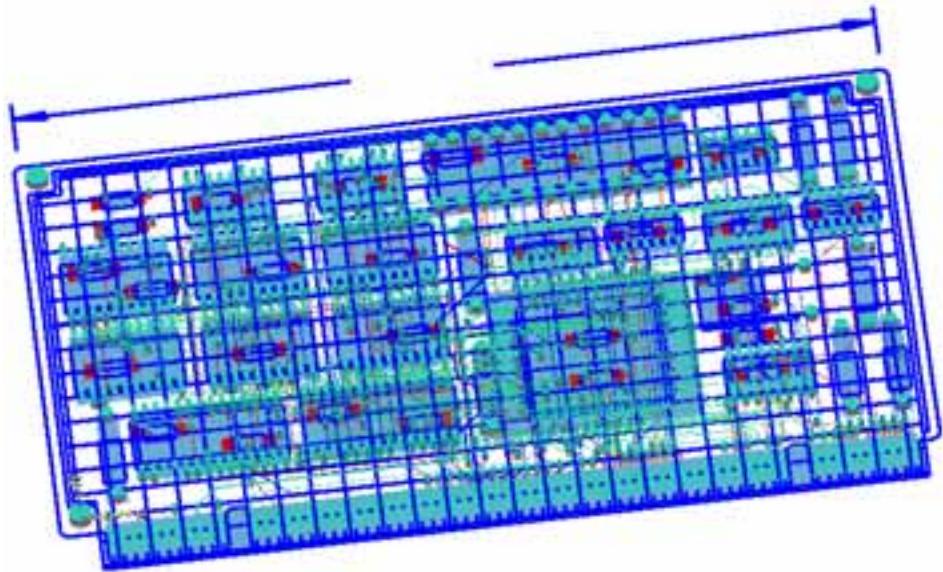
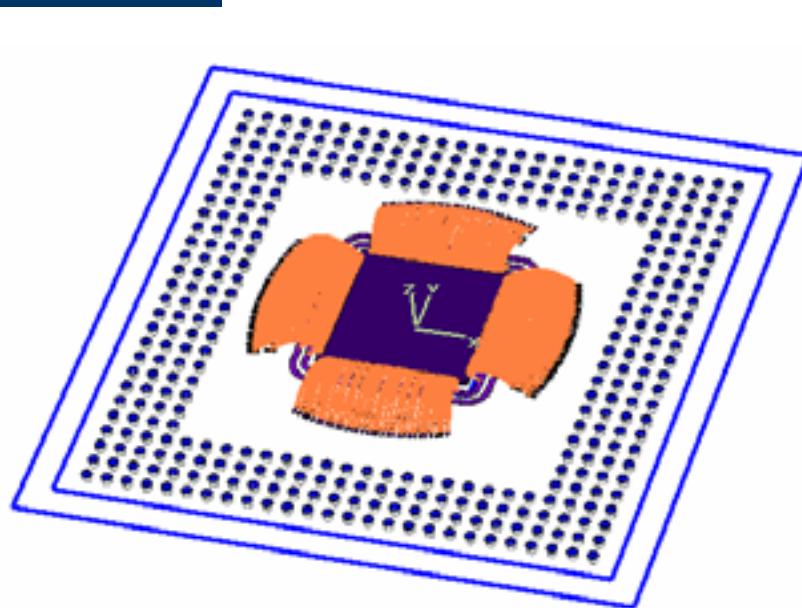




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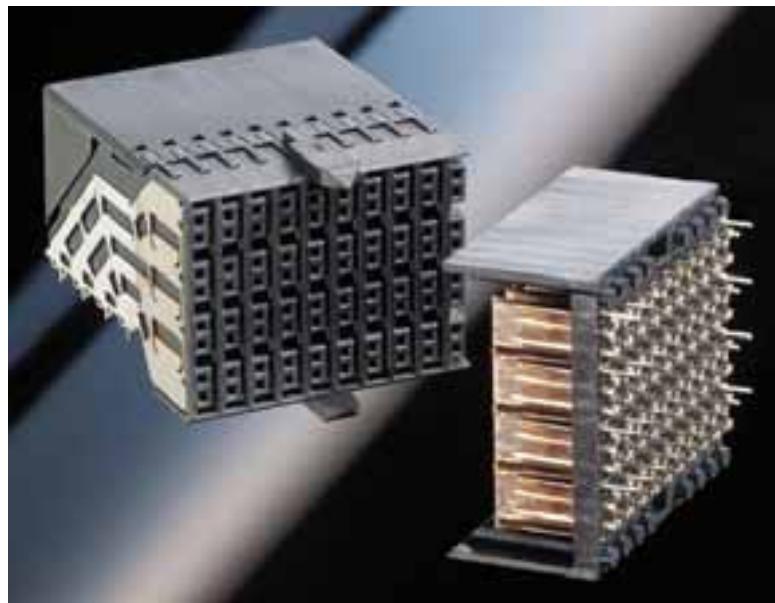
Structures get more complex



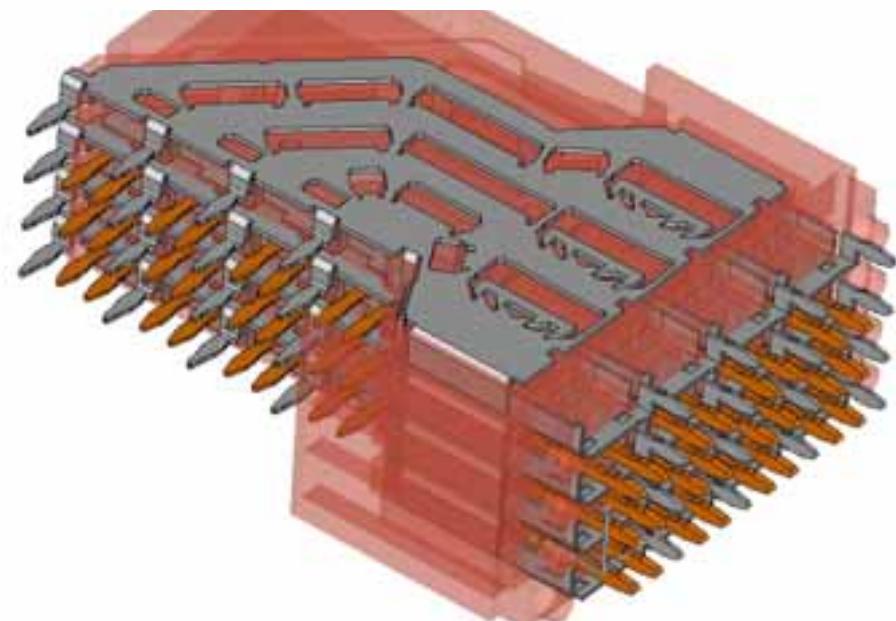
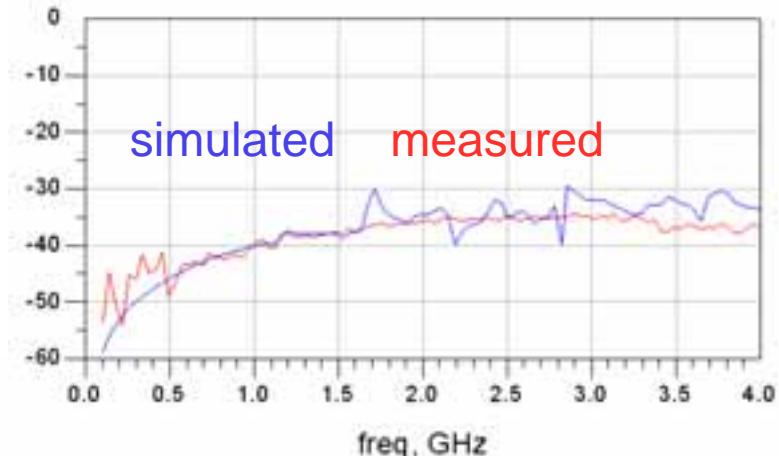


ERNI ERmet zeroXT High Speed SMT Connector

Can handle differential signals up to 10 GBit/s



Near end crosstalk pairs CD - EF

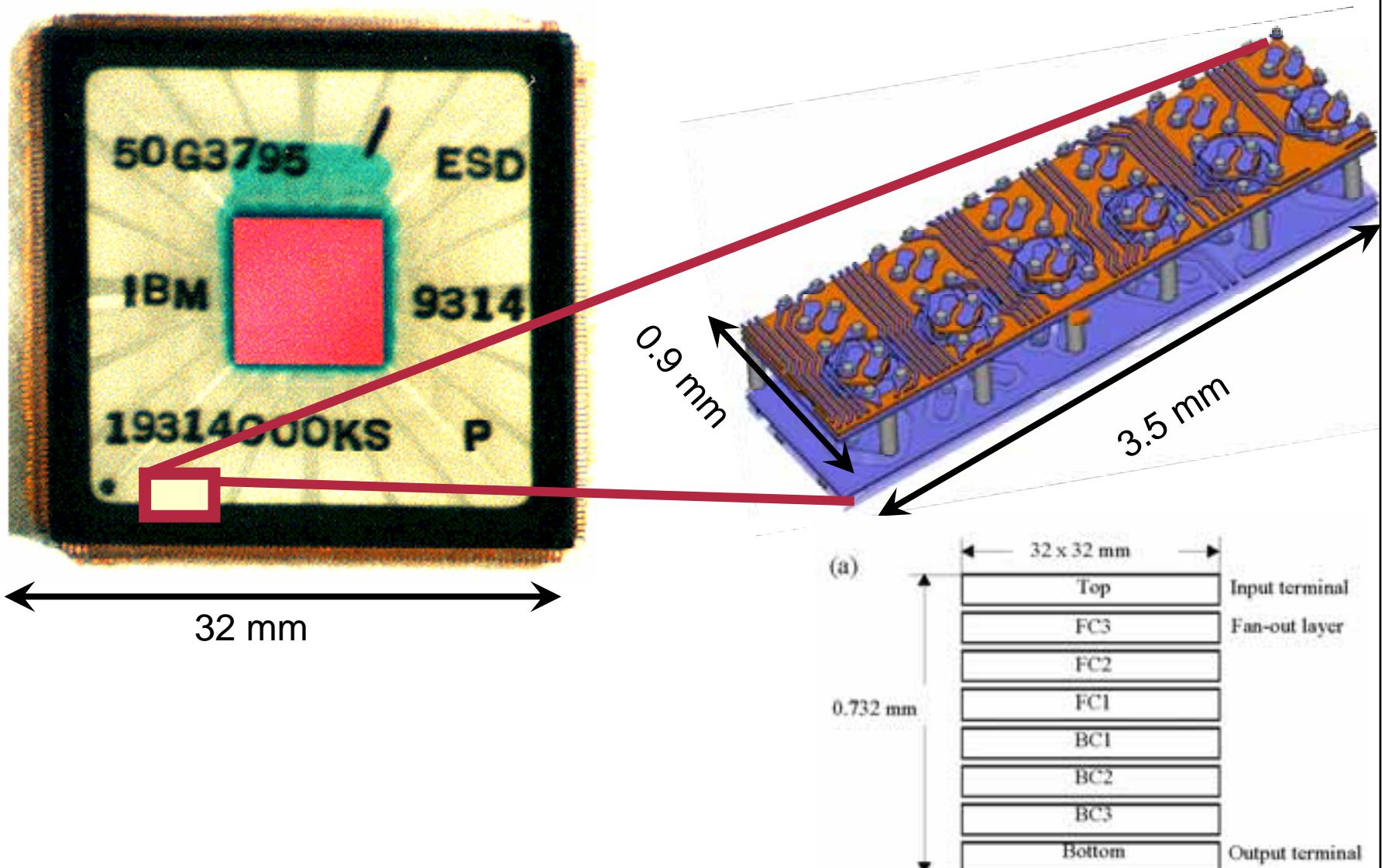


ERNI:

*... the connector could be manufactured without
a major re-design in one pass...."*

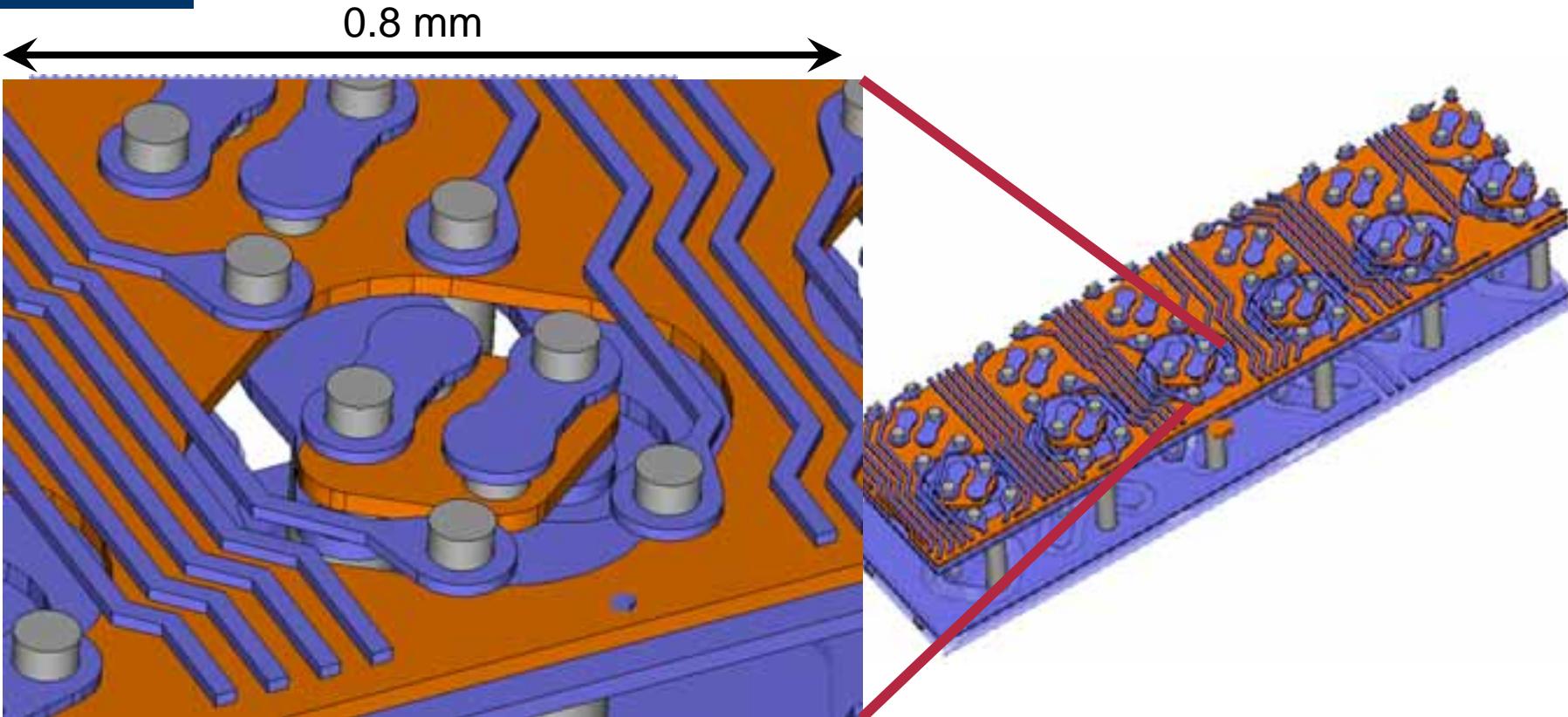
Very Large Problems

- IBM Example





E-Small Very Large Problems





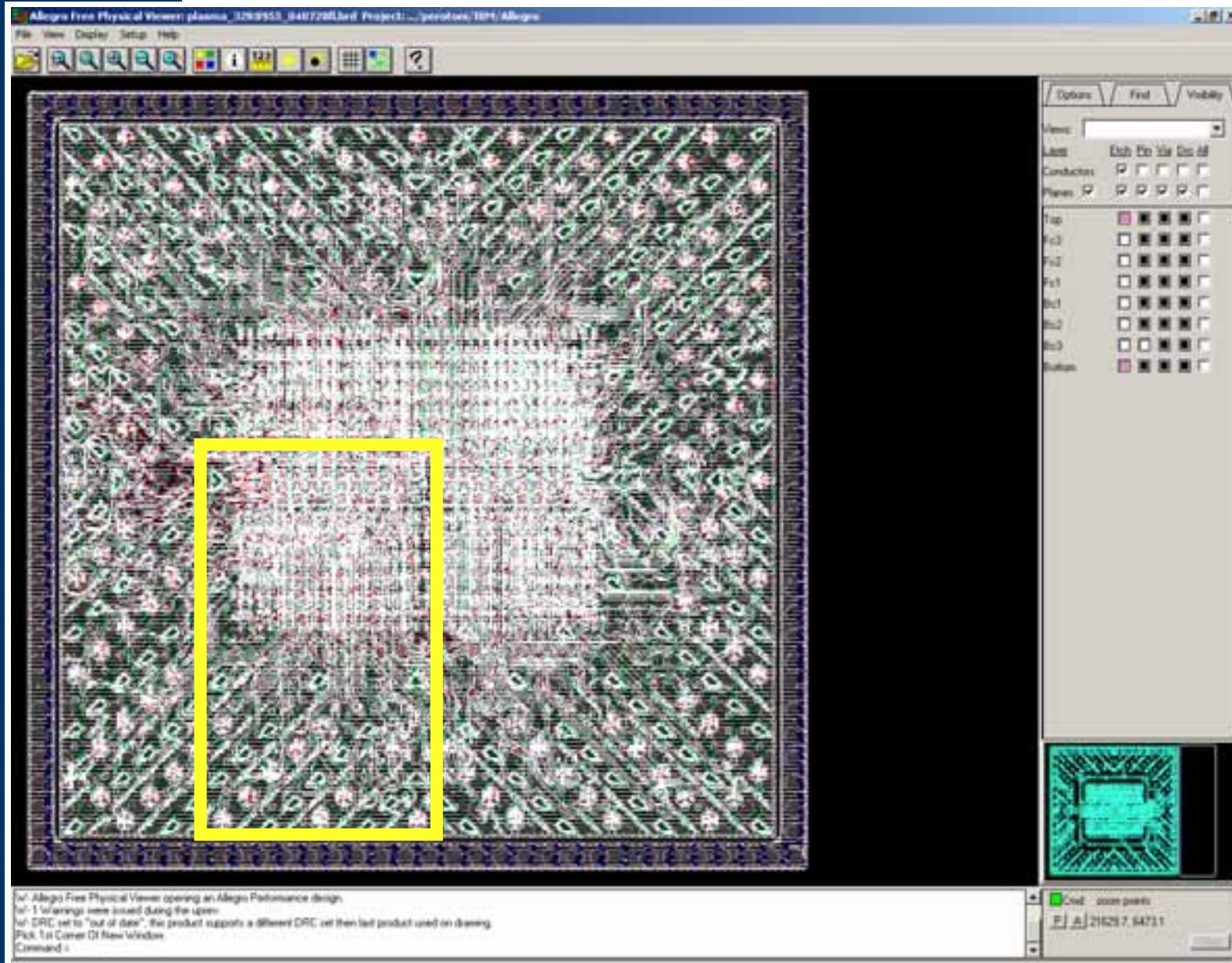
- Use commerical software „as is“
Limited by memory size of my computer (5GB)
Size of domain only 25% of entire structure
 - **Time domain hexahedral mesh (30 million cells)**
 - **Frequency domain tetrahedral mesh (5.3 million tet's)**

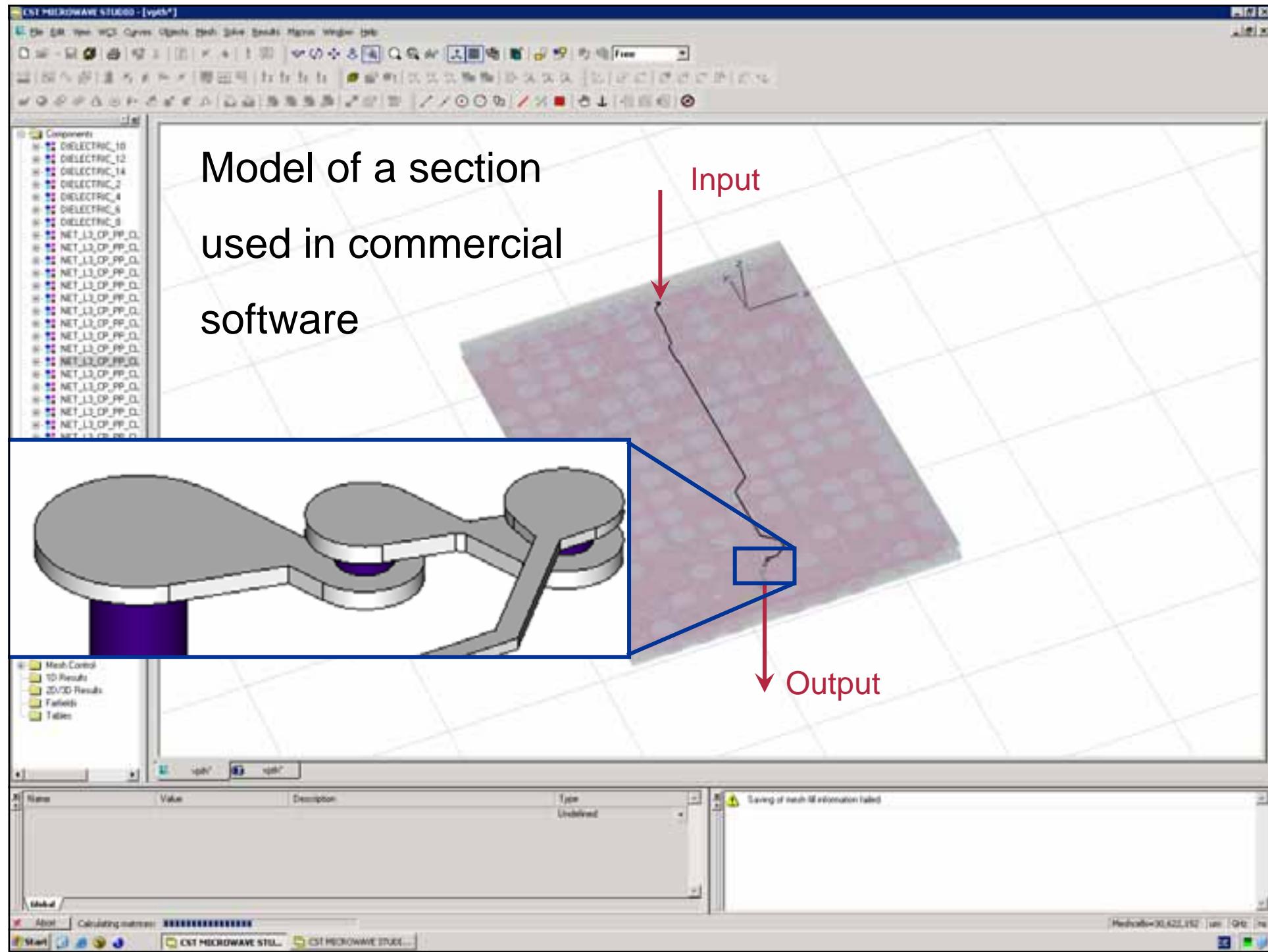
Could be easily extended by a bigger computer
- New parallel software
 - **Time domain hexahedral mesh (650 million cells)**

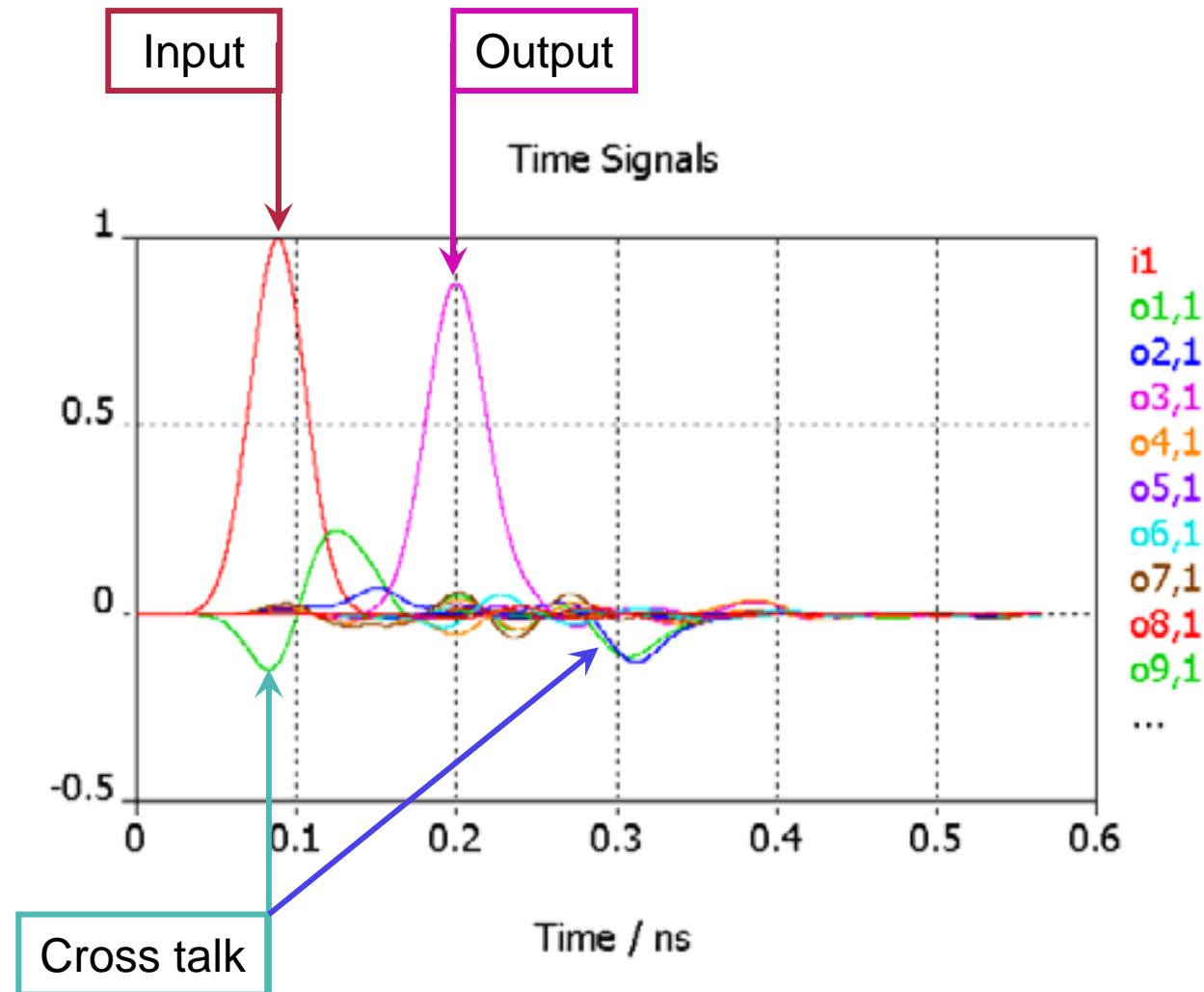
Not yet with all features



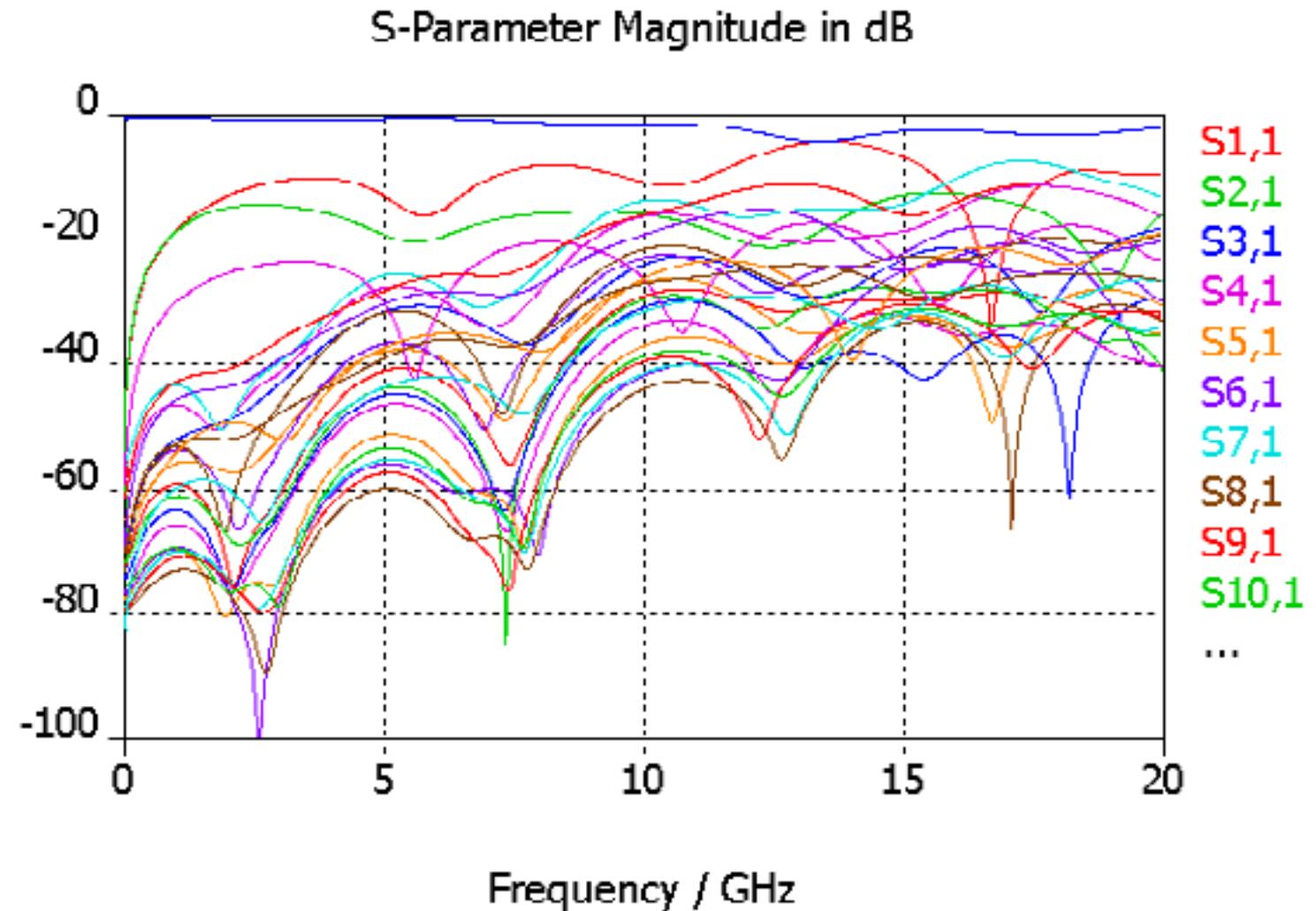
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FFT(Output) / FFT(Input)
⇒ S-Parameter for 0 to 20 GHz in **One Go!**

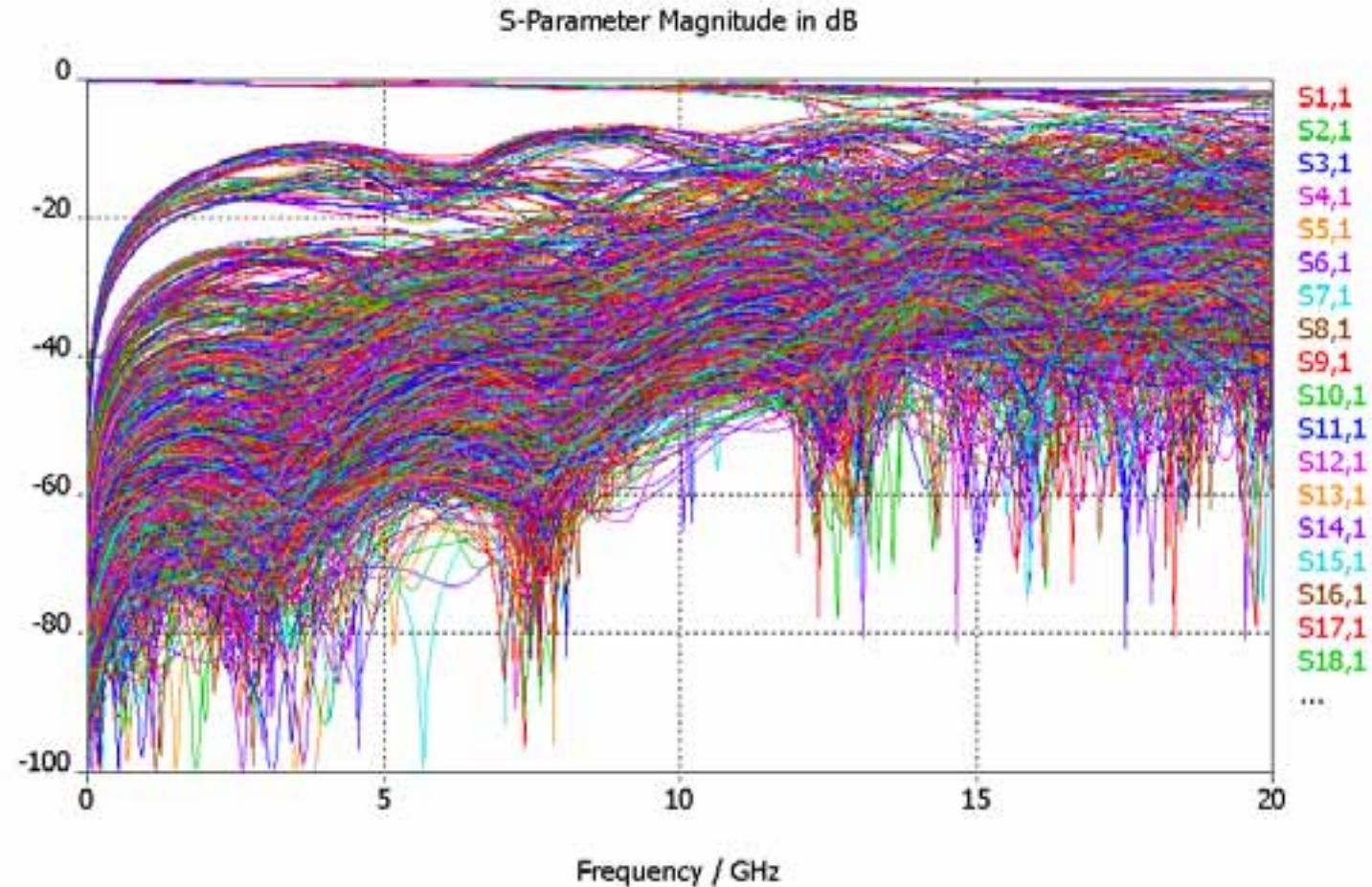




All S-parameter in one Plot

FFT(Output) / FFT(Input)

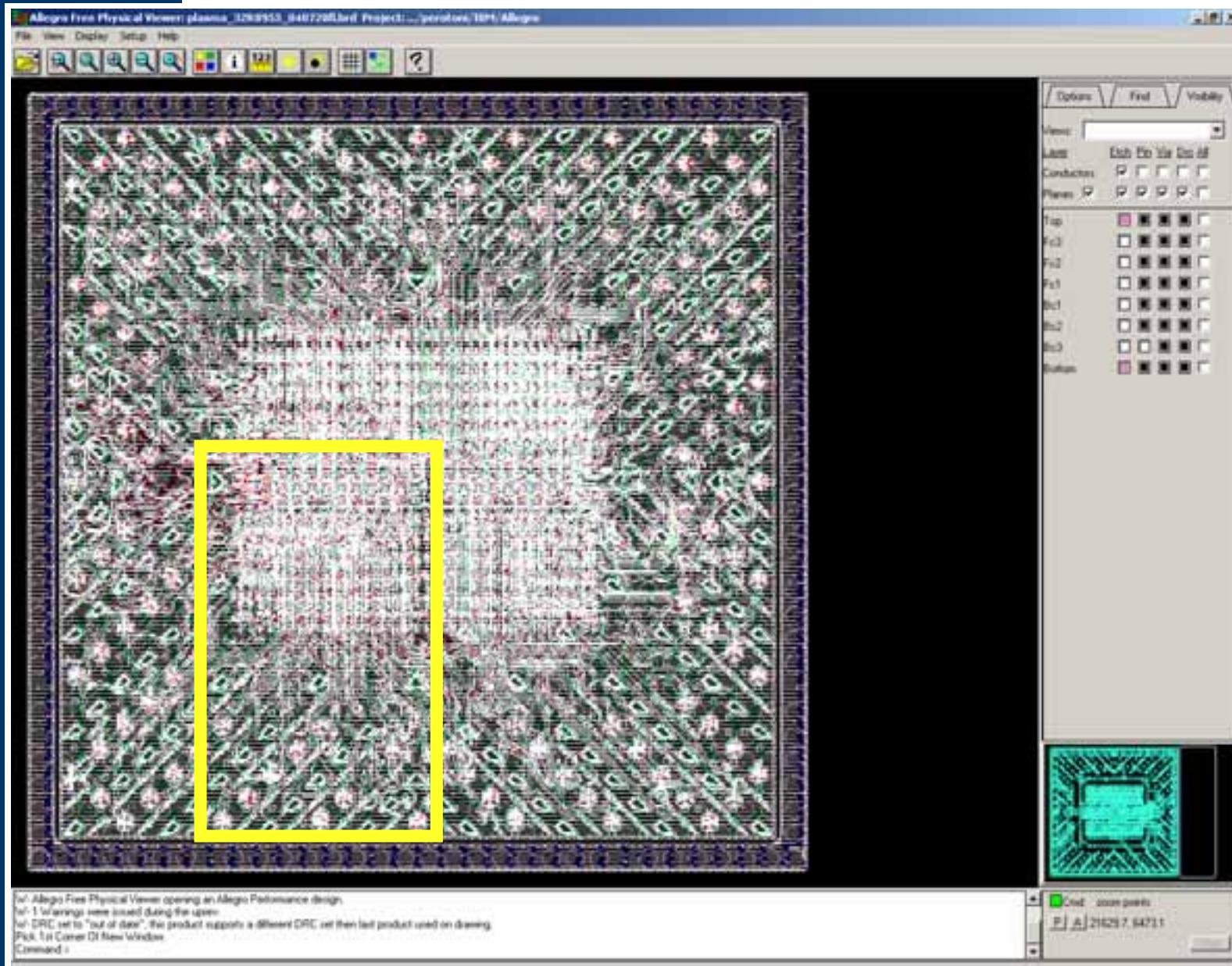
⇒ S-Parameter for 0 to 20 GHZ in One Go! **1600 curves!**

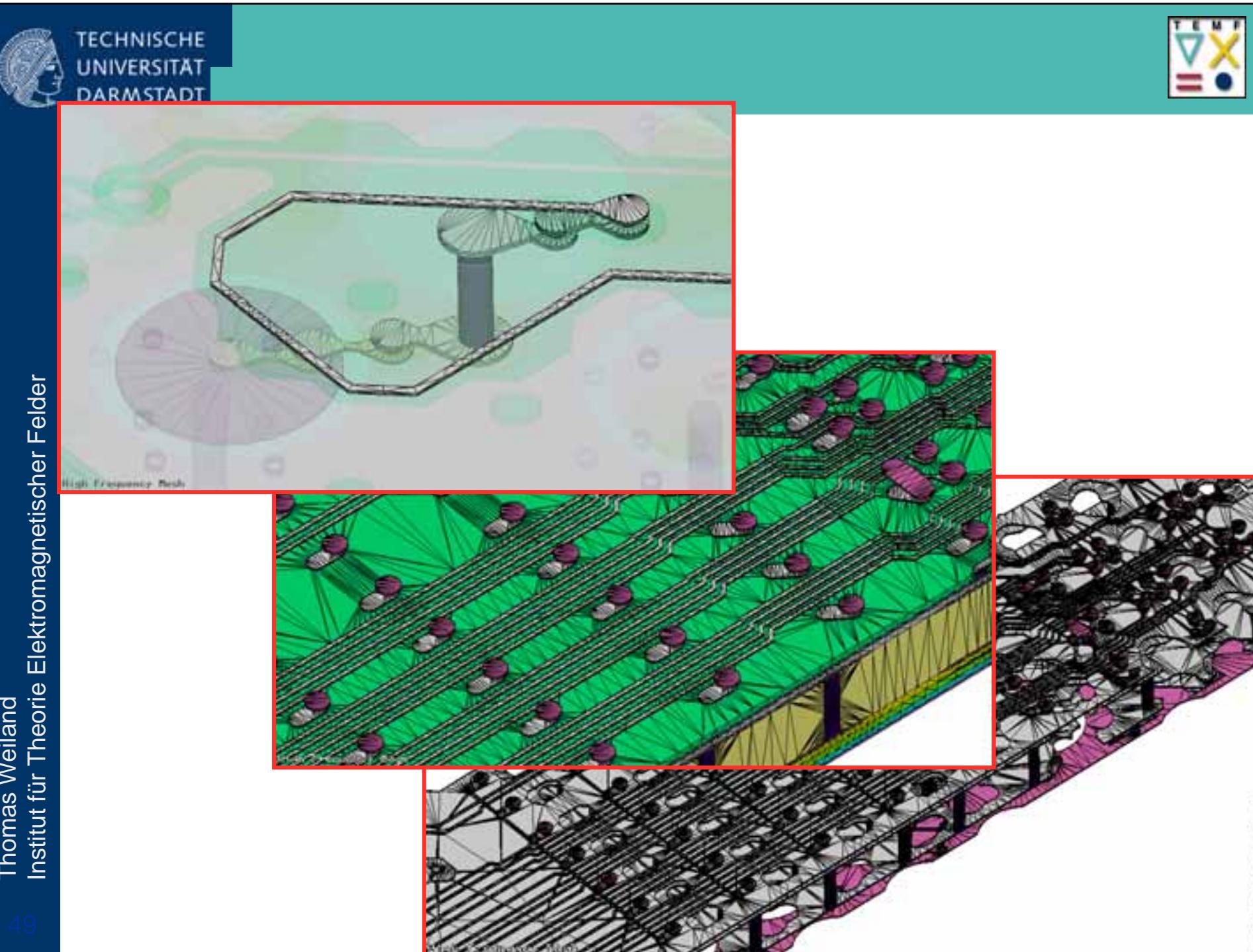




Three Solutions

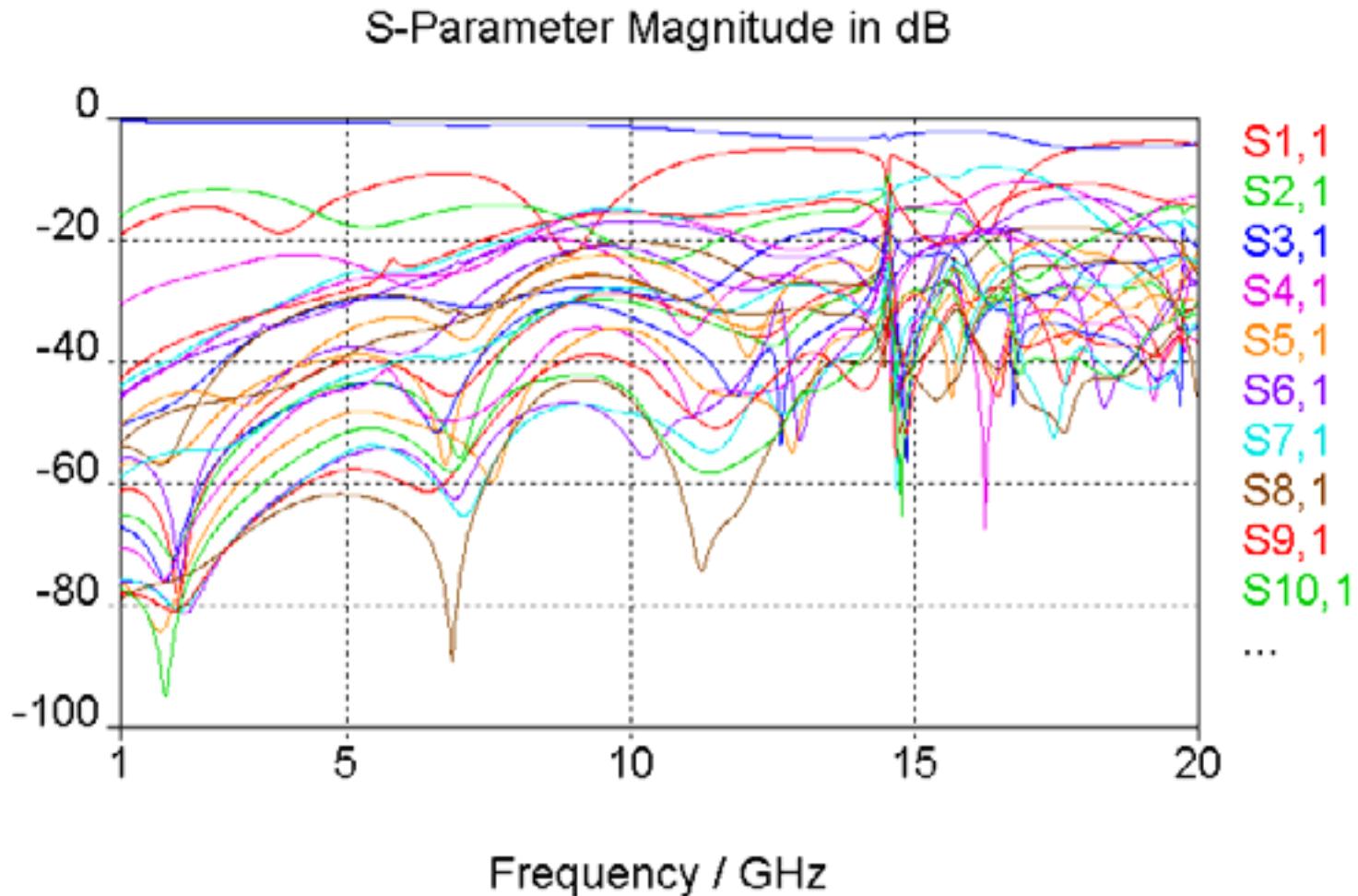
- Use commerical software „as is“
Limited by memory size of my computer (5GB)
Size of domain only 25% of entire structure
 - Time domain hexahedral mesh
(30 million cells)
 - **Frequency domain tetrahedral mesh
(5.3 million tet's)***Could be easily extended by a bigger computer*
- New parallel software
 - Time domain hexahedral mesh (650 million cells)*Not yet with all features*







5.3 million tet's, broad band frequency domain





- Use commerical software „as is“
Limited by memory size of my computer (5GB)
Size of domain only 25% of entire structure
 - Time domain hexahedral mesh
(30 million cells)
 - Frequency domian tetrahedral mesh
(5.3 million tets)*Could be easily extended by a bigger computer*
- New parallel software
 - **Time domain hexahedral mesh (650 million cells)***Not yet with all features*



The screenshot shows a complex circuit board layout in Allegro Free Physical Viewer. A yellow rectangular box highlights a specific area of the board, likely indicating the region of interest for the simulation. The layout consists of various green and red traces on a dark background. The viewer interface includes a menu bar (File, View, Display, Setup, Help) and a toolbar with icons for zooming, selecting, and saving.

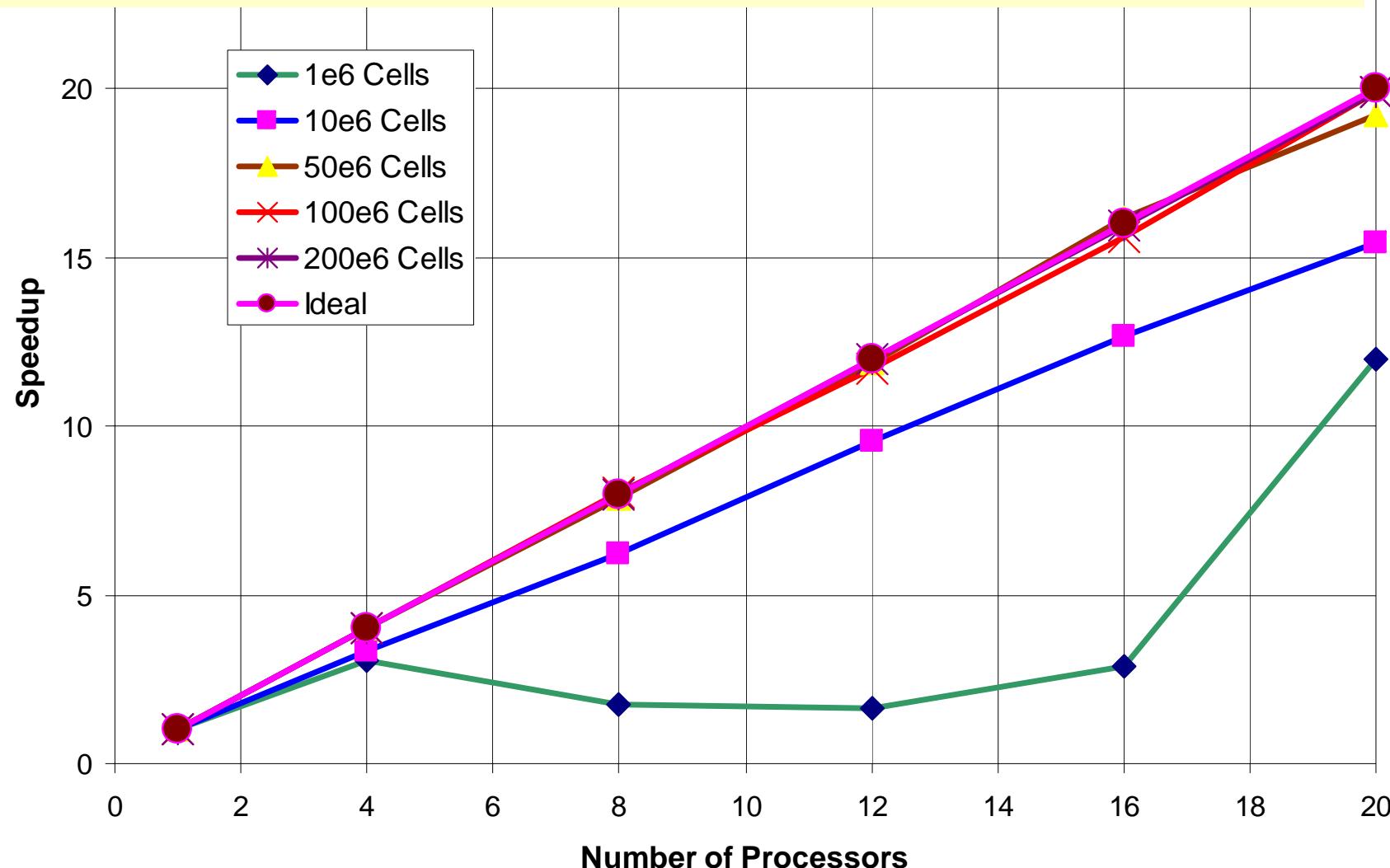
- New dedicated parallelized code
- FIT method Hexahedral discretization time domain
- Parallelized Domain partitioning algorithm
- The **complete model** was simulated
(not only a small part of it!)
- The **complete model** was simulated
without any geometrical simplification
- 3,900,000,000 DoFs
24-CPU Cluster - Meshing: 3 hours

This inset image provides a closer look at the highlighted region from the main screenshot. It shows a detailed hexahedral mesh of the selected area, with various colors (green, red, blue) representing different simulation results or field values. The mesh is composed of many small, interconnected hexagonal elements.

This smaller image shows another part of the Allegro interface. It displays a different section of the circuit board layout or a different simulation result. The screen is mostly black, with a small green and blue patterned area visible in the bottom right corner, possibly representing a zoomed-in view or a specific simulation output.



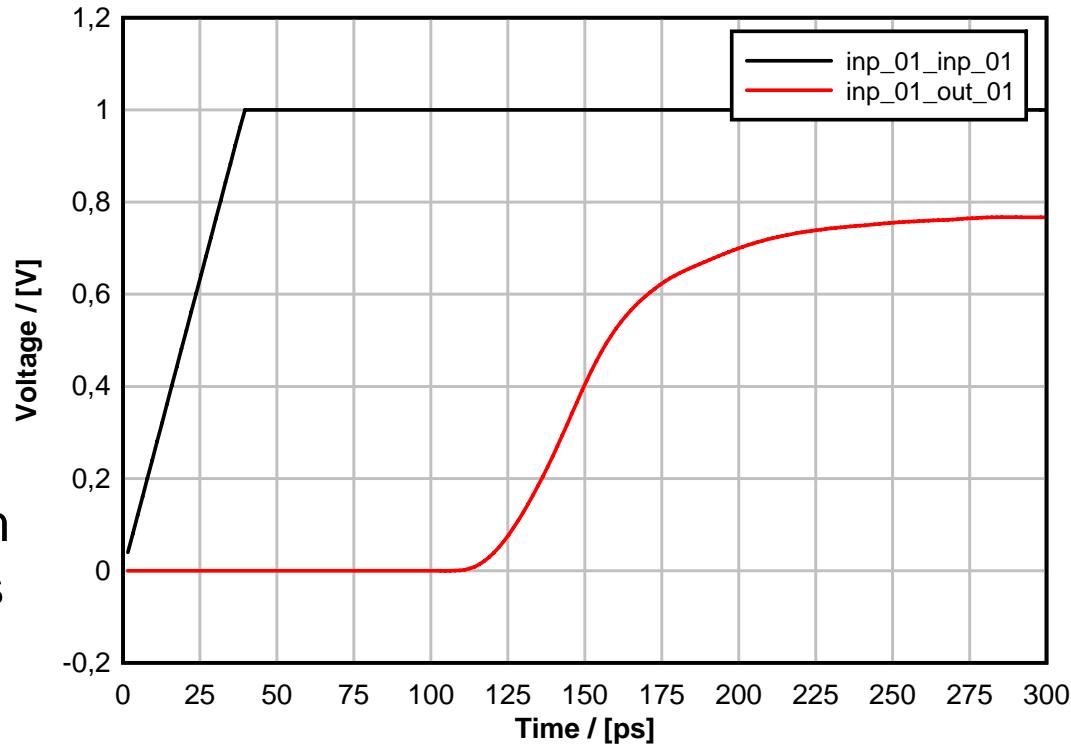
Speedup for a simple test model (no ports)



Input

Output

Good agreement with
the measured results
provided by IBM:



Dedicated talk/paper
on Wednesday

EPEP - Session XIII



Allora Free Physical Viewer: plasma_3293953_04072003.rdf Project... (operators, TEMF, Allegro)

File View Display Setup Help

Options Find Visibility

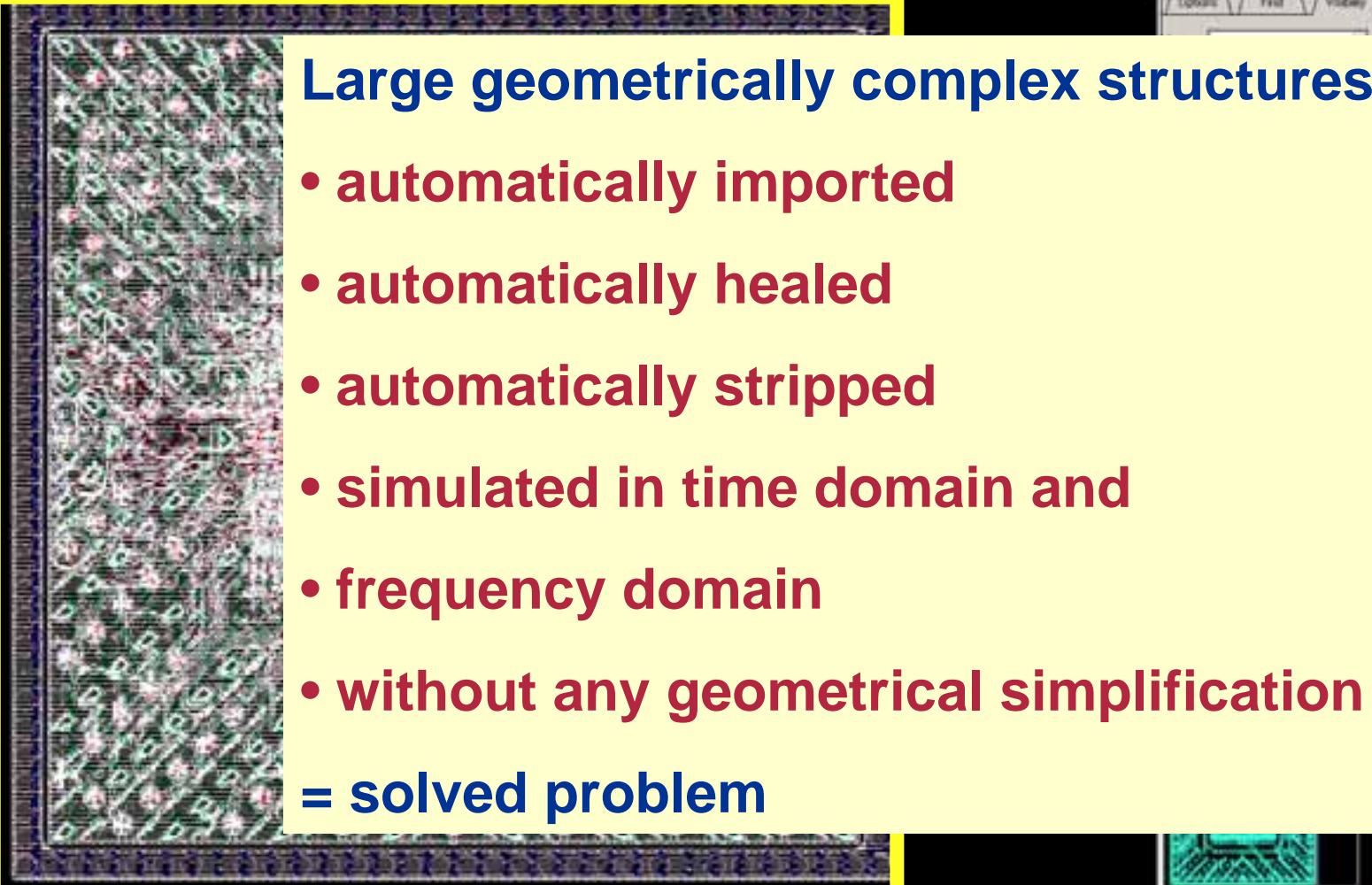
Ctrl zoom points
P A 21629.7, 6473.1

Large geometrically complex structures can be

- automatically imported
- automatically healed
- automatically stripped
- simulated in time domain and
- frequency domain
- without any geometrical simplification

= solved problem

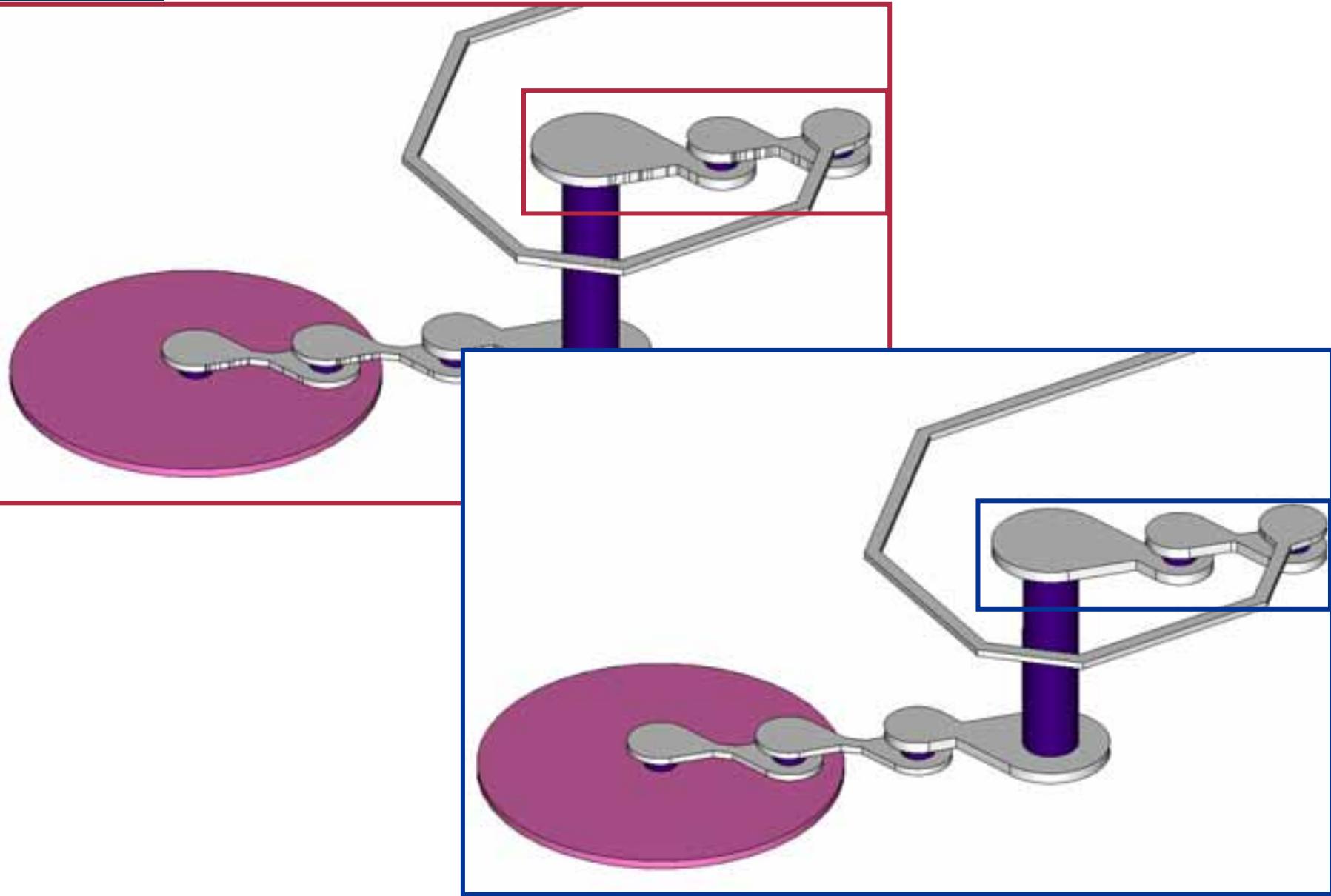
Warning: Allegro Free Physical Viewer opening an Allegro Performance drawing.
Info: 1 Warnings were issued during this open.
Info: DRC set to "out of date", the product supports a different DRC set than last product used on drawing.
Pick 1 in Corner Of New Window
Command:

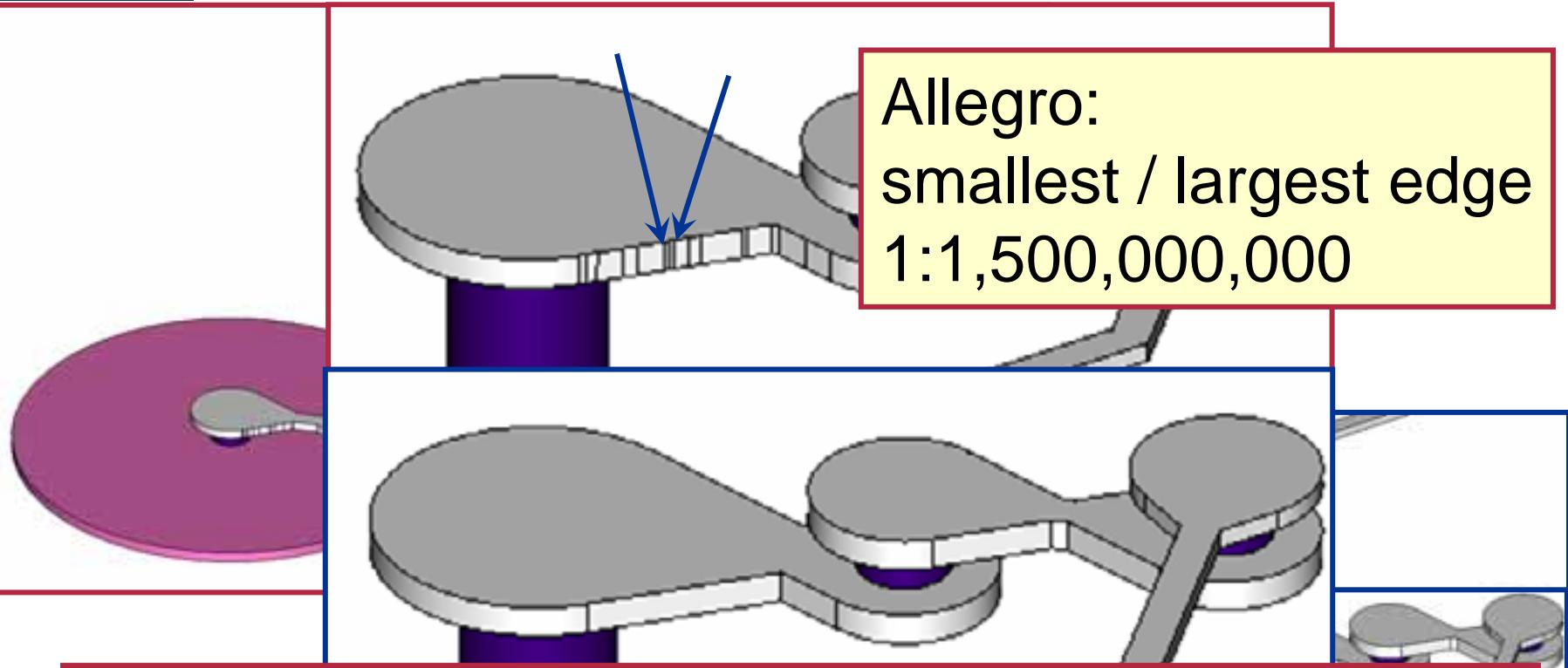




Hardware acceleration





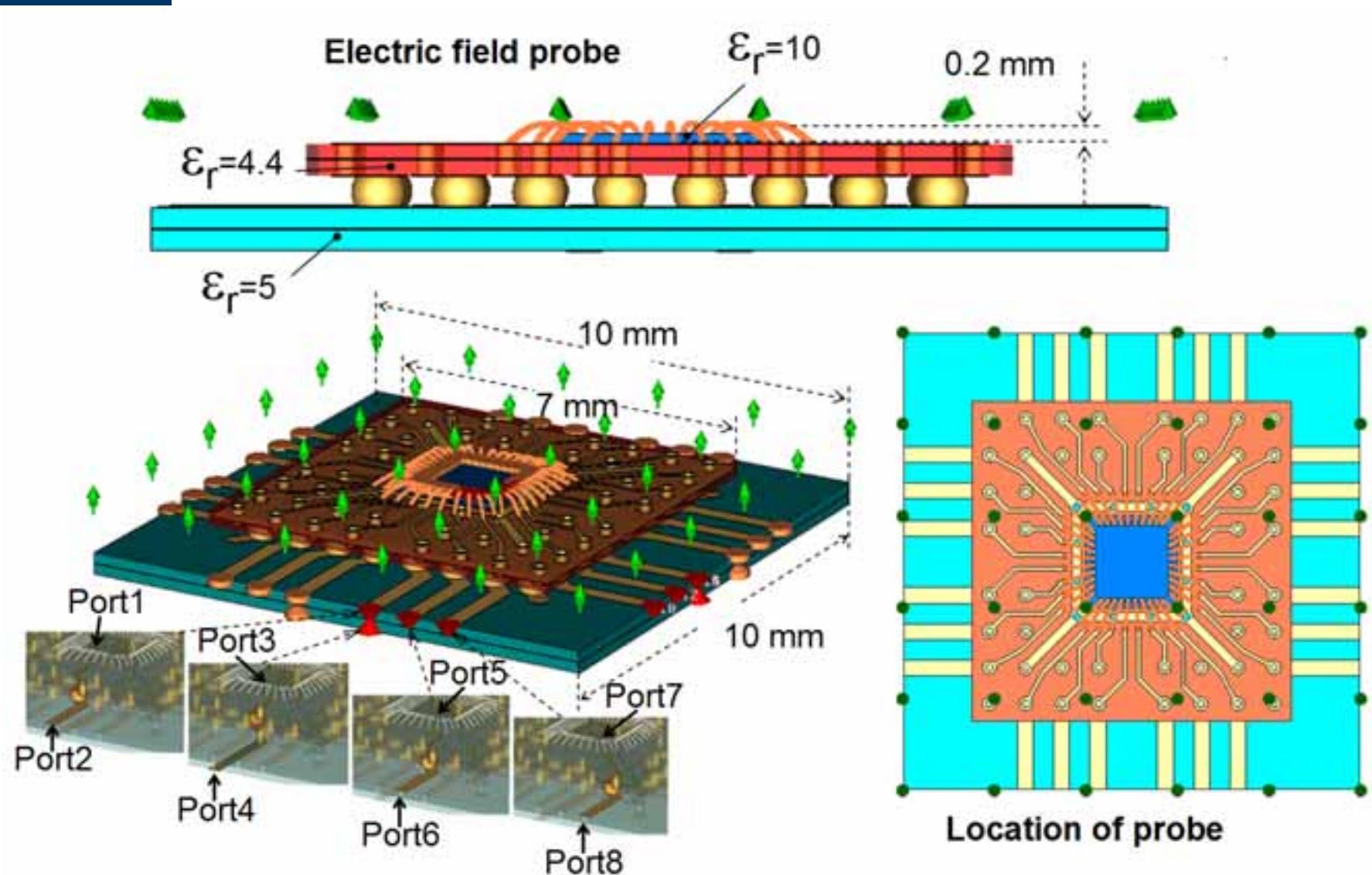


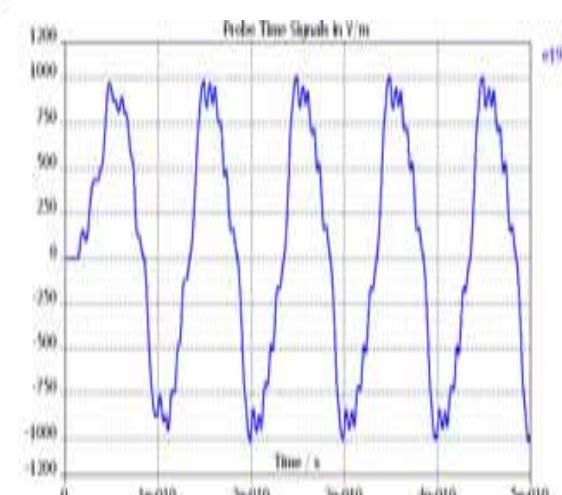
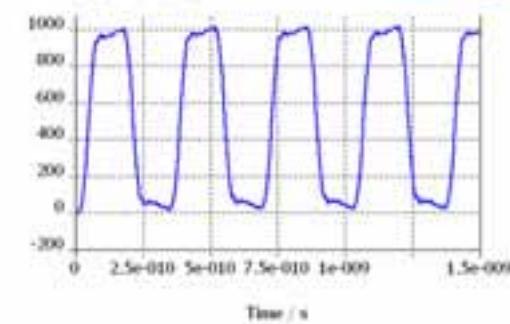
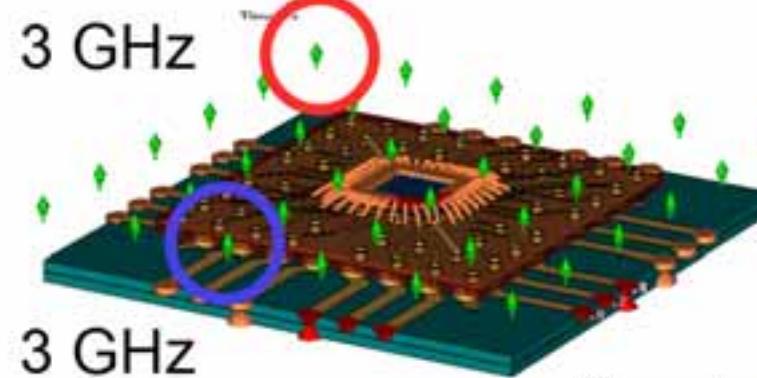
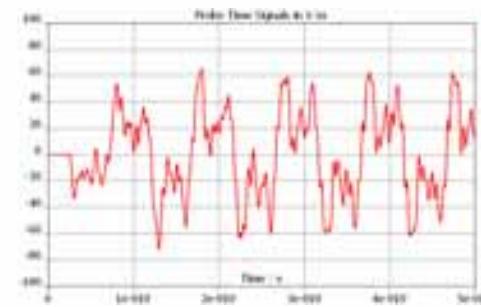
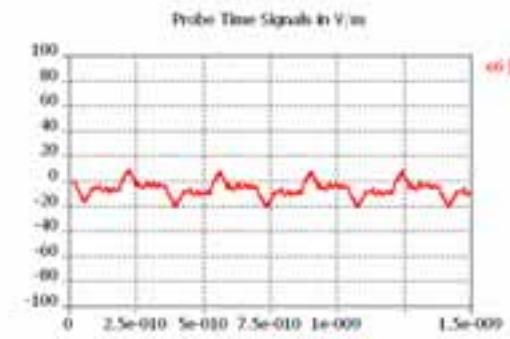
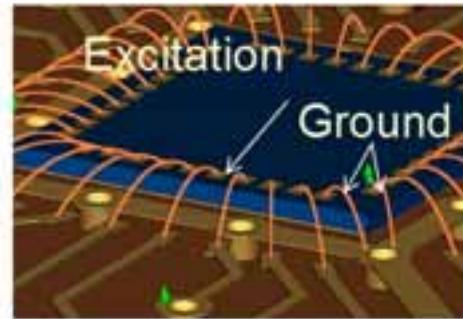
CST MICROWAVE STUDIO®:
Fully automatic clean-up and healing

No simplification of the model,
Just healing and stripping unnecessary edges



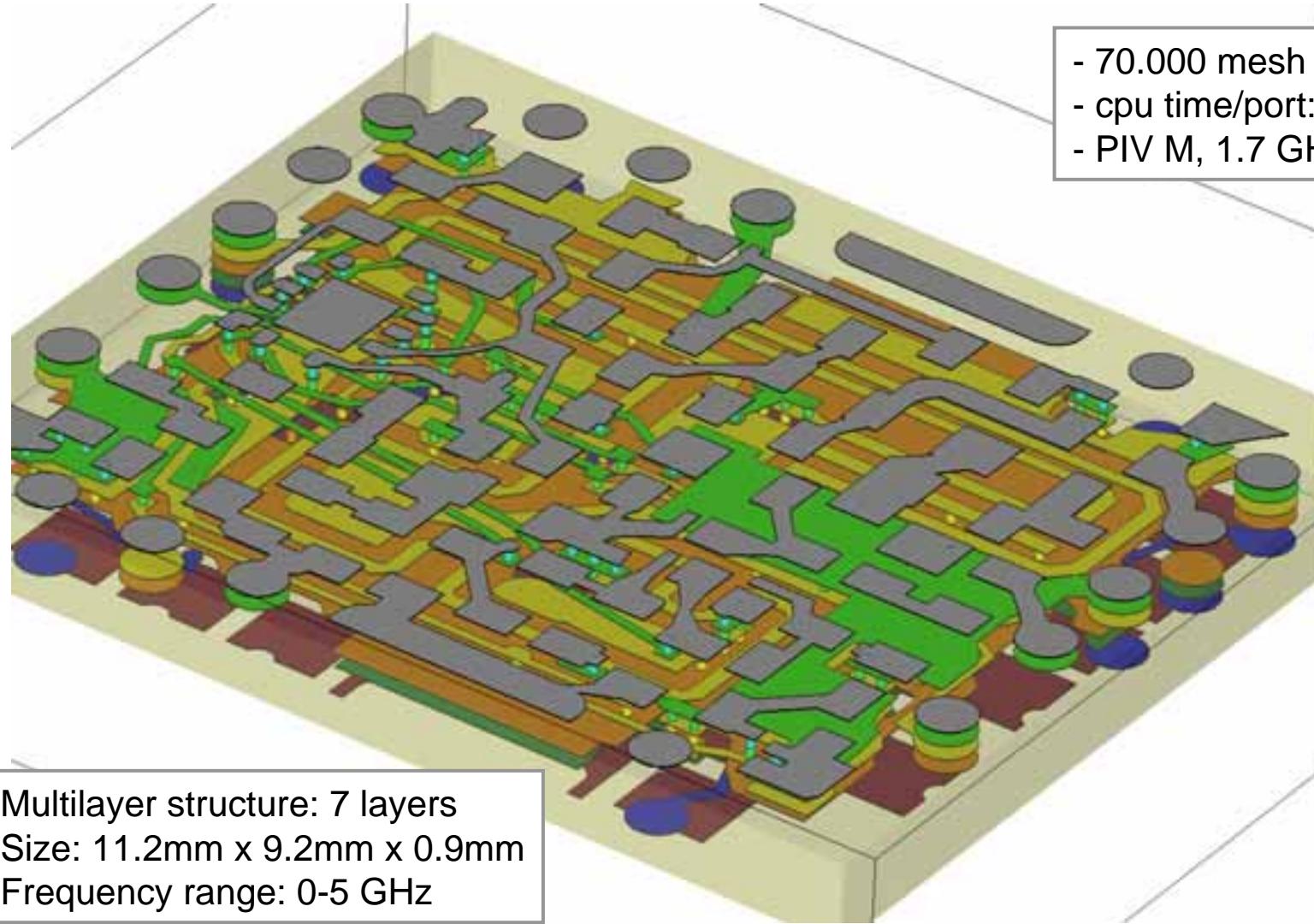
- Introduction
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 - Geometrically complex problems
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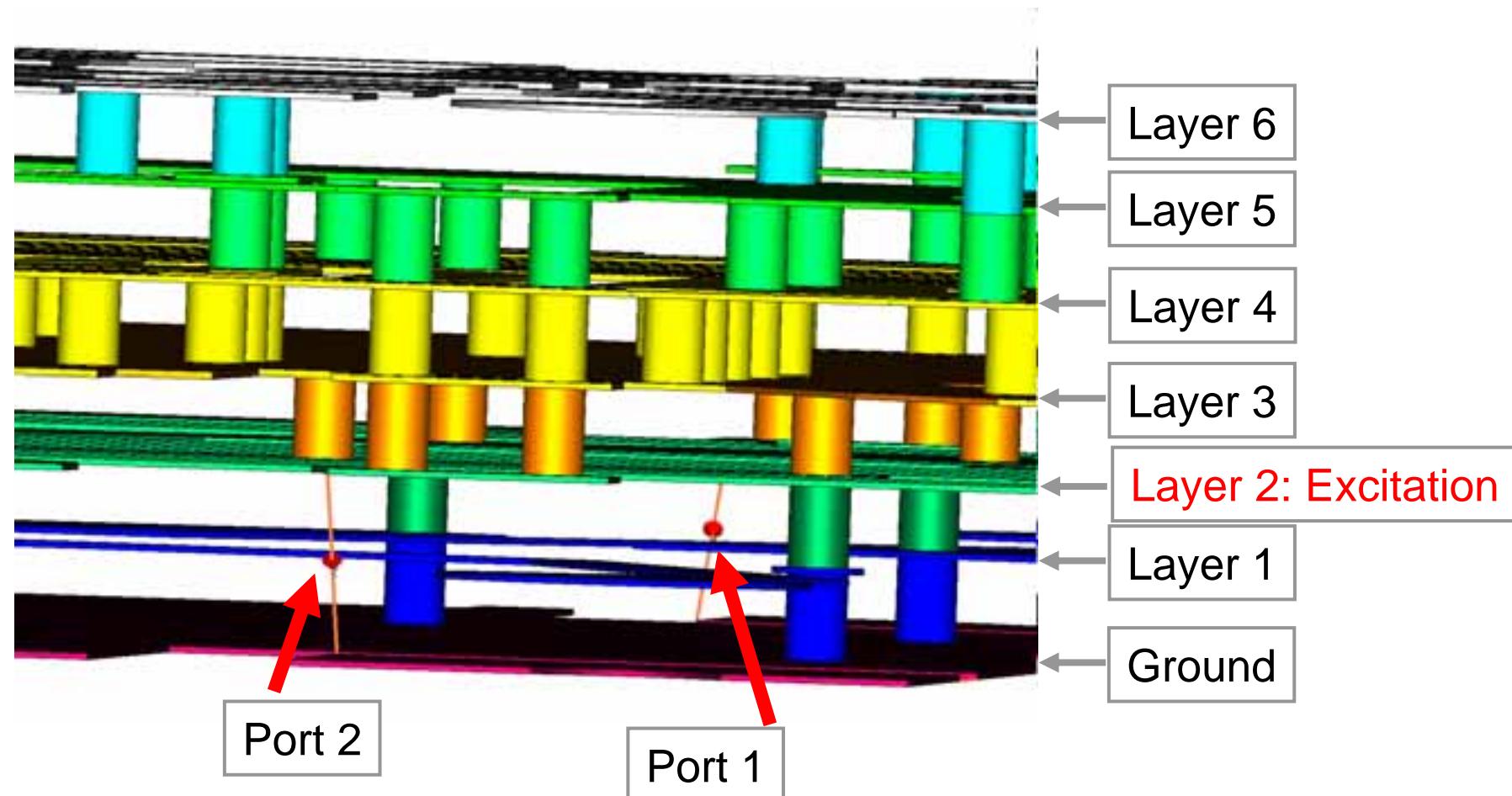






Multilayer structure

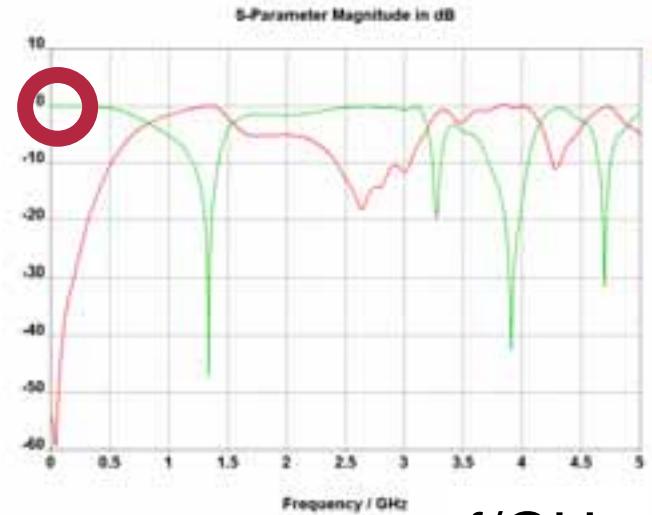






0.10 GHz

S_{11} , S_{21}



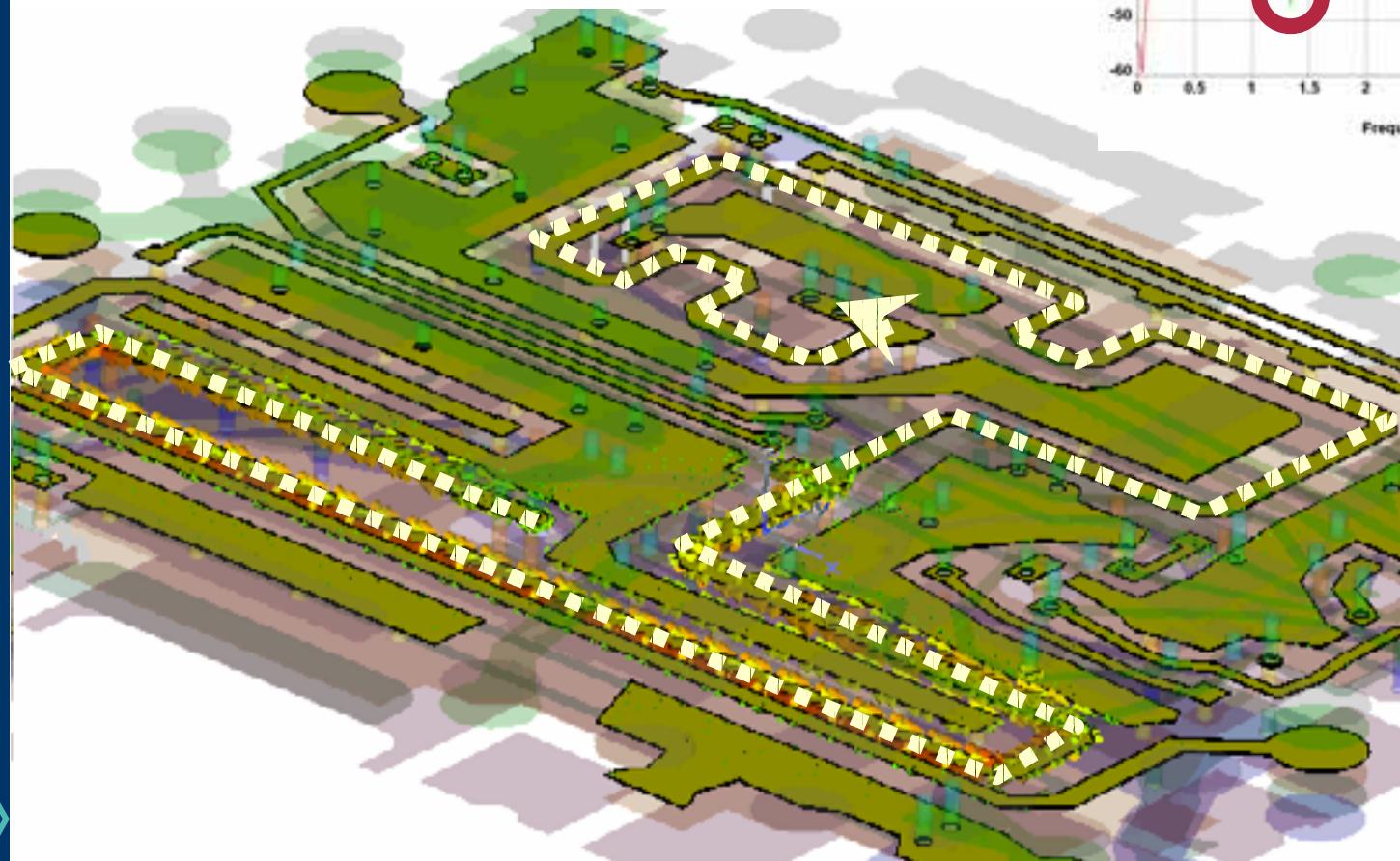
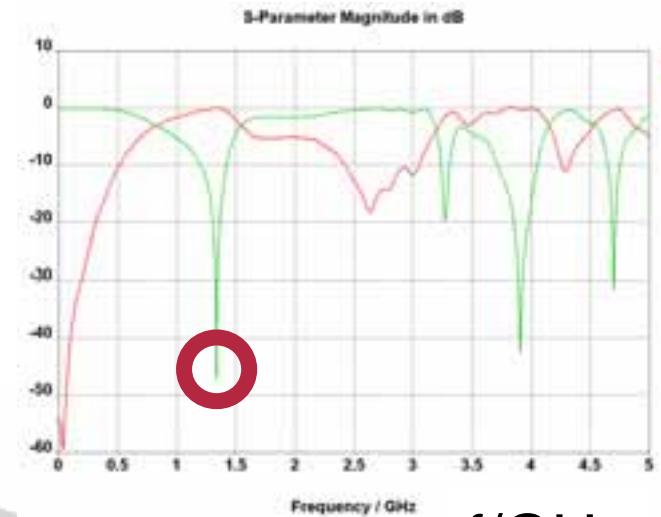
f/GHz





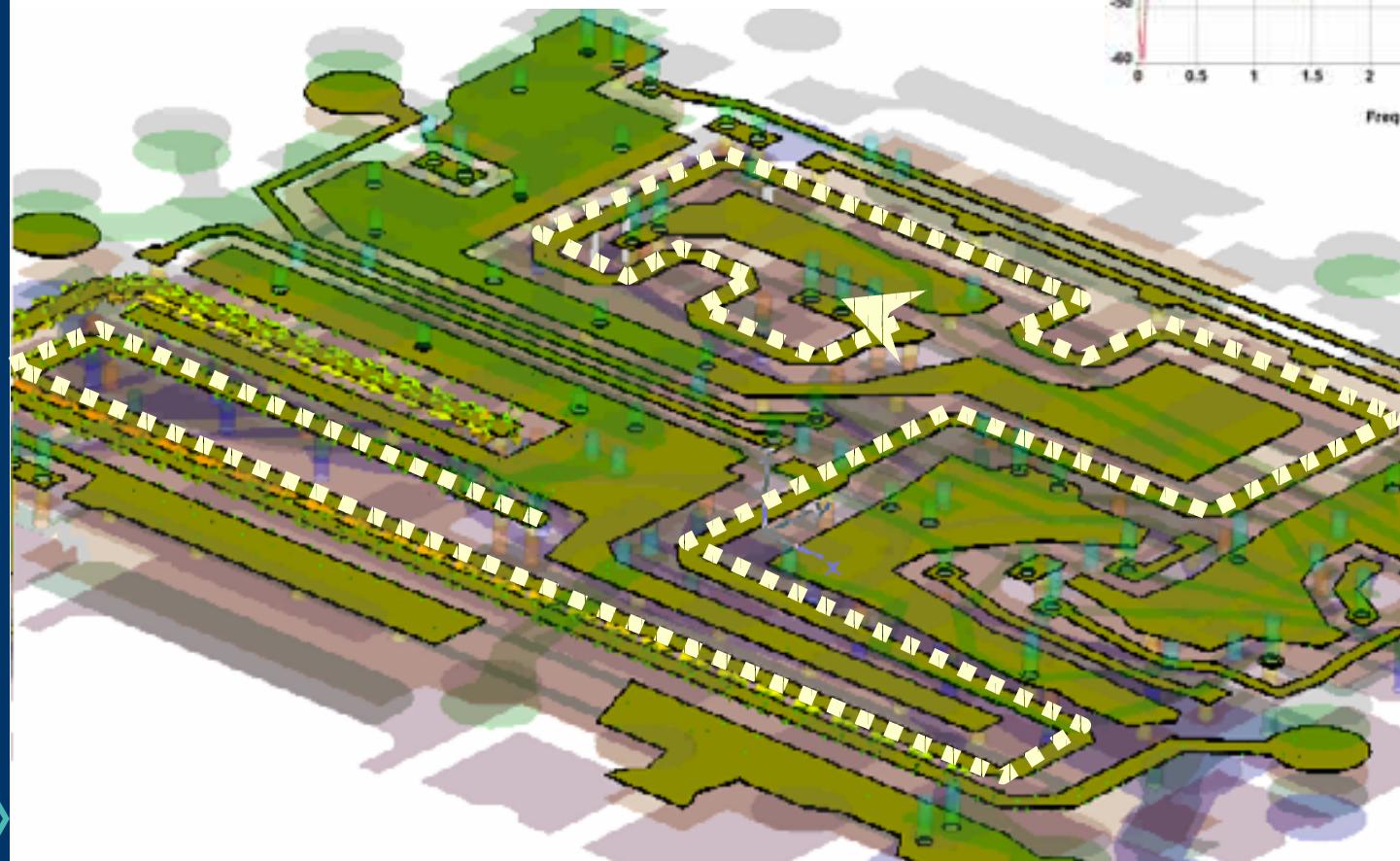
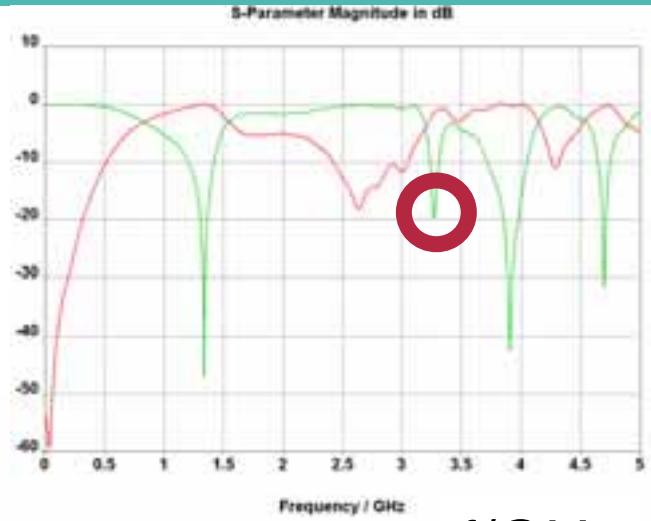
1.34 GHz

S_{11} , S_{21}



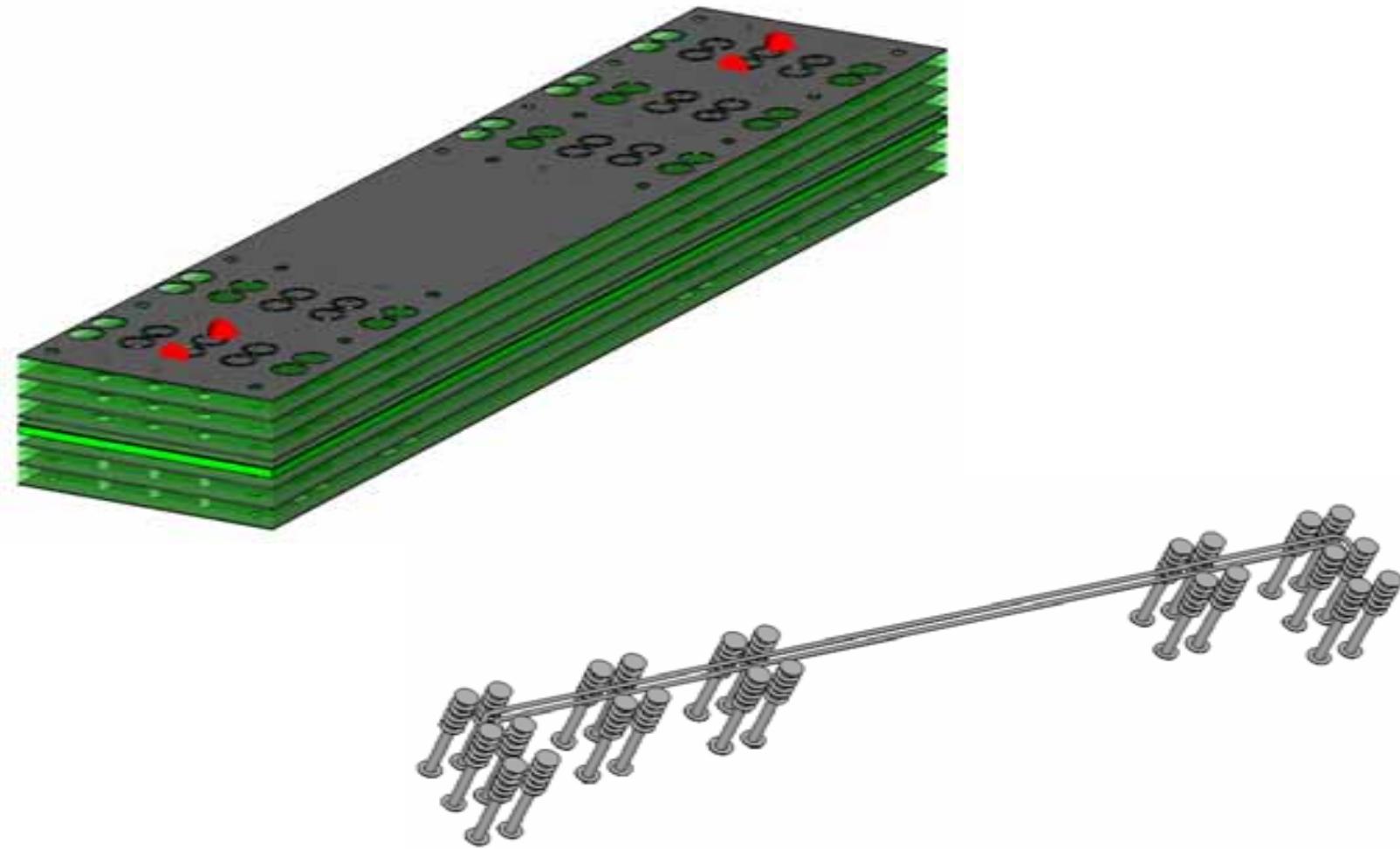


S_{11} , S_{21}



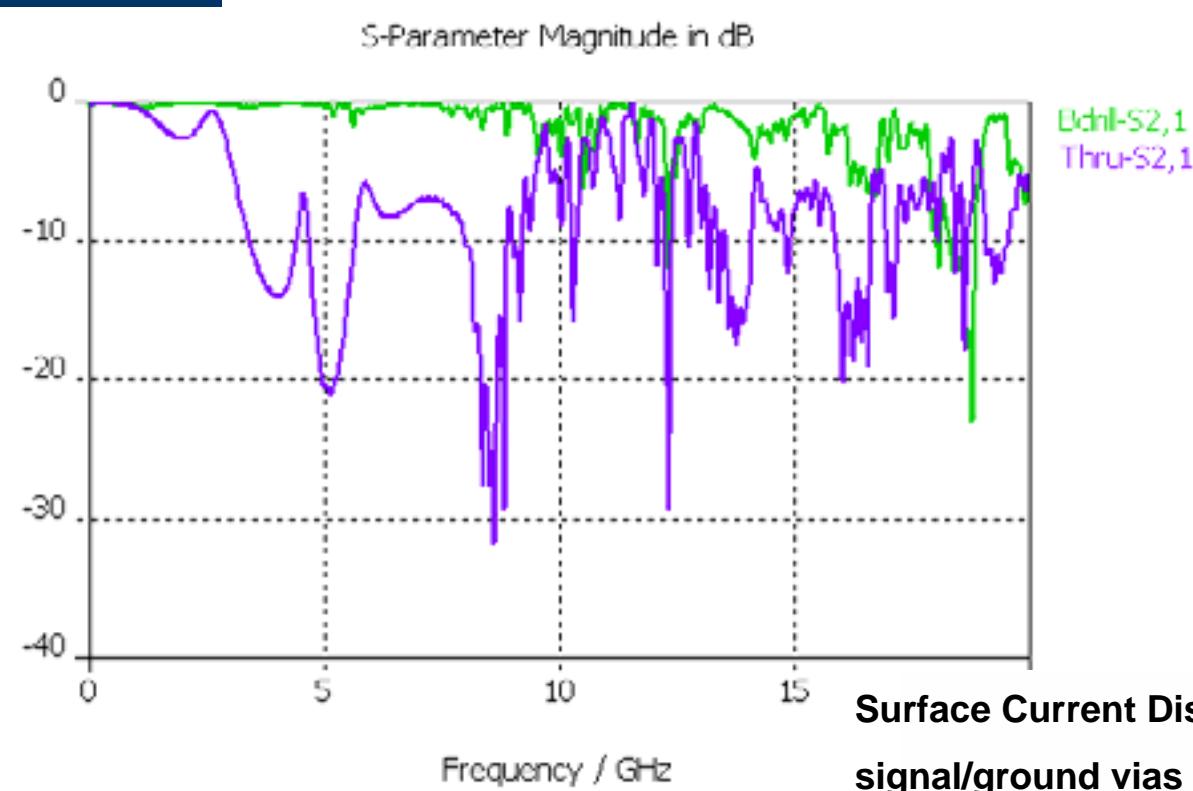


Allegro import of backplane pair

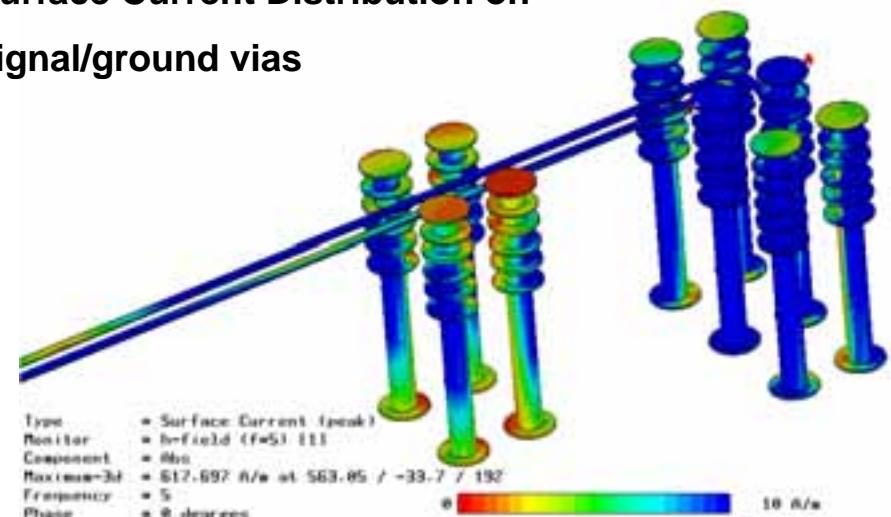


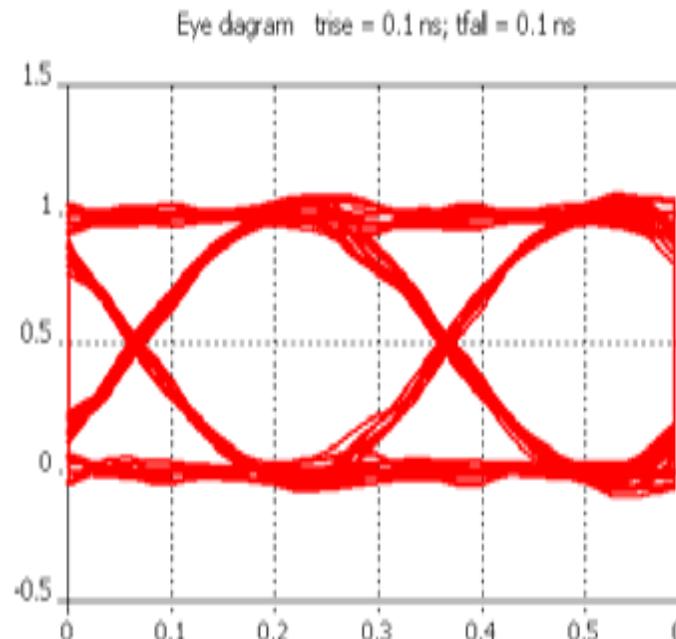


S21 Thru via vs. back drilled via

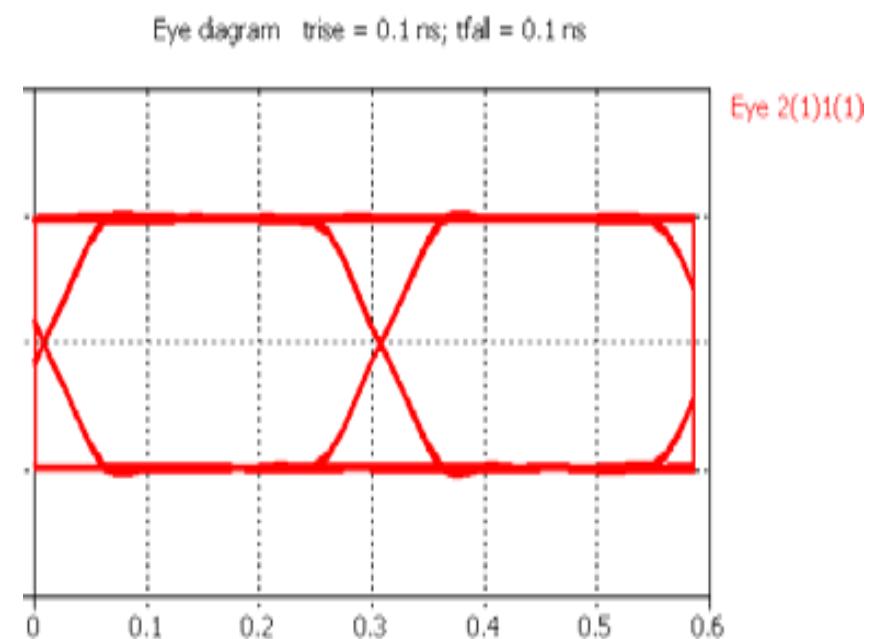


Surface Current Distribution on
signal/ground vias



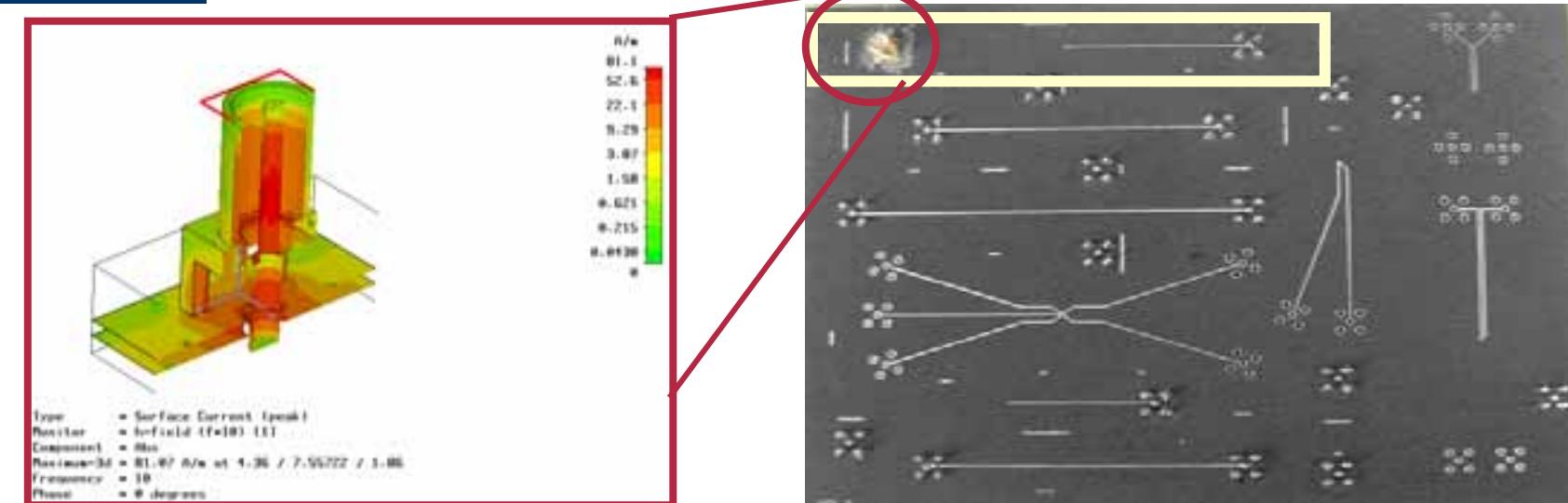


Through Hole Via

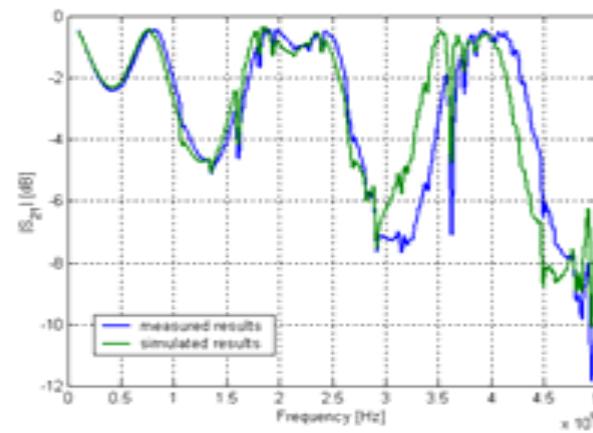
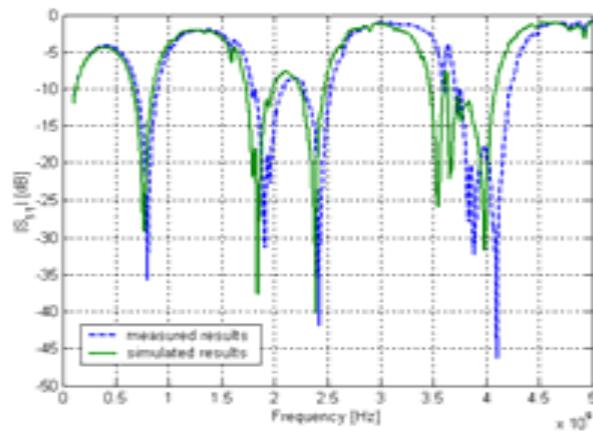


Back Drill Via

Stripline and via hole on PCB board

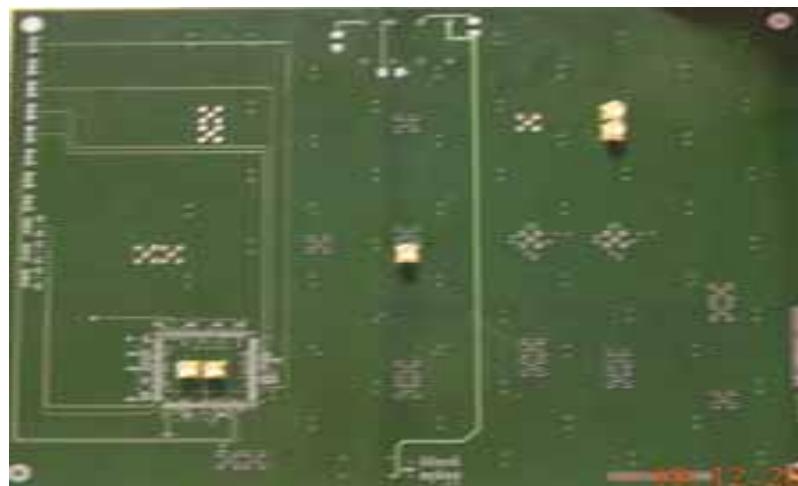


measured simulated

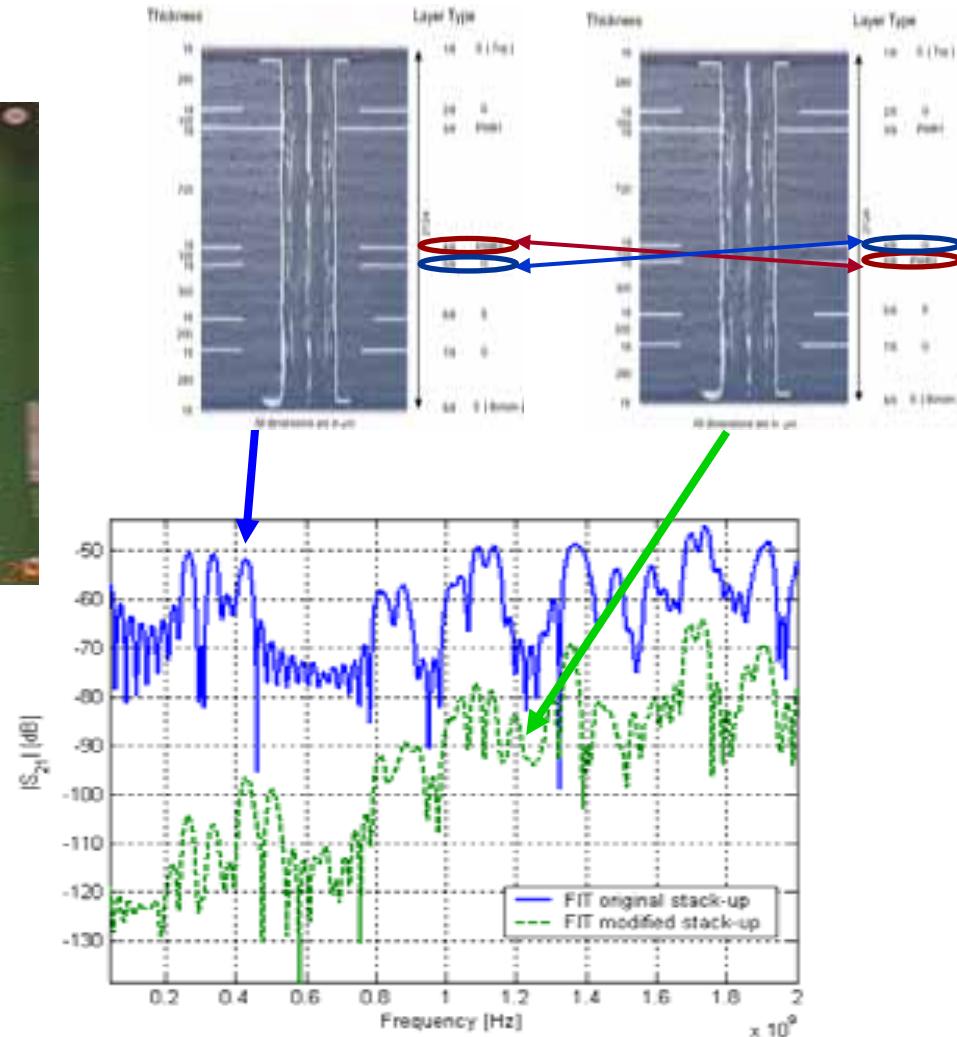


Model and simulation: UAq EMC Lab (L'Aquila, Italy)

Test board: UMR EMC Lab (Rolla, MO, USA) Courtesy Prof. A. Orlandi



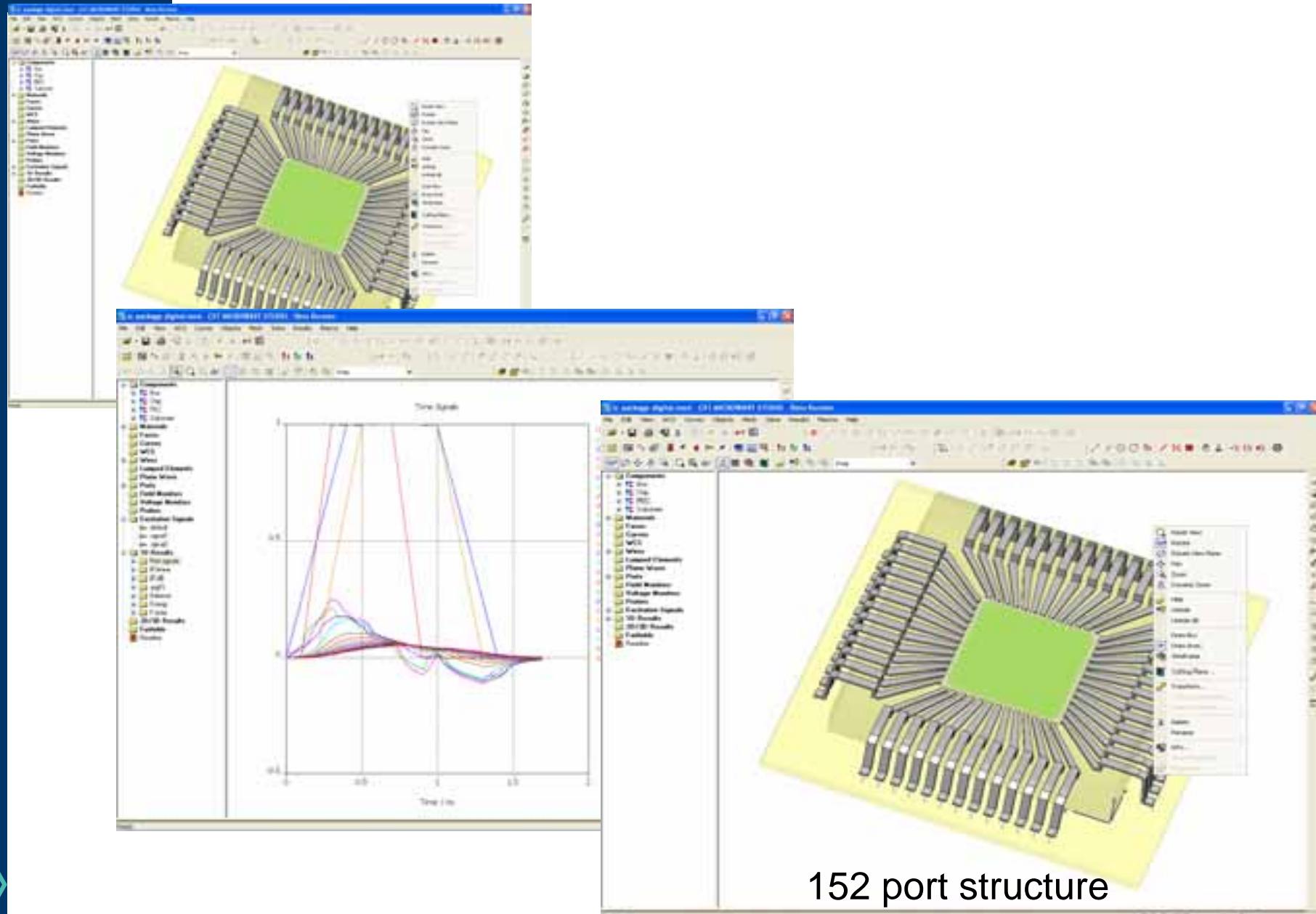
Swapping **PWR1**
and **PWR2** drastically
reduces the coupling
between the power planes



Test board: Siemens C.N.X.- UAq EMC Lab
Model and simulation: UAq EMC Lab (L'Aquila, Italy)
Courtesy Prof. A. Orlandi



IC Package – Digital signal simulation



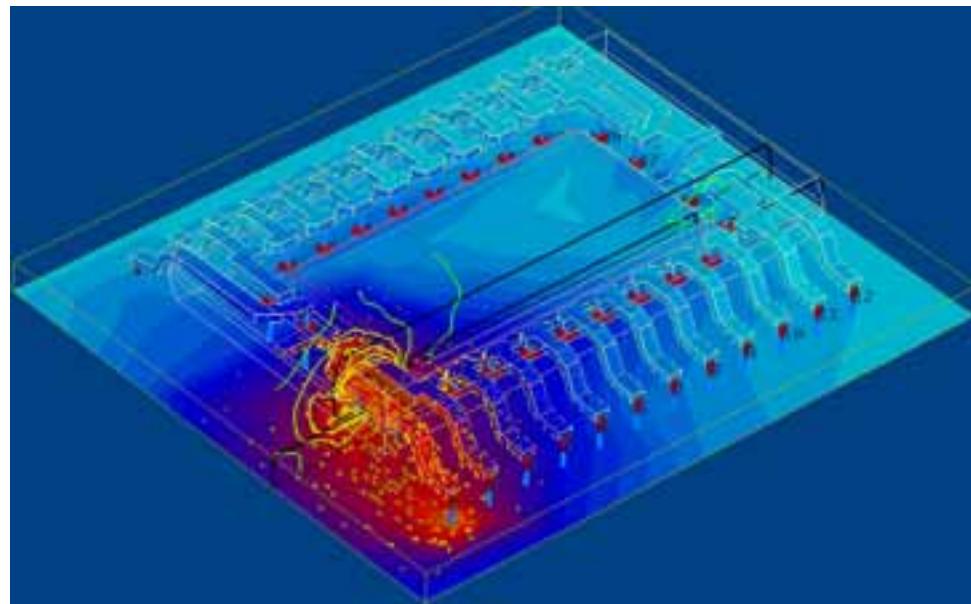


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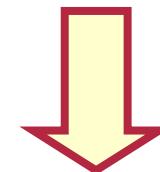
Static extraction

- Based on quasistatic fields
- Computes SPICE network from L,C
- Does not contain dynamic effects



Dynamic extraction

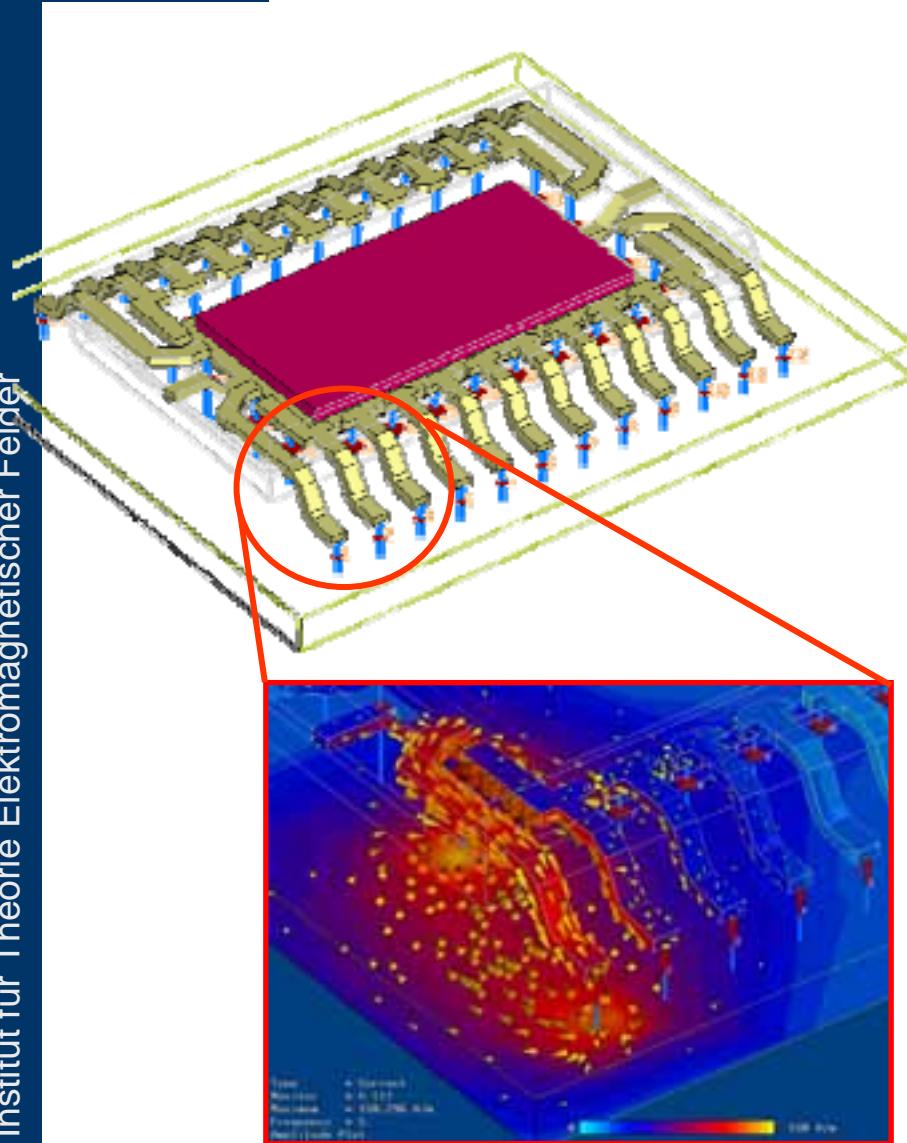
- Based on dynamic EM fields
- Computes SPICE network from S-parameters
- Allows cascaded networks



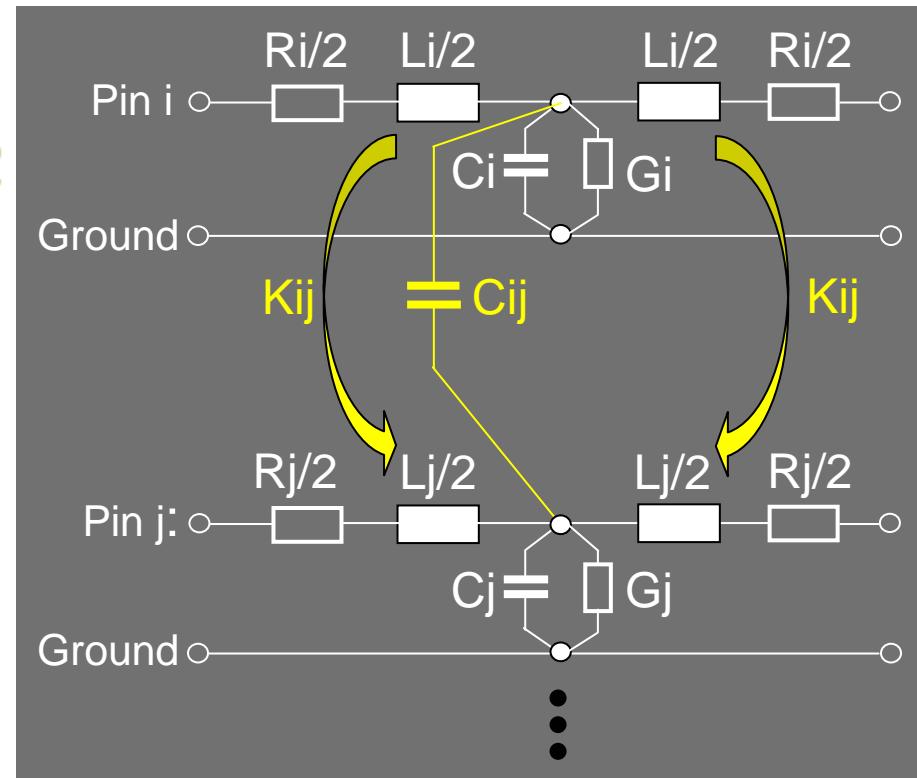
Full EM-SPICE



SPICE Model 1



Fixed topology, R,L,C,G elements

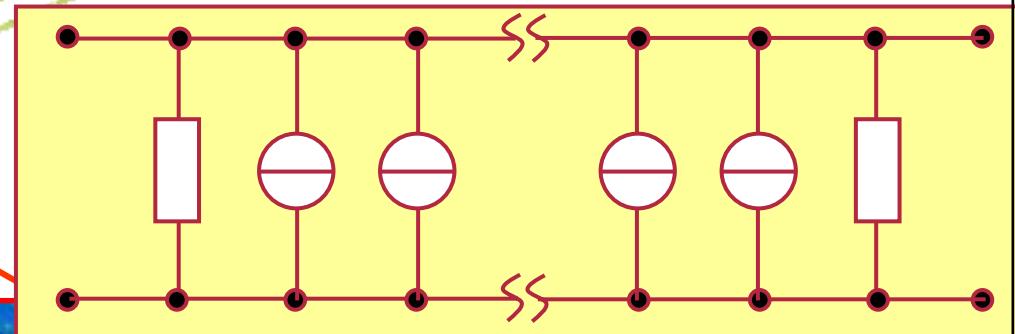
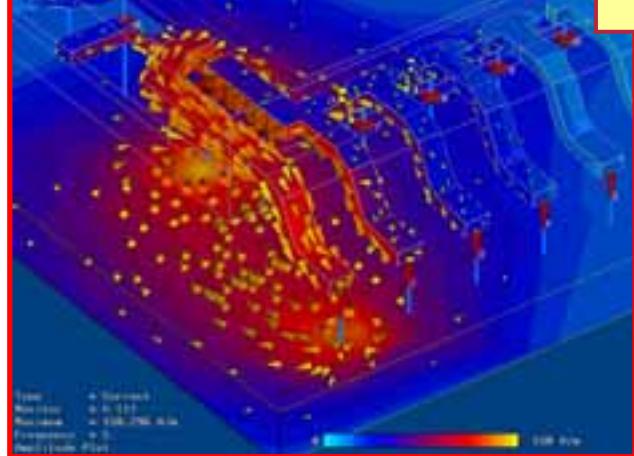
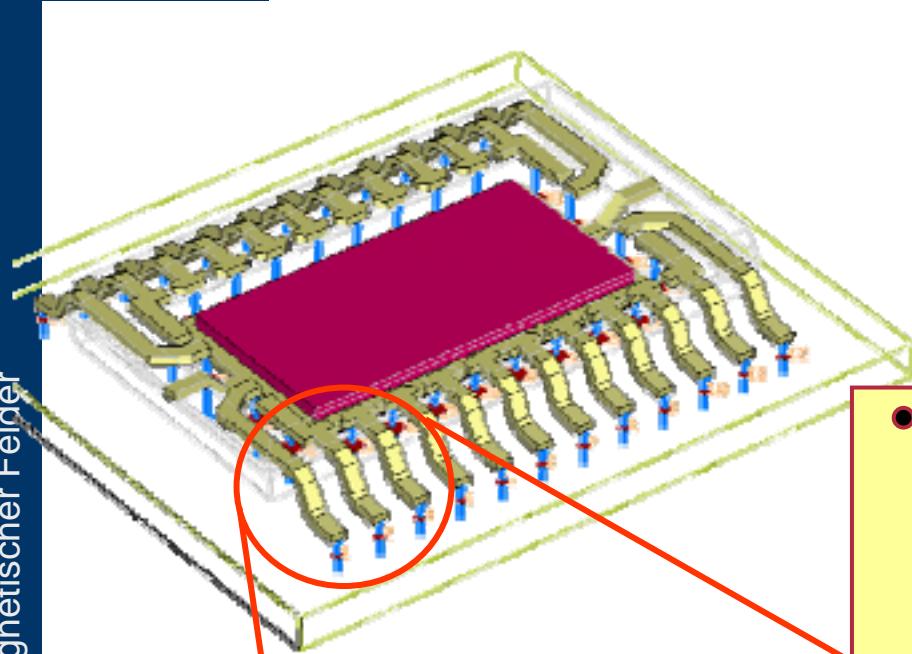


Cascaded SPICE models needed
to fit for larger frequency bands !



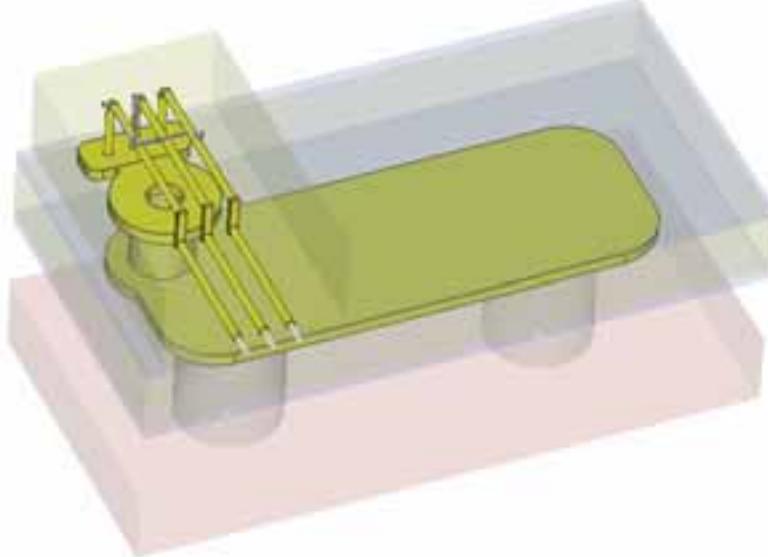
SPICE Model 2: Extraction

Flexible topology, R,L,C,G elements
+ controlled sources



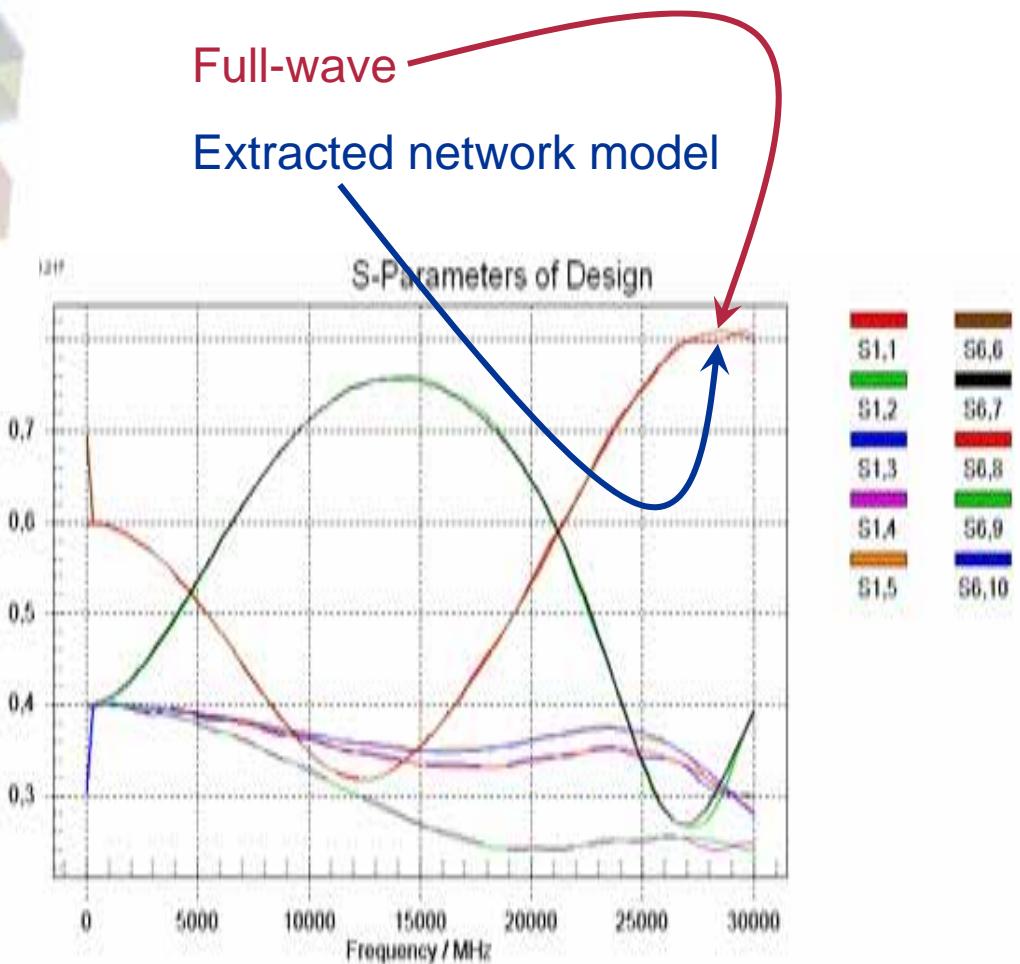
Fits naturally large frequency bands
Model should be stable and **passive** !

Automatically Generated Netlist



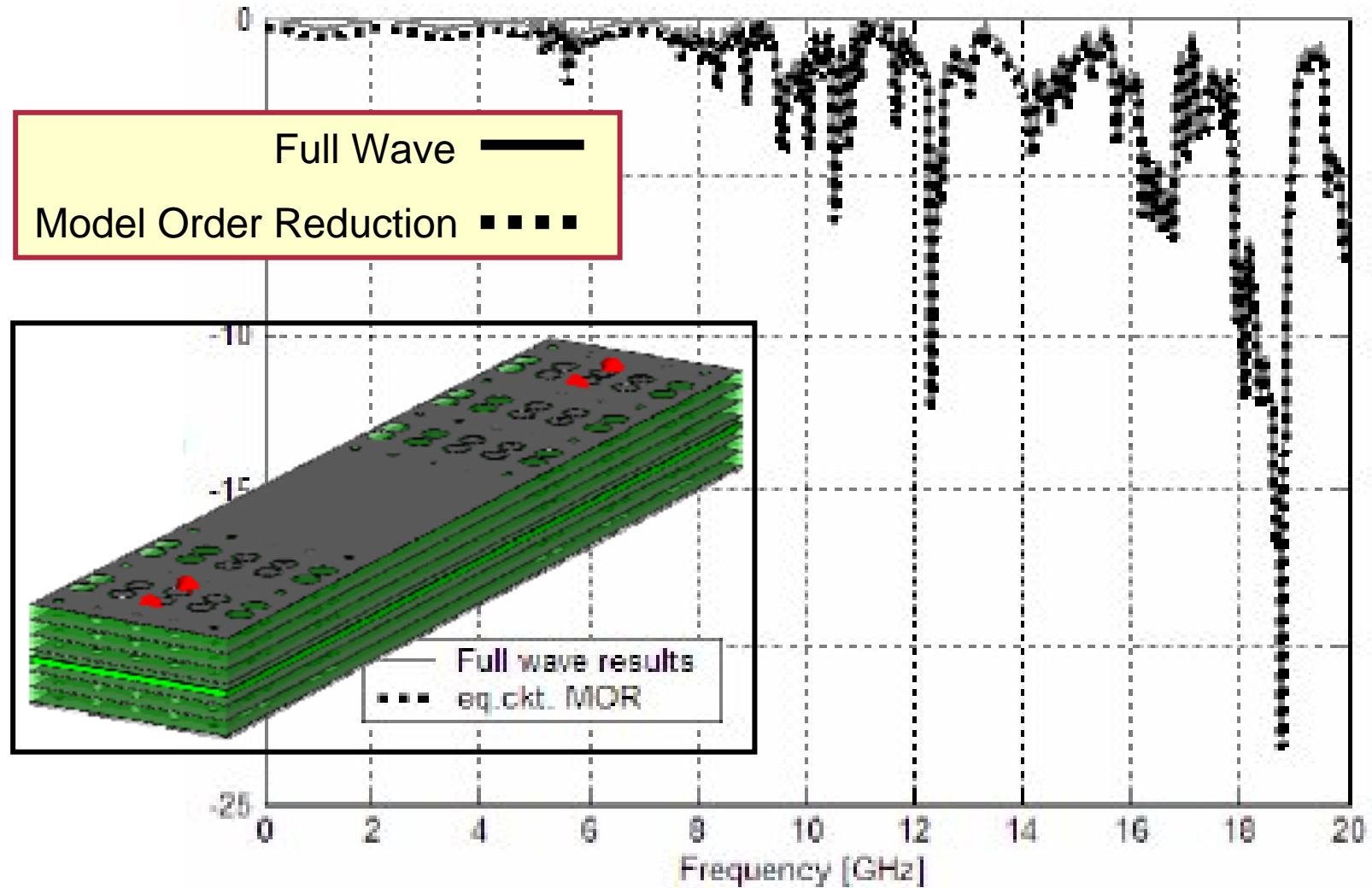
Section of BGA integrated circuit package

- 5 Port structure (discrete)
- Port impedance: 50 Ohm





S21 of MWS simulation and extracted model





TECHNISCHE
UNIVERSITÄT
DARMSTADT

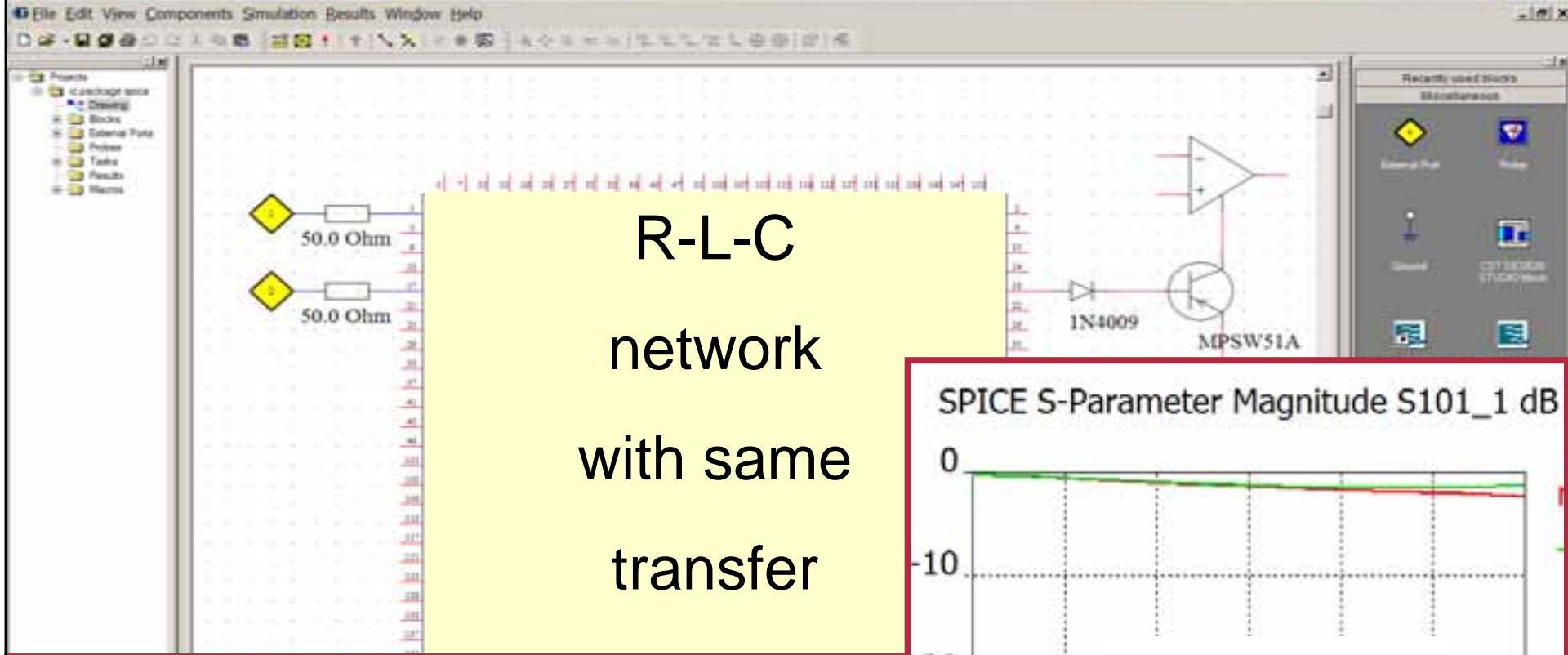
CST MICROWAVE STUDIO [ic package spice*]

Challenges



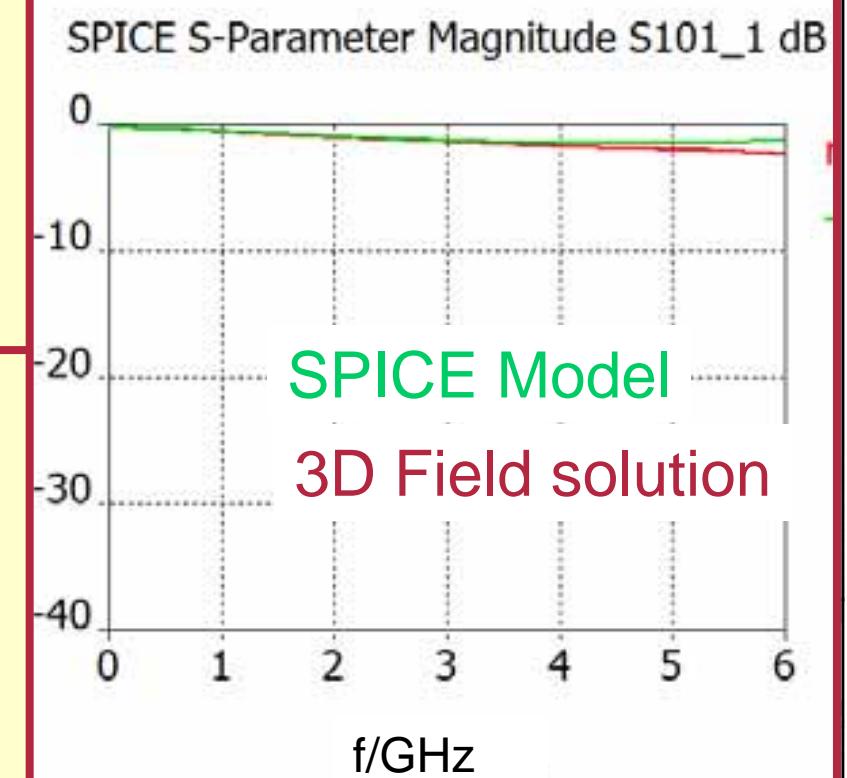
Cross Talk on Micro Chips

The screenshot shows the CST MICROWAVE STUDIO interface. On the left, the project tree shows a single item: "ic package spice". The main workspace displays a 3D rendering of a microchip with a complex metal interconnect pattern and a central green rectangular region. To the right of the 3D view is a schematic diagram of an electronic circuit. The circuit consists of a voltage source (50.0 Ohm), a diode (1N4009), a MOSFET (MPSW51A), and an operational amplifier (op-amp) configured as a buffer. The op-amp's non-inverting input is connected to the drain of the MOSFET, and its inverting input is connected to ground. The output of the op-amp is connected to the gate of the MOSFET. The circuit is powered by a 50.0 Ohm source at both the input and output. A detailed parameter table is visible at the bottom left, and a unit conversion bar is at the bottom right. The taskbar at the bottom shows various open files and the CST MICROWAVE STUDIO icon.



R-L-C
network
with same
transfer

Network parameter extraction for a 152x152 S-parameter matrix is still a challenge for many extractors !

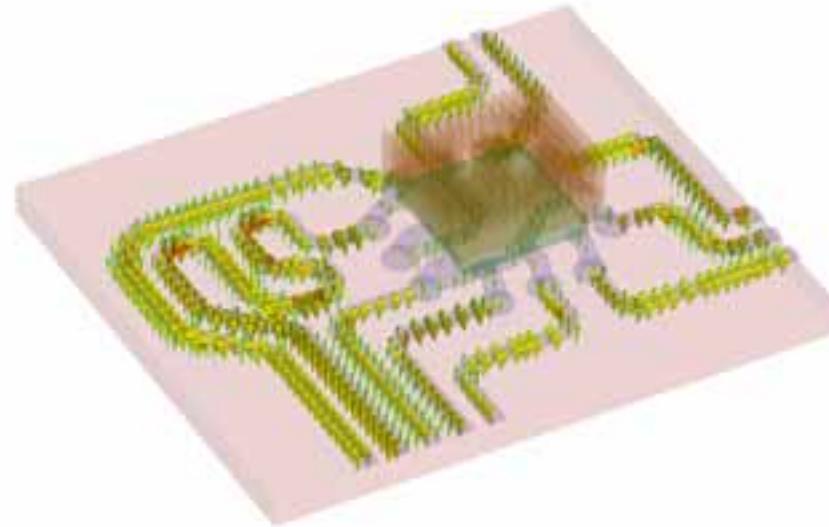




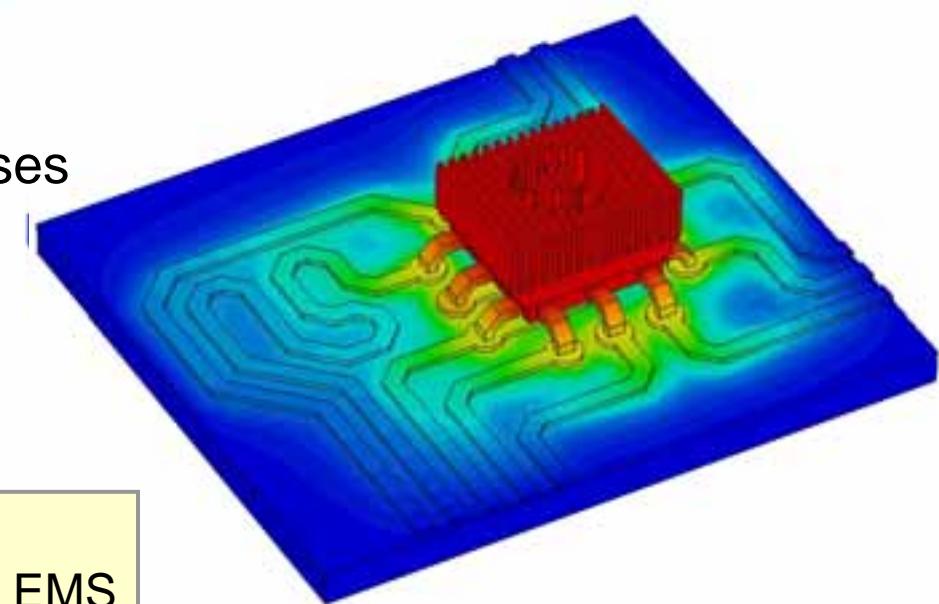
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HF- Thermal Solver Coupling



Thermal Analysis of electric losses



1. Currents: CST MWS
2. Temperature Analysis: CST EMS



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The screenshot shows a simulation software interface with the following components:

- Top Bar:** File, Edit, View, Components, Simulation, Results, Window, Macros, Help.
- Toolbar:** Includes icons for file operations, simulation, and analysis.
- Left Panel (Projects):**
 - Projects folder
 - sphere project
 - Drawing
 - Blocks
 - External Ports
 - Circuit Ports
 - Probes
 - Tasks
 - Results
 - Imp project
 - Drawing
 - Blocks
 - 3dB1
 - BJT1
 - CAP1
 - CAP2
 - GND1
 - GND2
 - GND3
 - GND4
- Middle Panel (Circuit Diagram):** A schematic diagram of a circuit. It includes a 100 V DC voltage source, a BFR505 transistor, resistors (180 kOhm, 1 kOhm, 20 kOhm), inductors (L1, L2), capacitors (C1, C2), and a matching network block. The circuit is connected to a dual patch antenna model.
- Right Panel (Recently used blocks):** Shows recently used blocks including "dual patch antenna combineSight.mod", "Microstrip Line", and "EST MICRODRAVE".
- Bottom Left (Parameter Table):**

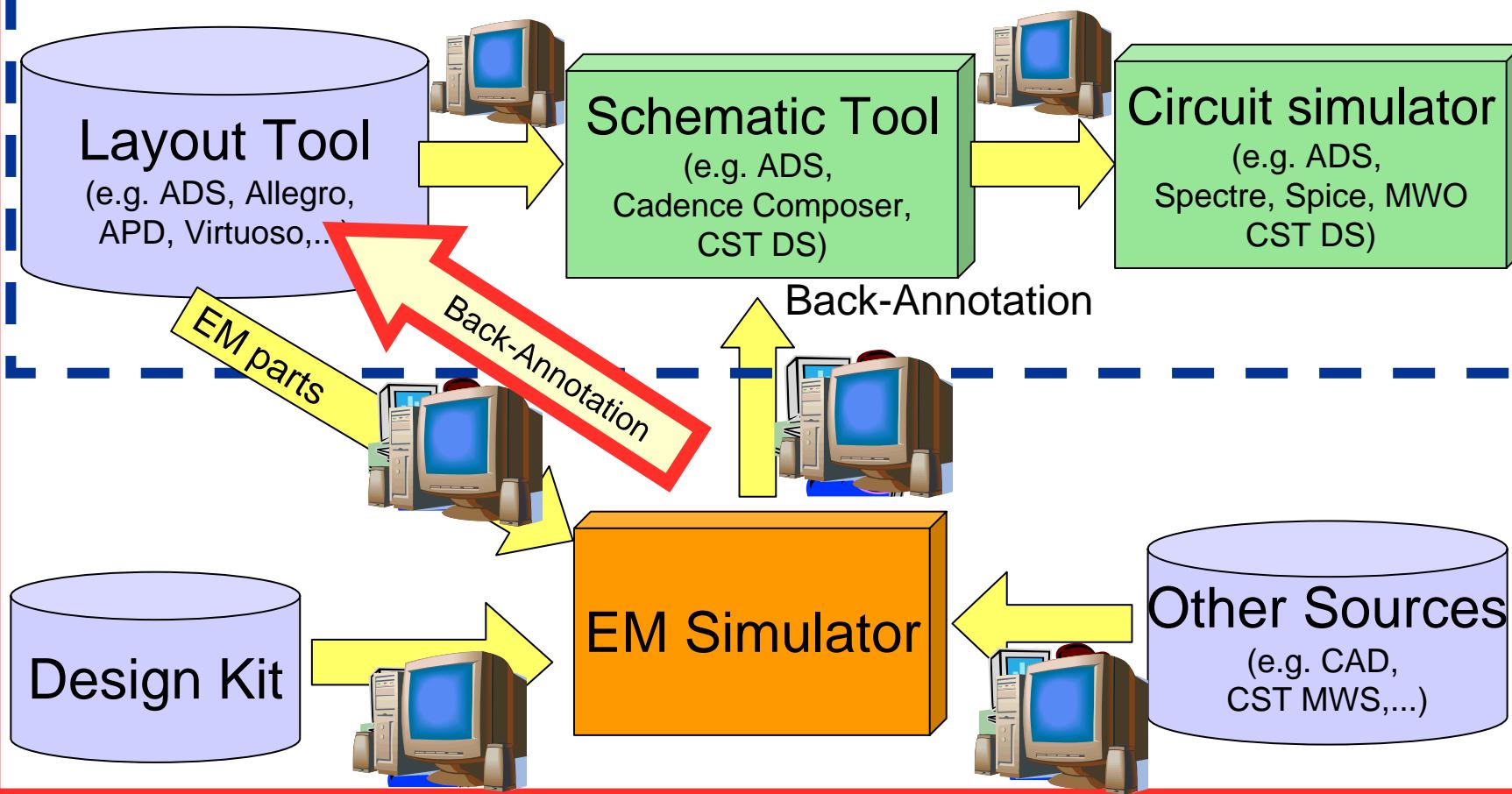
Name	Value	Description
C1	0.16001755368914	
C2	0.33996369605556	
L1	4.5475369271573	
L2	6.8010969214486	
- Bottom Right (3D Plots):** Two 3D plots. The left one shows a sphere with a color-coded field distribution (ranging from -16.6 dB to 8.64 dB) with axes labeled theta and phi. The right one shows a 3D model of a substrate with two red rectangular patches.

Text Overlay:

Full integration from one hand is already available
How about 3D integration into standard flows?

Design Flow Integration

Present



Future

Conclusions

- EM field computation **tools**
 - Flexibility in Mesh Generation
 - Flexibility in local approximation (FI,FE,FV,...)
 - Wide choice of tools for one problem
 - for comparison + validation
 - Choose the best tool for your current problem
- Future trends
 - Larger problems: Parallel computing, hardware acceleration
 - Power and signal integrity, EMC issues
 - EM Simulation will need to be fully integrated in automated design flows

